

8M-bit Synchronous GRAM

Description

The μ PD481850 is a synchronous graphics memory (SGRAM) organized as 128 K words \times 32 bits \times 2 banks random access port.

This device can operate up to 100 MHz by using synchronous interface. Also, it has 8-column Block Write function to improve capability in graphics system.

This product is packaged in 100-pin plastic QFP (14 \times 20 mm).

Features

- 131,072 words \times 32 bits \times 2 banks memory
- Synchronous interface (Fully synchronous DRAM with all input signals are latched at rising edge of clock)
 - : Pulsed interface
 - : Automatic precharge and controlled precharge commands
 - : Ping-pong operation between the two internal memory banks
 - : Up to 100 MHz operation frequency
- Possible to assert random column address in every cycle
- Dual internal banks controlled by A9 (Bank Address: BA)
- Byte control using DQM0 to DQM3 signals both in read and write cycle
- 8-column Block Write (BW) function
- Persistent write per bit (WPB) function
- Programmable wrap sequence (Sequential/Interleave)
- Programmable burst length (1, 2, 4, 8 and full page)
- Programmable $\overline{\text{CAS}}$ latency (1, 2, and 3)
- Power Down operation and Clock Suspend operation
- Auto refresh (CBR refresh) or self refresh capability
- Single 3.3 V \pm 0.3 V power supply
- LVTTTL compatible inputs and outputs
- 100-pin Plastic QFP (14 \times 20 mm)
- 1,024 refresh cycles/16 ms
- Burst termination by Precharge command
- Burst termination by Burst stop command (in case of full-page burst)

Ordering Information

Part number	Cycle time ns (MIN.)	Clock frequency MHz (MAX.)	Package
μ PD481850GF-A10-JBT	10	100	100-pin Plastic QFP (14 \times 20 mm)
μ PD481850GF-A12-JBT	12	83	
μ PD481850GF-A15-JBT	15	66	

The information in this document is subject to change without notice.

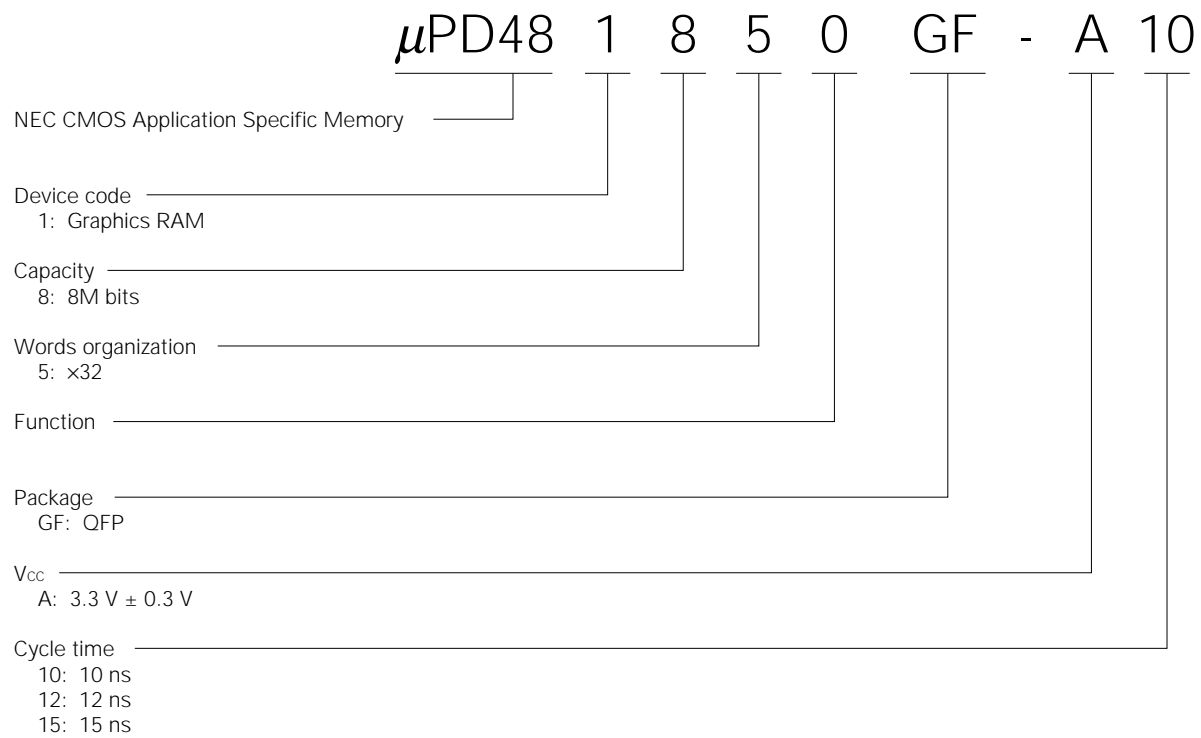
NEC

DATA SHEET

μPD481850 (PRELIMINARY)

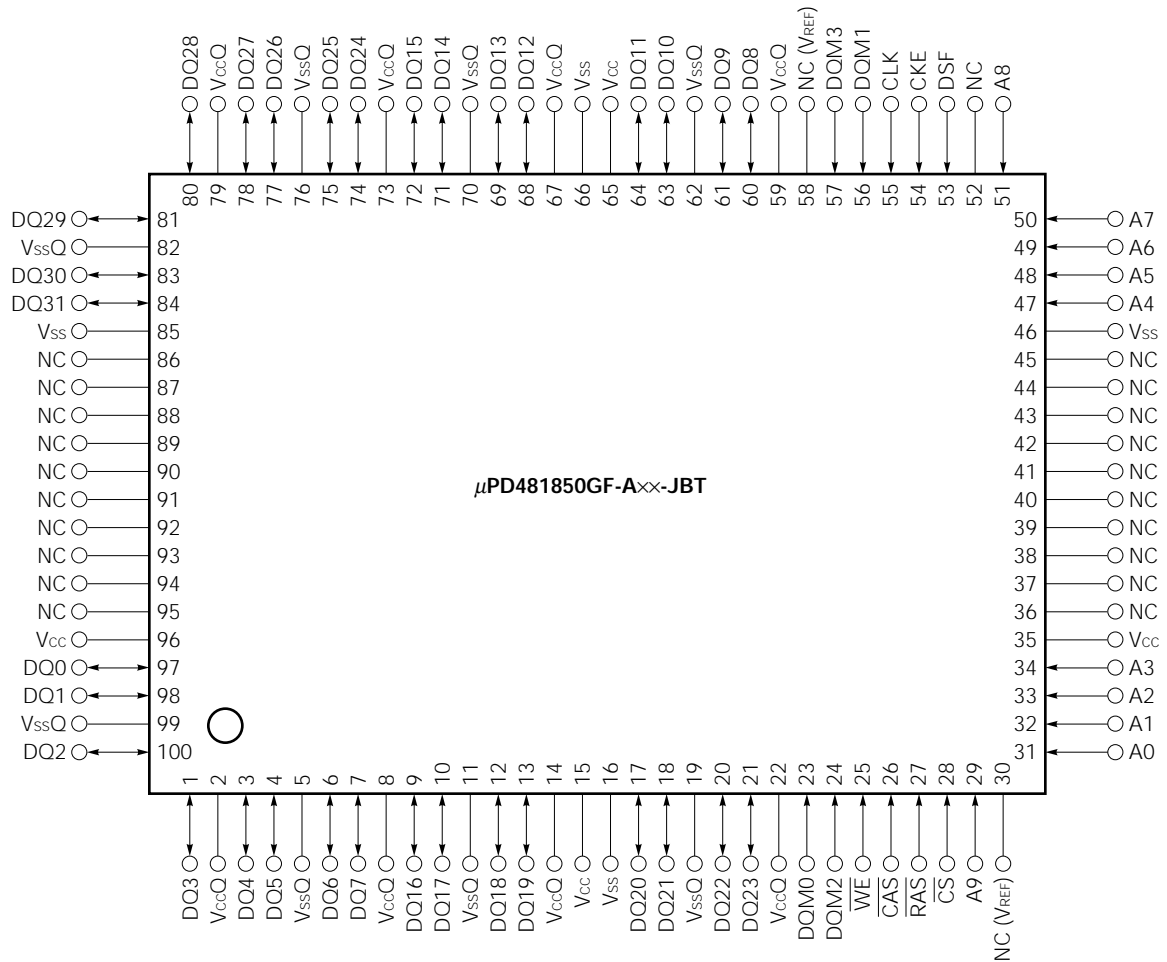
Part Number

Synchronous GRAM



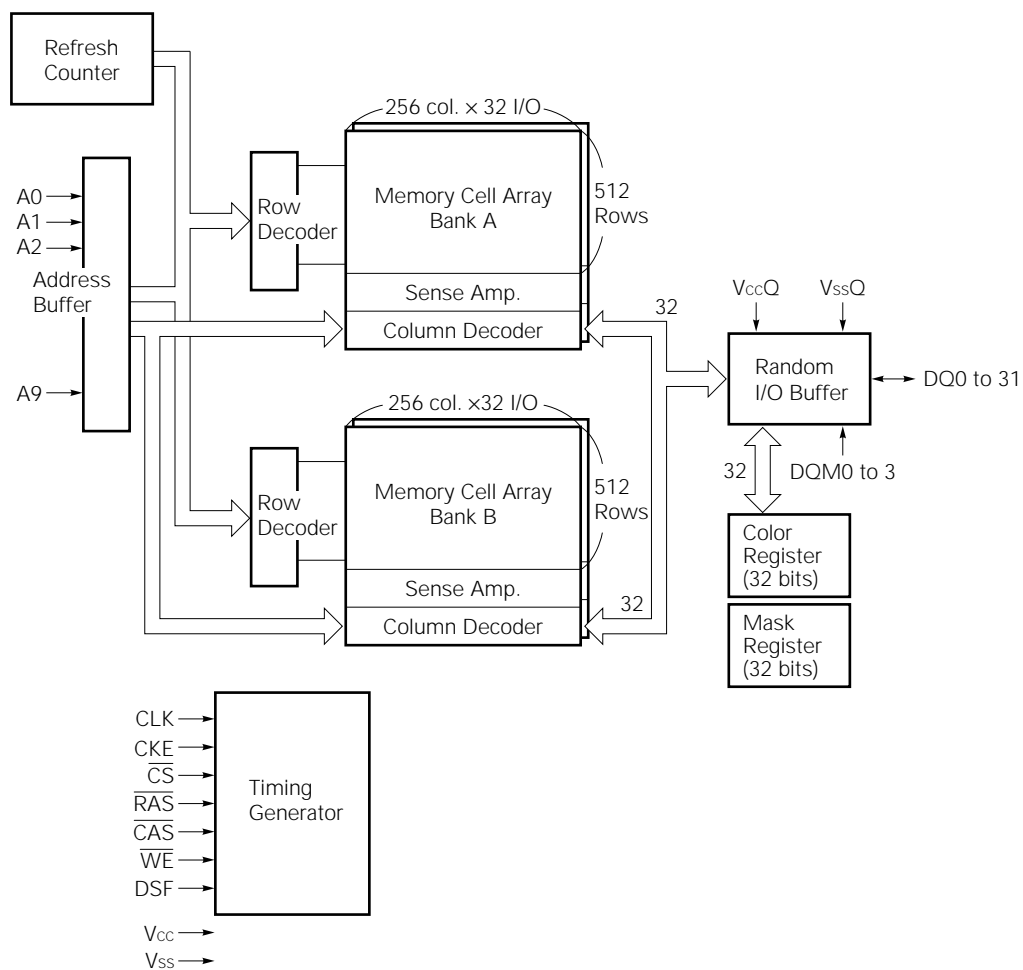
Pin Configuration (Marking Side)

100-pin Plastic QFP (14 × 20 mm)



- A0 - A9 : Address inputs
- A0 - A8 : Row address inputs
- A0 - A7 : Column address inputs
- A9 : Bank address
- DQ0 - DQ31 : Data inputs/outputs
- \overline{CS} : Chip select
- \overline{RAS} : Row address strobe
- \overline{CAS} : Column address strobe
- \overline{WE} : Write enable
- DQM0 - DQM3 : DQ mask enable
- DSF : Special function enable
- CKE : Clock enable
- CLK : System clock input
- Vcc : Supply voltage
- Vss : Ground
- VccQ : Supply voltage for DQ
- VssQ : Ground for DQ
- NC : No connection

Block Diagram



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1. Input/Output Pin Function

Pin name	Input/Output	Function
CLK	Input	CLK is the master clock input. Other inputs signals are referenced to the CLK rising edge.
CKE	Input	CKE determine validity of the next CLK (clock). If CKE is high, the next CLK rising edge is valid; otherwise it is invalid. If the CLK rising edge is invalid, the internal clock is not asserted and the μPD481850 suspends operation. When the μPD481850 is not in burst mode and CKE is negated, the device enters power down mode. During power down mode, CKE must remain low. In Self refresh mode, low level on this pin is also used as part of the input command to specify Self refresh.
\overline{CS}	Input	\overline{CS} low starts the command input cycle. When \overline{CS} is high, commands are ignored but operations continue.
\overline{RAS} , \overline{CAS} , \overline{WE}	Input	\overline{RAS} , \overline{CAS} and \overline{WE} have the same symbols on conventional DRAM but different functions. For details, refer to the command table.
DSF	Input	DSF is part of the inputs of graphics command of the μPD481850. If DSF is inactive (Low level), μPD481850 operates as same as SDRAM.
A0 - A8	Input	Row Address is determined by A0 - A8 at the CLK (clock) rising edge in the activate command cycle. Column Address is determined by A0 - A7 at the CLK rising edge in the read or write command cycle. A8 defines the precharge mode. When A8 is high in the precharge command cycle, both banks are precharged; when A8 is low, only the bank selected by A9 is precharged. When A8 high in read or write command cycle, the precharge start automatically after the burst access.
A9		A9 is the bank select signal (BA). In command cycle, A9 low selects bank A and A9 high selects bank B.
DQM0 - DQM3	Input	DQM controls I/O buffers. DQM0 corresponds to the lowest byte (DQ0 to DQ7), DQM1 corresponds to DQ8 to DQ15, DQM2 corresponds to DQ16 to DQ23. DQM3 corresponds to DQ24 to DQ31. In read mode, DQM controls the output buffers like a conventional \overline{OE} pin. DQM high and DQM low turn the output buffers off and on, respectively. The DQM latency for the read is two clocks. In write mode, DQM controls the word mask. Input data is written to the memory cell if DQM is low but not if DQM is high. The DQM latency for the write is zero.
DQ0 - DQ31	Input/Output	DQ pins have the same function as I/O pins on a conventional DRAM. These are normally 32-bit data bus and are used for inputting and outputting data. · Function as the mask data input pins in the special register set command. Write operations can be performed after Active command with WPB (old mask data). · Functions as the column selection data input pin in the block write cycle.
V _{CC} V _{SS} V _{CCQ} V _{SSQ}	(Power supply)	V _{CC} and V _{SS} are power supply pins for internal circuits. V _{CCQ} and V _{SSQ} are power supply pins for the output buffers.

2. Commands

Mode register set command

$$(\overline{CS}, \overline{RAS}, \overline{CAS}, \overline{WE}, DSF = \text{Low})$$

The μPD481850 has a mode register that defines how the device operates. In this command, A0 through A9 are the data input pins. After power on, the mode register set command must be executed to initialize the device.

The mode register can be set only when both banks are in idle state.

During 20 ns (t_{RSC}) following this command, the μPD481850 cannot accept any other commands.

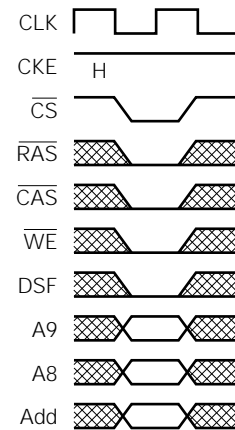


Fig. 1 Mode register set command

Bank activate command

$$(\overline{CS}, \overline{RAS}, DSF = \text{Low}, \overline{CAS}, \overline{WE} = \text{High})$$

The μPD481850 has two banks, each with 512 rows.

This command activates the bank selected by A9 (BA) and a row address selected by A0 through A8.

This command corresponds to a conventional DRAM's \overline{RAS} falling.

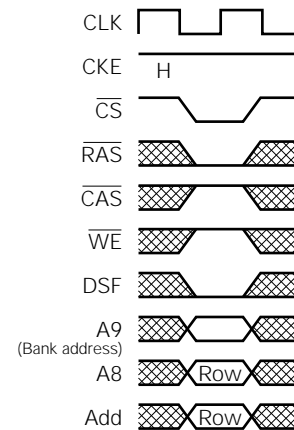


Fig. 2 Row address strobe and bank active command

Bank activate command with WPB enable

$$(\overline{CS}, \overline{RAS} = \text{Low}, \overline{CAS}, \overline{WE}, DSF = \text{High})$$

This command is same as Bank activate command. After this command, write per bit function is available. Mask register's data is used as write mask data.

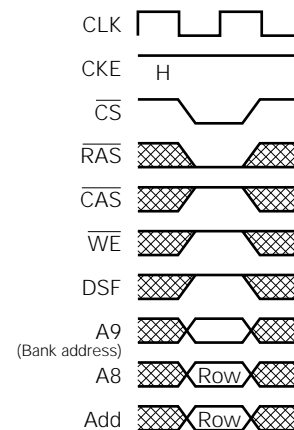


Fig. 3 Row address strobe and bank active command with WPB enable

Precharge command

$$(\overline{CS}, \overline{RAS}, \overline{WE}, DSF = \text{Low}, \overline{CAS} = \text{High})$$

This command begins precharge operation of the bank selected by A9 (BA) and A8. When A8 is High, both banks are precharged, regardless of A9. When A8 is Low, only the bank selected by A9 is precharged. A9 low selects bank A and A9 high selects bank B.

After this command, the μPD481850 can't accept the activate command to the precharging bank during t_{RP} (precharge to activate command period). This command can terminate the current burst operation (2, 4, 8, full page burst length).

This command corresponds to a conventional DRAM's \overline{RAS} rising.

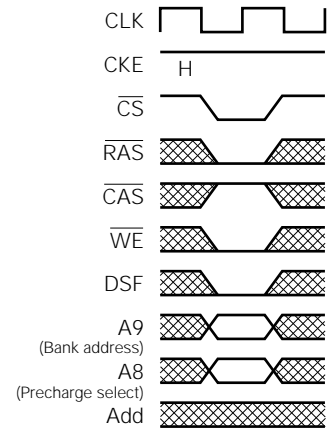


Fig. 4 Precharge command

Write command

$$(\overline{CS}, \overline{CAS}, \overline{WE}, DSF = \text{Low}, \overline{RAS} = \text{High})$$

If the mode register is in the burst write mode, this command sets the burst start address given by the column address to begin the burst write operation. The first write data must be input with this write operation. The first write data in burst mode can input with this command with subsequent data on following clocks.

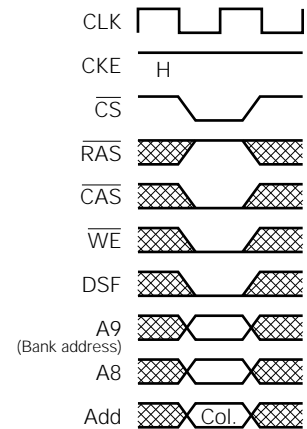


Fig. 5 Column address and write command

Read command

$$(\overline{CS}, \overline{CAS}, DSF = \text{Low}, \overline{RAS}, \overline{WE} = \text{High})$$

This command sets the burst start address given by the column address.

Read data is available after \overline{CAS} latency requirements have been met.

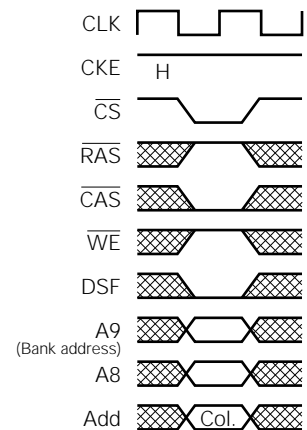


Fig. 6 Column address and read command

CBR (auto) refresh command

$$(\overline{CS}, \overline{RAS}, \overline{CAS}, DSF = \text{Low}, \overline{WE}, \text{CKE} = \text{High})$$

This command is a request to begin the CBR refresh operation. The refresh address is generated internally.

Before executing CBR refresh, both banks must be precharged.

After this cycle, both banks will be in the idle (precharged) state and ready for a bank activate command.

During t_{RC} period (from refresh command to refresh or activate command), the μPD481850 cannot accept any other command.

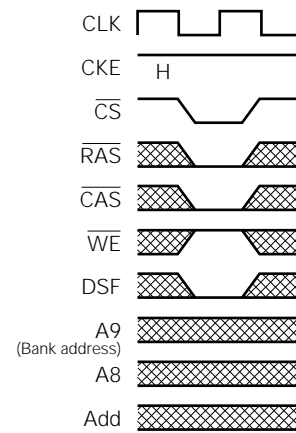


Fig. 7 Auto refresh command

Self refresh entry command

$$(\overline{CS}, \overline{RAS}, \overline{CAS}, DSF, \text{CKE} = \text{Low}, \overline{WE} = \text{High})$$

After the command execution, self refresh operation continues while CKE remains low. When CKE goes high, the μPD481850 exits the self refresh mode.

During self refresh mode, refresh interval and refresh operation are performed internally, so there is no need for external control.

Before executing self refresh, both banks must be precharged.

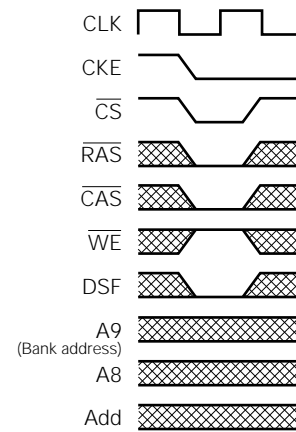


Fig. 8 Self refresh entry command

Burst stop command in full page

$$(\overline{CS}, \overline{WE}, DSF = \text{Low}, \overline{RAS}, \overline{CAS} = \text{High})$$

This command can stop the current full page burst (BL = 256) operation. If BL is set to 2, 4, 8, to execute this command is Nop.

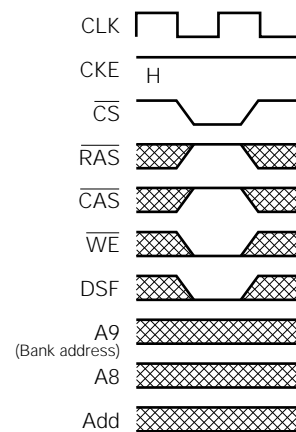


Fig. 9 Burst stop command in Full Page mode

No operation

(\overline{CS} , DSF = Low, \overline{RAS} , \overline{CAS} , \overline{WE} = High)

This command is not a execution command. No operations begin or terminate by this command.

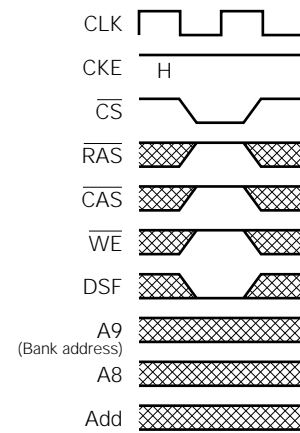


Fig. 10 No operation

Special register set command

(\overline{CS} , \overline{RAS} , \overline{CAS} , \overline{WE} = Low, DSF = High)

The μPD481850 has two special registers for graphics commands. One is color register and the other is mask register. In this command, A0 through A9 are the data input pins for the register select (color or mask register). DQ0 through DQ31 are the data input pins for the Color data or the WPB data.

During 20 ns (t_{RSC}) following this command, the μPD481850 can not accept any other commands.

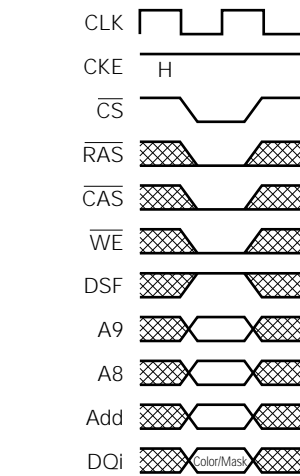


Fig. 11 Mode register set command

Masked block write command

(\overline{CS} , \overline{CAS} , \overline{WE} = Low, \overline{RAS} , DSF = High)

This command activates 8-column block write function. This command assumes as burst length = 1. Write data comes from color register, column address mask data is input from DQi in this command.

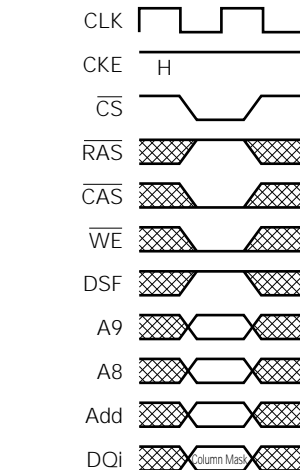
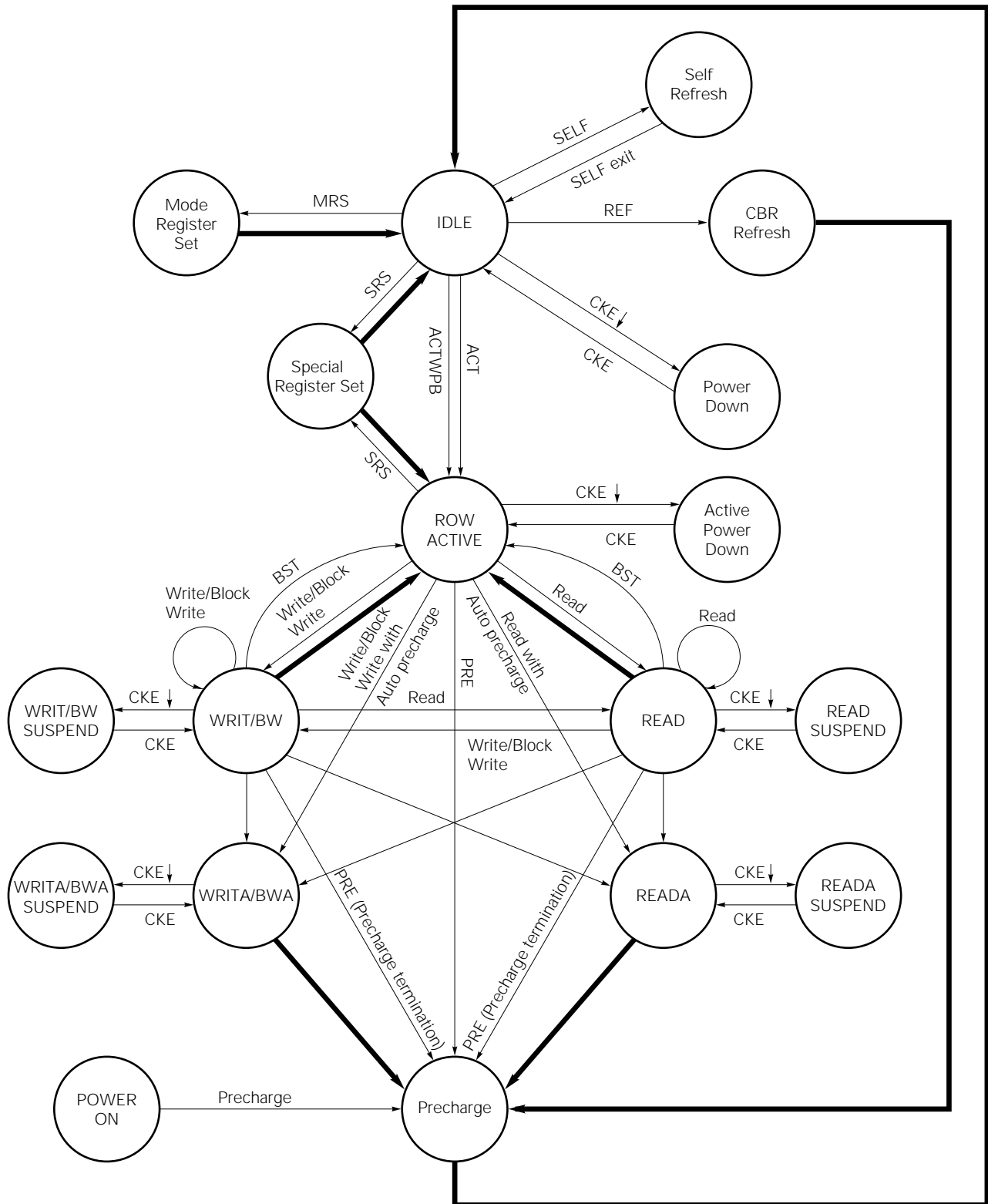


Fig. 12 Mode register set command

3. Simplified State Diagram



 Automatic sequence
 Manual input

4. Truth Table

4.1 Command Truth Table

Function	Symbol	CKE		\overline{CS}	\overline{RAS}	\overline{CAS}	\overline{WE}	DSF	Address		
		n-1	n						A9	A8	A7 - A0
Device deselect	DESL	H	×	H	×	×	×	×	×	×	×
No operation	NOP	H	×	L	H	H	H	L	×	×	×
Burst stop in full page	BST	H	×	L	H	H	L	L	×	×	×
Read	READ	H	×	L	H	L	H	L	BA	L	CA
Read with auto precharge	READA	H	×	L	H	L	H	L	BA	H	CA
Write	WRIT	H	×	L	H	L	L	L	BA	L	CA
Write with auto precharge	WRITA	H	×	L	H	L	L	L	BA	H	CA
Masked block write	BW	H	×	L	H	L	L	H	BA	L	CA
Masked block write with auto precharge	BWA	H	×	L	H	L	L	H	BA	H	CA
Bank activate	ACT	H	×	L	L	H	H	L	BA	RA	
Bank activate with WPB enable	ACTWPB	H	×	L	L	H	H	H	BA	RA	
Precharge select bank	PRE	H	×	L	L	H	L	L	BA	L	×
Precharge all banks	PALL	H	×	L	L	H	L	L	×	H	×
Mode register set	MRS	H	×	L	L	L	L	L	OP. CODE		
Special register set	SRS	H	×	L	L	L	L	H	OP. CODE		

Remark Legend:

H = High level, L = Low level, × = High or Low level (Don't care), BA = Bank address (A9), RA = Row address, CA = Column address

4.2 DQM Truth Table

Function	Symbol	CKE		DQM _i
		n-1	n	
Data write/output enable	ENB _i	H	×	L
Data mask/output disable	MASK _i	H	×	H

Remark Legend:

H = High level, L = Low level, × = High or Low level (Don't care), i = 0, 1, 2, 3

4.3 CKE Truth Table

Current state	Function	Symbol	CKE		\overline{CS}	\overline{RAS}	\overline{CAS}	\overline{WE}	DSF	Address
			n-1	n						
Activating	Clock suspend mode entry		H	L	×	×	×	×	×	×
Any	Clock suspend		L	L	×	×	×	×	×	×
Clock suspend	Clock suspend mode exit		L	H	×	×	×	×	×	×
Idle	CBR refresh command	REF	H	H	L	L	L	H	L	×
Idle	Self refresh entry	SELF	H	L	L	L	L	H	L	×
			L	H	L	H	H	H	×	×
Self refresh	Self refresh exit		L	H	H	×	×	×	×	×
Idle	Power down entry		H	L	×	×	×	×	×	×
Power down	Power down exit		L	H	×	×	×	×	×	×

Remark Legend:

H = High Level, L = Low level, × = High or Low level (Don't care)

4.4 Operative Command Table^{Note 1}

(1/7)

Current state	\overline{CS}	\overline{RAS}	\overline{CAS}	\overline{WE}	DSF	Address	Command	Action	Notes
Idle	H	x	x	x	x	x	DESL	Nop or Power down	2
	L	H	H	H	x	x	NOP	Nop or Power down	2
	L	H	H	L	H	x	Undefined	ILLEGAL	
	L	H	H	L	L	x	BST	ILLEGAL	3
	L	H	L	H	H	x	Undefined	ILLEGAL	
	L	H	L	H	L	BA, CA, A8	READ/READA	ILLEGAL	3
	L	H	L	L	H	BA, CA, A8	BW/BWA	ILLEGAL	3
	L	H	L	L	L	BA, CA, A8	WRIT/WRITA	ILLEGAL	3
	L	L	H	H	H	BA, RA	ACTWPB	Bank active with WPB: Latch RA	
	L	L	H	H	L	BA, RA	ACT	Bank active: Latch RA	
	L	L	H	L	H	x	Undefined	ILLEGAL	
	L	L	H	L	L	BA, A8	PRE/PALL	Nop	11
	L	L	L	H	H	x	Undefined	ILLEGAL	
	L	L	L	H	L	x	REF/SELF	CBR refresh/Self refresh	4, 12
	L	L	L	L	H	Op-Code	SRS	Special register access	
L	L	L	L	L	Op-Code	MRS	Mode register access	12	
Bank active	H	x	x	x	x	x	DESL	Nop	
	L	H	H	H	x	x	NOP	Nop	
	L	H	H	L	H	x	Undefined	ILLEGAL	
	L	H	H	L	L	x	BST	ILLEGAL	3
	L	H	L	H	H	x	Undefined	ILLEGAL	
	L	H	L	H	L	BA, CA, A8	READ/READA	Begin read; Latch CA: Determine AP	5
	L	H	L	L	H	BA, CA, A8	BW/BWA	Begin block write: Latch CA: Determine AP	5
	L	H	L	L	L	BA, CA, A8	WRIT/WRITA	Begin write; Latch CA: Determine AP	5
	L	L	H	H	H	BA, RA	ACTWPB	ILLEGAL	3
	L	L	H	H	L	BA, RA	ACT	ILLEGAL	3
	L	L	H	L	H	x	Undefined	ILLEGAL	
	L	L	H	L	L	BA, A8	PRE/PALL	Precharge	6
	L	L	L	H	H	x	Undefined	ILLEGAL	
	L	L	L	H	L	x	REF/SELF	ILLEGAL	
	L	L	L	L	H	Op-Code	SRS	Special register access	
L	L	L	L	L	Op-Code	MRS	ILLEGAL		

(2/7)

Current state	CS	RAS	CAS	WE	DSF	Address	Command	Action	Notes
Read	H	×	×	×	×	×	DESL	Continue burst to end → Bank active	
	L	H	H	H	×	×	NOP	Continue burst to end → Bank active	
	L	H	H	L	H	×	Undefined	ILLEGAL	
	L	H	H	L	L	×	BST	1, 2, 4, 8 burst length; Nop (Continue burst to end → Bank active) Full page burst; Burst stop → Bank active	
	L	H	L	H	H	×	Undefined	ILLEGAL	
	L	H	L	H	L	BA, CA, A8	READ/READA	Term burst, new read: Determine AP	7
	L	H	L	L	H	BA, CA, A8	BW/BWA	Term burst, Start block write: Determine AP	7, 8
	L	H	L	L	L	BA, CA, A8	WRIT/WRITA	Term burst, start write: Determine AP	7, 8
	L	L	H	H	H	BA, RA	ACTWPB	ILLEGAL	3
	L	L	H	H	L	BA, RA	ACT	ILLEGAL	3
	L	L	H	L	H	×	Undefined	ILLEGAL	
	L	L	H	L	L	BA, A8	PRE/PALL	Term burst, precharge timing for reads	
	L	L	L	H	H	×	Undefined	ILLEGAL	
	L	L	L	H	L	×	REF/SELF	ILLEGAL	
	L	L	L	L	H	Op-Code	SRS	ILLEGAL	
L	L	L	L	L	Op-Code	MRS	ILLEGAL		
Write/Block write	H	×	×	×	×	×	DESL	Continue burst to end → Write recovering	
	L	H	H	H	×	×	NOP	Continue burst to end → Write recovering	
	L	H	H	L	H	×	Undefined	ILLEGAL	
	L	H	H	L	L	×	BST	1, 2, 4, 8 burst length; Nop (Continue burst to end → Bank active) Full page burst; Burst stop → Bank active	
	L	H	L	H	H	×	Undefined	ILLEGAL	
	L	H	L	H	L	BA, CA, A8	READ/READA	Term burst, start read: Determine AP	7, 8
	L	H	L	L	H	BA, CA, A8	BW/BWA	Term burst, new block write: Determine AP	7
	L	H	L	L	L	BA, CA, A8	WRIT/WRITA	Term burst, new write: Determine AP	7
	L	L	H	H	H	BA, RA	ACTWPB	ILLEGAL	3
	L	L	H	H	L	BA, RA	ACT	ILLEGAL	3
	L	L	H	L	H	×	Undefined	ILLEGAL	
	L	L	H	L	L	BA, A8	PRE/PALL	Term burst, precharge timing for writes	3, 9
	L	L	L	H	H	×	Undefined	ILLEGAL	
	L	L	L	H	L	×	REF/SELF	ILLEGAL	
	L	L	L	L	H	Op-Code	SRS	ILLEGAL	
L	L	L	L	L	Op-Code	MRS	ILLEGAL		

(3/7)

Current state	\overline{CS}	RAS	\overline{CAS}	WE	DSF	Address	Command	Action	Notes
Read with auto precharge	H	×	×	×	×	×	DESL	Continue burst to end → precharging	
	L	H	H	H	×	×	NOP	Continue burst to end → precharging	
	L	H	H	L	H	×	Undefined	ILLEGAL	
	L	H	H	L	L	×	BST	ILLEGAL	
	L	H	L	H	H	×	Undefined	ILLEGAL	
	L	H	L	H	L	BA, CA, A8	READ/READA	ILLEGAL	
	L	H	L	L	H	BA, CA, A8	BW/BWA	ILLEGAL	
	L	H	L	L	L	BA, CA, A8	WRIT/WRITA	ILLEGAL	
	L	L	H	H	H	BA, RA	ACTWPB	ILLEGAL	3
	L	L	H	H	L	BA, RA	ACT	ILLEGAL	3
	L	L	H	L	H	×	Undefined	ILLEGAL	
	L	L	H	L	L	BA, A8	PRE/PALL	ILLEGAL	3
	L	L	L	H	H	×	Undefined	ILLEGAL	
	L	L	L	H	L	×	REF/SELF	ILLEGAL	
	L	L	L	L	H	Op-Code	SRS	ILLEGAL	
L	L	L	L	L	Op-Code	MRS	ILLEGAL		
Write/Block write with auto precharge	H	×	×	×	×	×	DESL	Continue burst to end → Write recovering with auto precharge	
	L	H	H	H	×	×	NOP	Continue burst to end → Write recovering with auto precharge	
	L	H	H	L	H	×	Undefined	ILLEGAL	
	L	H	H	L	L	×	BST	ILLEGAL	
	L	H	L	H	H	×	Undefined	ILLEGAL	
	L	H	L	H	L	BA, CA, A8	READ/READA	ILLEGAL	
	L	H	L	L	H	BA, CA, A8	BW/BWA	ILLEGAL	
	L	H	L	L	L	BA, CA, A8	WRIT/WRITA	ILLEGAL	
	L	L	H	H	H	BA, RA	ACTWPB	ILLEGAL	3
	L	L	H	H	L	BA, RA	ACT	ILLEGAL	3
	L	L	H	L	H	×	Undefined	ILLEGAL	
	L	L	H	L	L	BA, A8	PRE/PALL	ILLEGAL	3
	L	L	L	H	H	×	Undefined	ILLEGAL	
	L	L	L	H	L	×	REF/SELF	ILLEGAL	
	L	L	L	L	H	Op-Code	SRS	ILLEGAL	
L	L	L	L	L	Op-Code	MRS	ILLEGAL		

(4/7)

Current state	CS	RAS	CAS	WE	DSF	Address	Command	Action	Notes
Precharging	H	×	×	×	×	×	DESL	Nop → Enter idle after t_{RP}	
	L	H	H	H	×	×	NOP	Nop → Enter idle after t_{RP}	
	L	H	H	L	H	×	Undefined	ILLEGAL	
	L	H	H	L	L	×	BST	ILLEGAL	3
	L	H	L	H	H	×	Undefined	ILLEGAL	
	L	H	L	H	L	BA, CA, A8	READ/READA	ILLEGAL	3
	L	H	L	L	H	BA, CA, A8	BW/BWA	ILLEGAL	3
	L	H	L	L	L	BA, CA, A8	WRIT/WRITA	ILLEGAL	3
	L	L	H	H	H	BA, RA	ACTWPB	ILLEGAL	3
	L	L	H	H	L	BA, RA	ACT	ILLEGAL	3
	L	L	H	L	H	×	Undefined	ILLEGAL	
	L	L	H	L	L	BA, A8	PRE/PALL	Nop → Enter idle after t_{RP}	11
	L	L	L	H	H	×	Undefined	ILLEGAL	
	L	L	L	H	L	×	REF/SELF	ILLEGAL	
	L	L	L	L	H	Op-Code	SRS	Special register access	
L	L	L	L	L	Op-Code	MRS	ILLEGAL		
Bank activating (t_{RCD})	H	×	×	×	×	×	DESL	Nop → Enter bank active after t_{RCD}	
	L	H	H	H	×	×	NOP	Nop → Enter bank active after t_{RCD}	
	L	H	H	L	H	×	Undefined	ILLEGAL	
	L	H	H	L	L	×	BST	ILLEGAL	3
	L	H	L	H	H	×	Undefined	ILLEGAL	
	L	H	L	H	L	BA, CA, A8	READ/READA	ILLEGAL	3
	L	H	L	L	H	BA, CA, A8	BW/BWA	ILLEGAL	3
	L	H	L	L	L	BA, CA, A8	WRIT/WRITA	ILLEGAL	3
	L	L	H	H	H	BA, RA	ACTWPB	ILLEGAL	3, 10
	L	L	H	H	L	BA, RA	ACT	ILLEGAL	3, 10
	L	L	H	L	H	×	Undefined	ILLEGAL	
	L	L	H	L	L	BA, A8	PRE/PALL	ILLEGAL	3
	L	L	L	H	H	×	Undefined	ILLEGAL	
	L	L	L	H	L	×	REF/SELF	ILLEGAL	
	L	L	L	L	H	Op-Code	SRS	Special register access	
L	L	L	L	L	Op-Code	MRS	ILLEGAL		

(5/7)

Current state	\overline{CS}	RAS	\overline{CAS}	WE	DSF	Address	Command	Action	Notes
Write recovering (t_{DPL})	H	×	×	×	×	×	DESL	Nop → Enter bank active after t_{DPL}	
	L	H	H	H	×	×	NOP	Nop → Enter bank active after t_{DPL}	
	L	H	H	L	H	×	Undefined	ILLEGAL	
	L	H	H	L	L	×	BST	ILLEGAL	3
	L	H	L	H	H	×	Undefined	ILLEGAL	
	L	H	L	H	L	BA, CA, A8	READ/READA	Begin read; Latch CA: Determine AP	8
	L	H	L	L	H	BA, CA, A8	BW/BWA	Begin block write; Latch CA: Determine AP	
	L	H	L	L	L	BA, CA, A8	WRIT/WRITA	Begin write; Latch CA: Determine AP	
	L	L	H	H	H	BA, RA	ACTWPB	ILLEGAL	3
	L	L	H	H	L	BA, RA	ACT	ILLEGAL	3
	L	L	H	L	H	×	Undefined	ILLEGAL	
	L	L	H	L	L	BA, A8	PRE/PALL	ILLEGAL	3
	L	L	L	H	H	×	Undefined	ILLEGAL	
	L	L	L	H	L	×	REF/SELF	ILLEGAL	
	L	L	L	L	H	Op-Code	SRS	Special register access	
L	L	L	L	L	Op-Code	MRS	ILLEGAL		
Write recovering with auto precharge	H	×	×	×	×	×	DESL	Nop → Enter precharge after t_{DPL}	
	L	H	H	H	×	×	NOP	Nop → Enter precharge after t_{DPL}	
	L	H	H	L	H	×	Undefined	ILLEGAL	
	L	H	H	L	L	×	BST	ILLEGAL	
	L	H	L	H	H	×	Undefined	ILLEGAL	
	L	H	L	H	L	BA, CA, A8	READ/READA	ILLEGAL	3, 8
	L	H	L	L	H	BA, CA, A8	BW/BWA	ILLEGAL	3
	L	H	L	L	L	BA, CA, A8	WRIT/WRITA	ILLEGAL	3
	L	L	H	H	H	BA, RA	ACTWPB	ILLEGAL	3
	L	L	H	H	L	BA, RA	ACT	ILLEGAL	3
	L	L	H	L	H	×	Undefined	ILLEGAL	
	L	L	H	L	L	BA, A8	PRE/PALL	ILLEGAL	3
	L	L	L	H	H	×	Undefined	ILLEGAL	
	L	L	L	H	L	×	REF/SELF	ILLEGAL	
	L	L	L	L	H	Op-Code	SRS	Special register access	
L	L	L	L	L	Op-Code	MRS	ILLEGAL		

(6/7)

Current state	CS	RAS	CAS	WE	DSF	Address	Command	Action	Notes
Refreshing	H	×	×	×	×	×	DESL	Nop → Enter idle after t_{RC}	
	L	H	H	H	×	×	NOP	Nop → Enter idle after t_{RC}	
	L	H	H	L	H	×	Undefined	ILLEGAL	
	L	H	H	L	L	×	BST	ILLEGAL	
	L	H	L	H	H	×	Undefined	ILLEGAL	
	L	H	L	H	L	BA, CA, A8	READ/READA	ILLEGAL	
	L	H	L	L	H	BA, CA, A8	BW/BWA	ILLEGAL	
	L	H	L	L	L	BA, CA, A8	WRIT/WRITA	ILLEGAL	
	L	L	H	H	H	BA, RA	ACTWPB	ILLEGAL	
	L	L	H	H	L	BA, RA	ACT	ILLEGAL	
	L	L	H	L	H	×	Undefined	ILLEGAL	
	L	L	H	L	L	BA, A8	PRE/PALL	ILLEGAL	
	L	L	L	H	H	×	Undefined	ILLEGAL	
	L	L	L	H	L	×	REF/SELF	ILLEGAL	
	L	L	L	L	H	Op-Code	SRS	ILLEGAL	
	L	L	L	L	L	Op-Code	MRS	ILLEGAL	
Mode register accessing	H	×	×	×	×	×	DESL	Nop → Enter idle after t_{RSC}	
	L	H	H	H	×	×	NOP	Nop → Enter idle after t_{RSC}	
	L	H	H	L	H	×	Undefined	ILLEGAL	
	L	H	H	L	L	×	BST	ILLEGAL	
	L	H	L	H	H	×	Undefined	ILLEGAL	
	L	H	L	H	L	BA, CA, A8	READ/READA	ILLEGAL	
	L	H	L	L	H	BA, CA, A8	BW/BWA	ILLEGAL	
	L	H	L	L	L	BA, CA, A8	WRIT/WRITA	ILLEGAL	
	L	L	H	H	H	BA, RA	ACTWPB	ILLEGAL	
	L	L	H	H	L	BA, RA	ACT	ILLEGAL	
	L	L	H	L	H	×	Undefined	ILLEGAL	
	L	L	H	L	L	BA, A8	PRE/PALL	ILLEGAL	
	L	L	L	H	H	×	Undefined	ILLEGAL	
	L	L	L	H	L	×	REF/SELF	ILLEGAL	
	L	L	L	L	H	Op-Code	SRS	ILLEGAL	
	L	L	L	L	L	Op-Code	MRS	ILLEGAL	

(7/7)

Current state	CS	RAS	CAS	WE	DSF	Address	Command	Action	Notes
Special mode register accessing	H	×	×	×	×	×	DESL	Nop → Enter previous state after t _{RSC}	
	L	H	H	H	×	×	NOP	Nop → Enter previous state after t _{RSC}	
	L	H	H	L	H	×	Undefined	ILLEGAL	
	L	H	H	L	L	×	BST	ILLEGAL	
	L	H	L	H	H	×	Undefined	ILLEGAL	
	L	H	L	H	L	BA, CA, A8	READ/READA	ILLEGAL	
	L	H	L	L	H	BA, CA, A8	BW/BWA	ILLEGAL	
	L	H	L	L	L	BA, CA, A8	WRIT/WRITA	ILLEGAL	
	L	L	H	H	H	BA, RA	ACTWPB	ILLEGAL	
	L	L	H	H	L	BA, RA	ACT	ILLEGAL	
	L	L	H	L	H	×	Undefined	ILLEGAL	
	L	L	H	L	L	BA, A8	PRE/PALL	ILLEGAL	
	L	L	L	H	H	×	Undefined	ILLEGAL	
	L	L	L	H	L	×	REF/SELF	ILLEGAL	
	L	L	L	L	H	Op-Code	SRS	ILLEGAL	
L	L	L	L	L	Op-Code	MRS	ILLEGAL		

- Notes**
1. All entries assume that CKE was active (High level) during the preceding clock cycle.
 2. If both banks are idle, and CKE is inactive (Low level), μPD481850 will enter Power down mode. All input buffers except CKE will be disabled.
 3. Illegal to bank in specified states; Function may be legal in the bank indicated by Bank Address (BA), depending on the state of that bank.
 4. If both banks are idle, and CKE is inactive (Low level), μPD481850 will enter Self refresh. All input buffers except CKE will be disabled.
 5. Illegal if t_{RCD} is not satisfied.
 6. Illegal if t_{RAS} is not satisfied.
 7. Must satisfy burst interrupt condition.
 8. Must satisfy bus contention, bus turn around, and/or write recovery requirements.
 9. Must mask preceding data which don't satisfy t_{DPL}.
 10. Illegal if t_{RRD} is not satisfied.
 11. Nop to bank precharging or in idle state. May precharge bank(s) indicated by BA (and A8).
 12. Illegal if any bank is not idle.

Remark Legend:

H = High level, L = Low level, × = High or Low level (Don't care), V = Valid Data input,
 BA = Bank address (A9), A8 = Precharge select, RA = Row address, CA = Column address,
 Term = Terminate, AP = Auto precharge, NOP = No operation,
 ILLEGAL = Device operation and/or data-integrity are not guaranteed

4.5 Command Truth Table for CKE

Current state	CKE		\overline{CS}	\overline{RAS}	\overline{CAS}	\overline{WE}	DSF	Address	Action	Notes
	n-1	n								
Self refresh (S.R.)	H	x	x	x	x	x	x	x	INVALID, CLK(n-1) would exit S.R.	
	H	H	H	x	x	x	x	x	S.R. Recovery	1
	L	H	L	H	H	x	x	x	S.R. Recovery	1
	L	H	L	H	L	x	x	x	ILLEGAL	1
	L	H	L	L	x	x	x	x	ILLEGAL	1
	L	L	x	x	x	x	x	x	Maintain S.R.	
Self refresh recovery	H	H	H	x	x	x	x	x	Idle after t_{RC}	
	H	H	L	H	H	H	x	x	Idle after t_{RC}	
	H	H	L	H	H	L	x	x	ILLEGAL	
	H	H	L	H	L	x	x	x	ILLEGAL	
	H	H	L	L	x	x	x	x	ILLEGAL	
	H	L	H	x	x	x	x	x	Begin clock suspend next cycle	
	H	L	L	H	H	H	x	x	Begin clock suspend next cycle	
	H	L	L	H	L	x	x	x	ILLEGAL	
	H	L	L	L	x	x	x	x	ILLEGAL	
	L	H	x	x	x	x	x	x	Exit clock suspend next cycle	1
	L	L	x	x	x	x	x	x	Maintain clock suspend	
Power down (P.D.)	H	x	x	x	x	x	x		INVALID, CLK(n-1) would exit P.D.	
	L	H	x	x	x	x	x	x	EXIT P.D. → Idle	1
	L	L	x	x	x	x	x	x	Maintain power down mode	
Both banks idle	H	H	H	x	x	x	x	x	Refer to operations in Operative Command Table	
	H	H	L	H	x	x	x	x	Refer to operations in Operative Command Table	
	H	H	L	L	H	x	x	x	Refer to operations in Operative Command Table	
	H	H	L	L	L	H	L	x	Refresh	
	H	H	L	L	L	L	x	Op-Code	Refer to operations in Operative Command Table	
	H	L	H	x	x	x	x	x	Refer to operations in Operative Command Table	
	H	L	L	H	x	x	x	x	Refer to operations in Operative Command Table	
	H	L	L	L	H	x	x	x	Refer to operations in Operative Command Table	
	H	L	L	L	L	H	L	x	Self refresh	2
	H	L	L	L	L	L	x	Op-Code	Refer to operations in Operative Command Table	
	L	x	x	x	x	x	x	x	Power down	2
Any state other than listed above	H	H	x	x	x	x	x	x	Refer to operations in Operative Command Table	
	H	L	x	x	x	x	x	x	Begin clock suspend next cycle	3
	L	H	x	x	x	x	x	x	Exit clock suspend next cycle	
	L	L	x	x	x	x	x	x	Maintain clock suspend	

- Notes**
1. CKE Low to High transition will re-enable CLK and other inputs asynchronously. A minimum setup time must be satisfied before any command other than EXIT.
 2. Power down and Self refresh can be entered only from the both banks idle state.
 3. Must be legal command as defined in Operative Command Table.

Remark Legend:

H = High level, L = Low level, x = High or Low level (Don't care)

4.6 Command Truth Table for Two Banks Operation

\overline{CS}	\overline{RAS}	\overline{CAS}	\overline{WE}	DSF	A9 (BA)	A8	A7 - A0	Action	"FROM" State ^{Note 1}	"TO" State ^{Note 2}
H	x	x	x	x	x	x	x	NOP	Any	Any
L	H	H	H	L	x	x	x	NOP	Any	Any
L	H	H	L	L	x	x	x	BST	(R/W/A)0(I/A)1	A0(I/A)1
									I0(I/A)1	I0(I/A)1
									(R/W/A)1(I/A)0	A1(I/A)0
									I1(I/A)0	I1(I/A)0
L	H	L	H	L	H	H	CA	Read	(R/W/A)1(I/A)0	RP1(I/A)0
					H	H	CA		A1(R/W)0	RP1A0
					H	L	CA		(R/W/A)1(I/A)0	R1(I/A)0
					H	L	CA		A1(R/W)0	R1A0
					L	H	CA		(R/W/A)0(I/A)1	RP0(I/A)1
					L	H	CA		A0(R/W)1	RP0A1
					L	L	CA		(R/W/A)0(I/A)1	R0(I/A)1
					L	L	CA		A0(R/W)1	R0A1
L	H	L	L	L/H	H	H	CA	Write/Block Write	(R/W/A)1(I/A)0	WP1(I/A)0
					H	H	CA		A1(R/W)0	WP1A0
					H	L	CA		(R/W/A)1(I/A)0	W1(I/A)0
					H	L	CA		A1(R/W)0	W1A0
					L	H	CA		(R/W/A)0(I/A)1	WP0(I/A)1
					L	H	CA		A0(R/W)1	WP0A1
					L	L	CA		(R/W/A)0(I/A)1	W0(I/A)1
					L	L	CA		A0(R/W)1	W0A1
L	L	H	H	L/H	H	RA		Activate Row	I1Any0	A1Any0
					L	RA			I0Any1	A0Any1
L	L	H	L	L	x	H	x	Precharge	(R/W/A/I)0(I/A)1	I0I1
					x	H	x		(R/W/A/I)1(I/A)0	I1I0
					H	L	x		(R/W/A/I)1(I/A)0	I1(I/A)0
					H	L	x		(I/A)1(R/W/A/I)0	I1(R/W/A/I)0
					L	L	x		(R/W/A/I)0(I/A)1	I0(I/A)1
					L	L	x		(I/A)0(R/W/A/I)1	I0(R/W/A/I)1
L	L	L	H	L	x	x	x	Refresh	I0I1	I0I1
L	L	L	L	L	Op-Code			Mode Register Access	I0I1	I0I1
L	L	L	L	H	Op-Code			Special Register Access	(I/A)0(I/A)1	(I/A)0(I/A)1

- Notes**
1. If the μPD481850 is in a state other than above listed in the "From State" column, the command is illegal.
 2. The states listed under "To" might not be entered on the next clock cycle. Timing restrictions apply.

Remark Legend:

H = High level, L = Low level, \times = High or Low level (Don't care),

BA = Bank address (A9), I = Idle, A = Bank active,

R = Read with No precharge (No precharge is posted)

W = Write with No precharge (No precharge is posted)

RP = Read with auto precharge (No precharge is posted)

WP = Write with auto precharge (No precharge is posted)

Any = Any State

X0Y1 = Bank0 is in state "X", Bank1 = in state "Y"

(X/Y)0Z1 = Z1(X/Y)0 = Bank0 is in state "X" or "Y", Bank1 is in state "Z"

5. Initialization

The synchronous GRAM is initialized in the power-on sequence according to the following.

- (1) To stabilize internal circuits, when power is applied, a 100- μ s or longer pause must precede any signal toggling.
- (2) After the pause, both banks must be precharged using the Precharge command (The Precharge all banks command is convenient).
- (3) Once the precharge is completed and the minimum t_{RP} is satisfied, the mode register can be programmed.
After the mode register set cycle, t_{RSC} (20 ns minimum) pause must be satisfied as well.
- (4) Two or more CBR (Auto) refresh must be performed.

- Remarks**
1. The sequence of Mode register programming and Refresh above may be transposed.
 2. CKE and DQM may be held high until the Precharge command is asserted to ensure data-bus Hi-Z.

6. Programming the Mode Register

The mode register is programmed by the Mode register set command using address bits A9 through A0 as data inputs. The register retains data until it is reprogrammed or the device loses power.

The mode register has four fields;

Options : A9 through A7
 $\overline{\text{CAS}}$ latency: A6 through A4
Wrap type : A3
Burst length: A2 through A0

Following mode register programming, no command can be asserted before at least 20 ns (t_{rsc}) have elapsed.

$\overline{\text{CAS}}$ Latency

$\overline{\text{CAS}}$ latency is the most critical of the parameters being set. It tells the device how many clocks must elapse before the data will be available.

The value is determined by the frequency of the clock and the speed grade of the device. The table on page 52 shows the relationship of $\overline{\text{CAS}}$ latency to the clock period and the speed grade of the device.

Burst Length

Burst Length is the number of words that will be output or input in a read or write cycle. After a read burst is completed, the output bus will become Hi-Z.

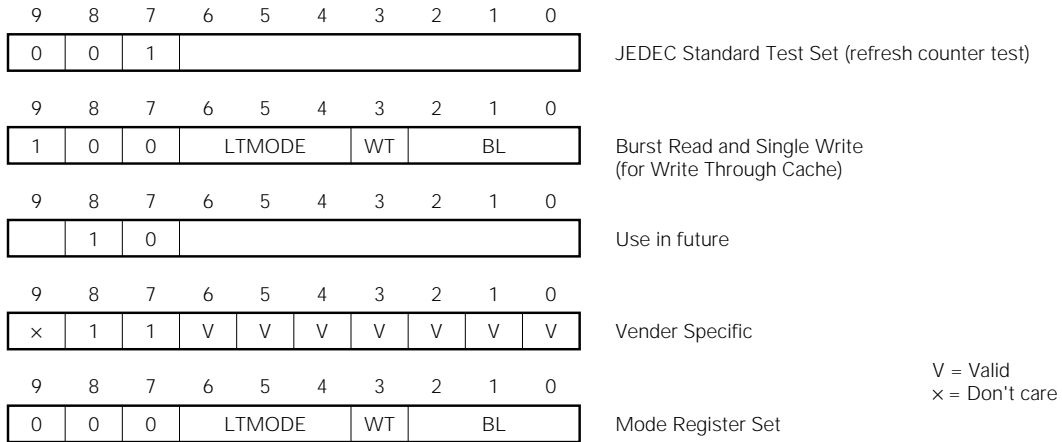
The burst length is programmable as 1, 2, 4, 8 or full page (256 columns).

Wrap Type (Burst Sequence)

The wrap type specifies the order in which the burst data will be addressed. This order is programmable as either "Sequential" or "Interleave". The method chosen will depend on the type of CPU in the system.

Some microprocessor cache system are optimized for sequential addressing and others for interleaved addressing. The table on the page 27 shows the addressing sequence for each burst length using them. Sequential mode supports bursts of 1, 2, 4 and 8, Interleave mode supports bursts of 4 and 8. Additionally, sequential sequence supports the full page length.

7. Mode Register



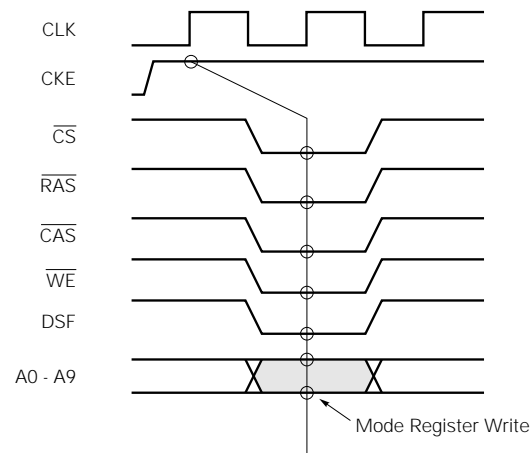
Burst length	Bits2-0	WT = 0	WT = 1
	000	1	R
	001	2	R
	010	4	4
	011	8	8
	100	R	R
	101	R	R
	110	R	R
111	Full page	R	

Wrap type	0	Sequential
	1	Interleave

Latency mode	Bits6-4	CAS latency
	000	R
	001	1
	010	2
	011	3
	100	R
	101	R
	110	R
111	R	

Remark R: Reserved

Mode Register Write Timing



7.1 Burst Length and Sequence

[Burst of Two]

Starting Address (column address A0, binary)	Sequential Addressing Sequence (decimal)	Interleave Addressing Sequence (decimal)
0	0, 1	Not support
1	1, 0	Not support

[Burst of Four]

Starting Address (column address A1 - A0, binary)	Sequential Addressing Sequence (decimal)	Interleave Addressing Sequence (decimal)
00	0, 1, 2, 3	0, 1, 2, 3
01	1, 2, 3, 0	1, 0, 3, 2
10	2, 3, 0, 1	2, 3, 0, 1
11	3, 0, 1, 2	3, 2, 1, 0

[Burst of Eight]

Starting Address (column address A2 - A0, binary)	Sequential Addressing Sequence (decimal)	Interleave Addressing Sequence (decimal)
000	0, 1, 2, 3, 4, 5, 6, 7	0, 1, 2, 3, 4, 5, 6, 7
001	1, 2, 3, 4, 5, 6, 7, 0	1, 0, 3, 2, 5, 4, 7, 6
010	2, 3, 4, 5, 6, 7, 0, 1	2, 3, 0, 1, 6, 7, 4, 5
011	3, 4, 5, 6, 7, 0, 1, 2	3, 2, 1, 0, 7, 6, 5, 4
100	4, 5, 6, 7, 0, 1, 2, 3	4, 5, 6, 7, 0, 1, 2, 3
101	5, 6, 7, 0, 1, 2, 3, 4	5, 4, 7, 6, 1, 0, 3, 2
110	6, 7, 0, 1, 2, 3, 4, 5	6, 7, 4, 5, 2, 3, 0, 1
111	7, 0, 1, 2, 3, 4, 5, 6	7, 6, 5, 4, 3, 2, 1, 0

Full page burst is an extension of the above tables of Sequential Addressing, with the length being 256.

8. Programming the Special Register

The special register is programming by the Special register set command using address bits A9 through A0 and data bits DQ0 through DQ31. The color and mask register retain data until it is reprogrammed or the device losed power.

The special register has four fields.

- Reserved : A9 through A7
- Color register : A6
- Mask register : A5
- Reserved : A4 through A0

Following special register programming, no command can be asserted before at least 20 ns (trsc) have elapsed.

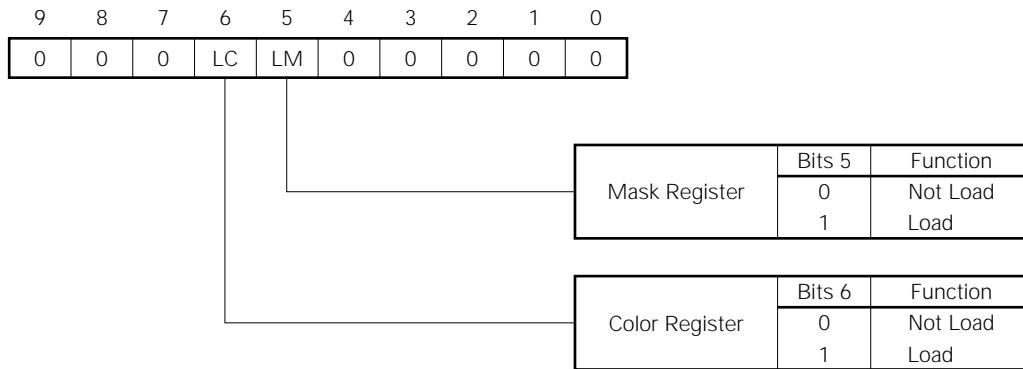
Color Register

Color register is used as write data in Block Write cycle. In Special Register set command, if A5 is "0" and A6 is "1", the color register is selected. And the data of DQ0 through DQ31 is stored to color register as color data (write data).

Mask Register

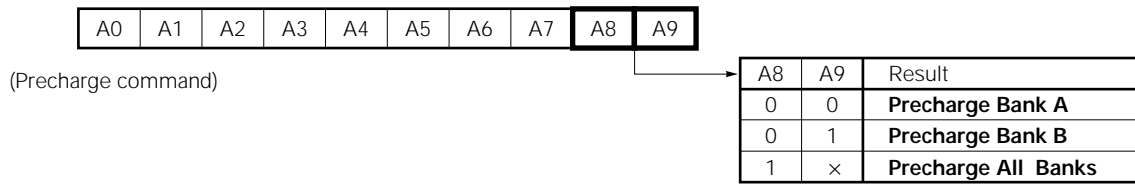
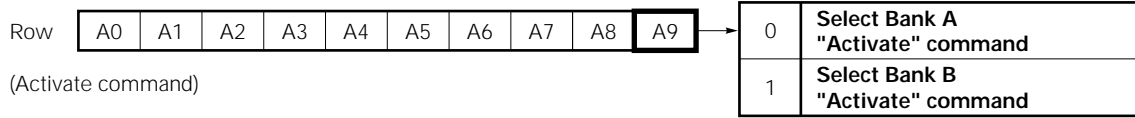
Mask register is used as write mask data in Write and Block Write cycle. In Special Register set command, if A5 is "1" and A6 is "0", the mask register is selected. And the data of DQ0 through DQ31 is stored to mask register as write mask data.

Special Register

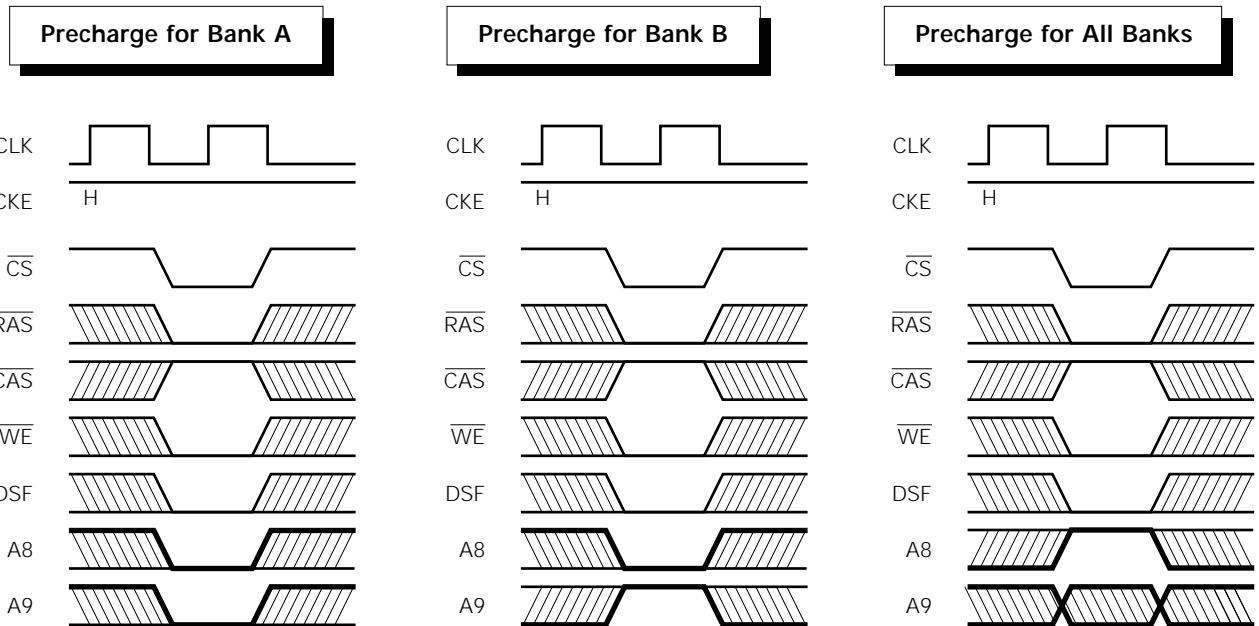
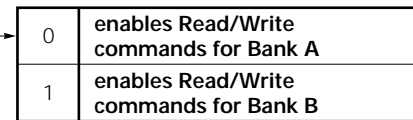
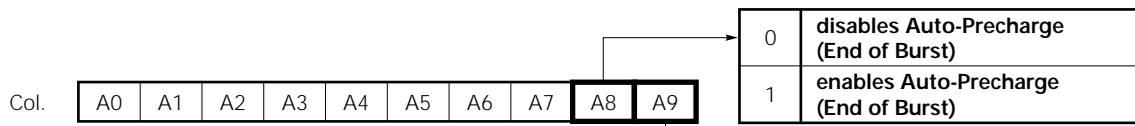


Remark If LC and LM are both high (1), data of Mask and Color register will be unknown.

9. Address Bits of Bank-Select and Precharge



x : Don't care



10. Precharge

The precharge command can be asserted anytime after $t_{RAS(MIN.)}$ is satisfied.

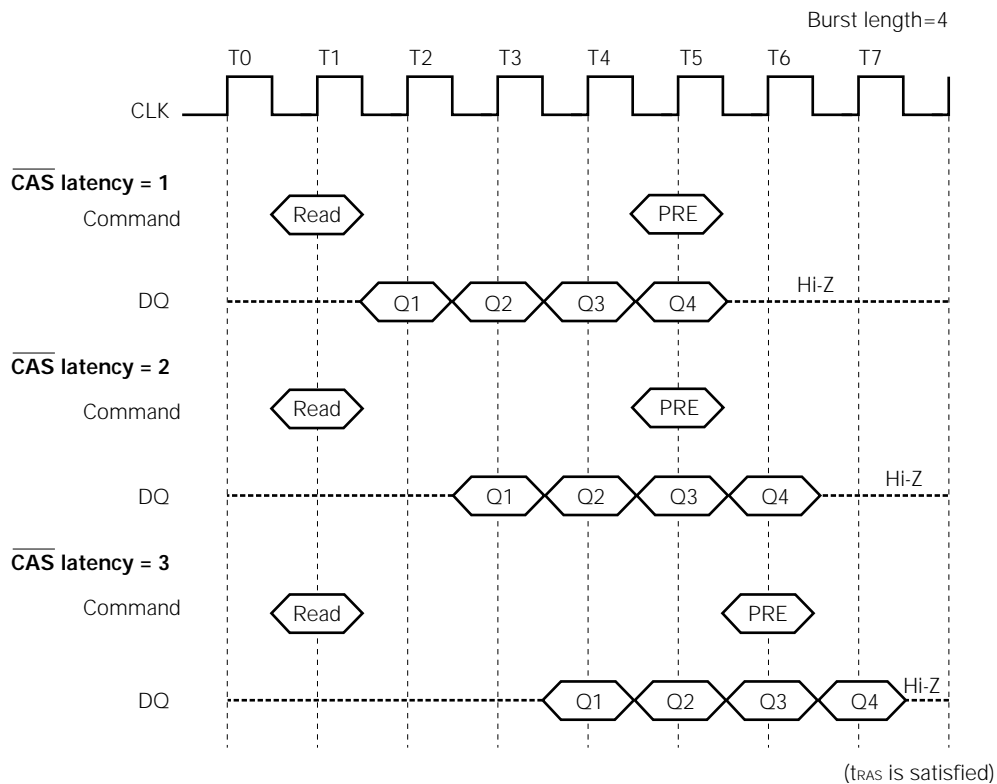
Soon after the precharge command is asserted, precharge operation performed and the synchronous GRAM enters the idle state after t_{RP} is satisfied. The parameter t_{RP} is the time required to perform the precharge.

The earliest timing in a read cycle that a precharge command can be asserted without losing any data in the burst is as follows.

It is depending on the \overline{CAS} latency.

\overline{CAS} latency = 1 : At the same clock as the last read data.

\overline{CAS} latency = 2 or 3 : One clock earlier than the last read data.



In order to write all data to the memory cell correctly, the asynchronous parameter “ t_{DPL} ” must be satisfied. The $t_{DPL(MIN.)}$ specification defines the earliest time that a precharge command can be asserted. Minimum number of clocks are calculated by dividing $t_{DPL(MIN.)}$ with clock cycle time.

In summary, the precharge command can be asserted relative to reference clock that indicates the last data word is valid. In the following table, minus means clocks before the reference; plus means time after the reference.

\overline{CAS} latency	Read	Write
1	0	+ $t_{DPL(MIN.)}$
2	-1	+ $t_{DPL(MIN.)}$
3	-1	+ $t_{DPL(MIN.)}$

11. Auto Precharge

During a read or write/block write command cycle, A8 controls whether auto precharge is selected. A8 high in the read or write/block write command (Read with Auto precharge command or Write with Auto precharge command/Block Write with Auto precharge command), auto precharge is selected and begins after the burst access automatically.

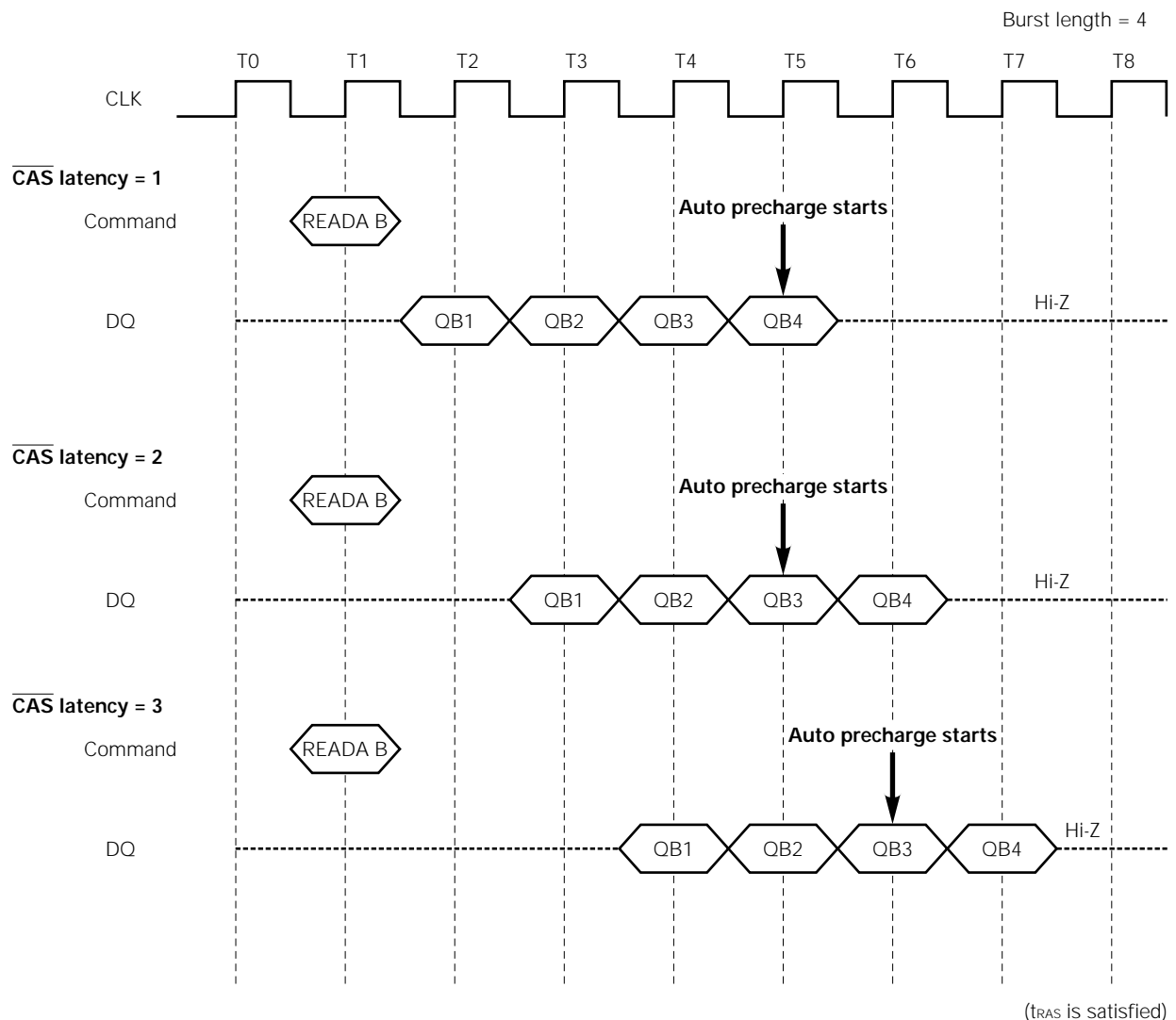
When the t_{RAS} is not satisfied, the precharge does not start at above timing. And the precharge will start when the t_{RAS} is satisfied.

The clock that begins the auto precharge cycle is depend on both the \overline{CAS} latency programmed into the mode register and whether READ or WRITE/BLOCK WRITE cycle.

11.1 Read with Auto Precharge

When using auto precharge in READ cycle, knowing when the precharge starts is important because the next activate command to the bank being precharged cannot be executed until the precharge cycle ends. Once auto precharge has started, an activate command to the bank can be asserted after t_{RP} has been satisfied.

During READ cycle, the auto precharge begins after t_{RAS} and begins on the clock that indicates the last data word output during the burst is valid (\overline{CAS} latency of 1) or one clock earlier (\overline{CAS} latency of 2 or 3).

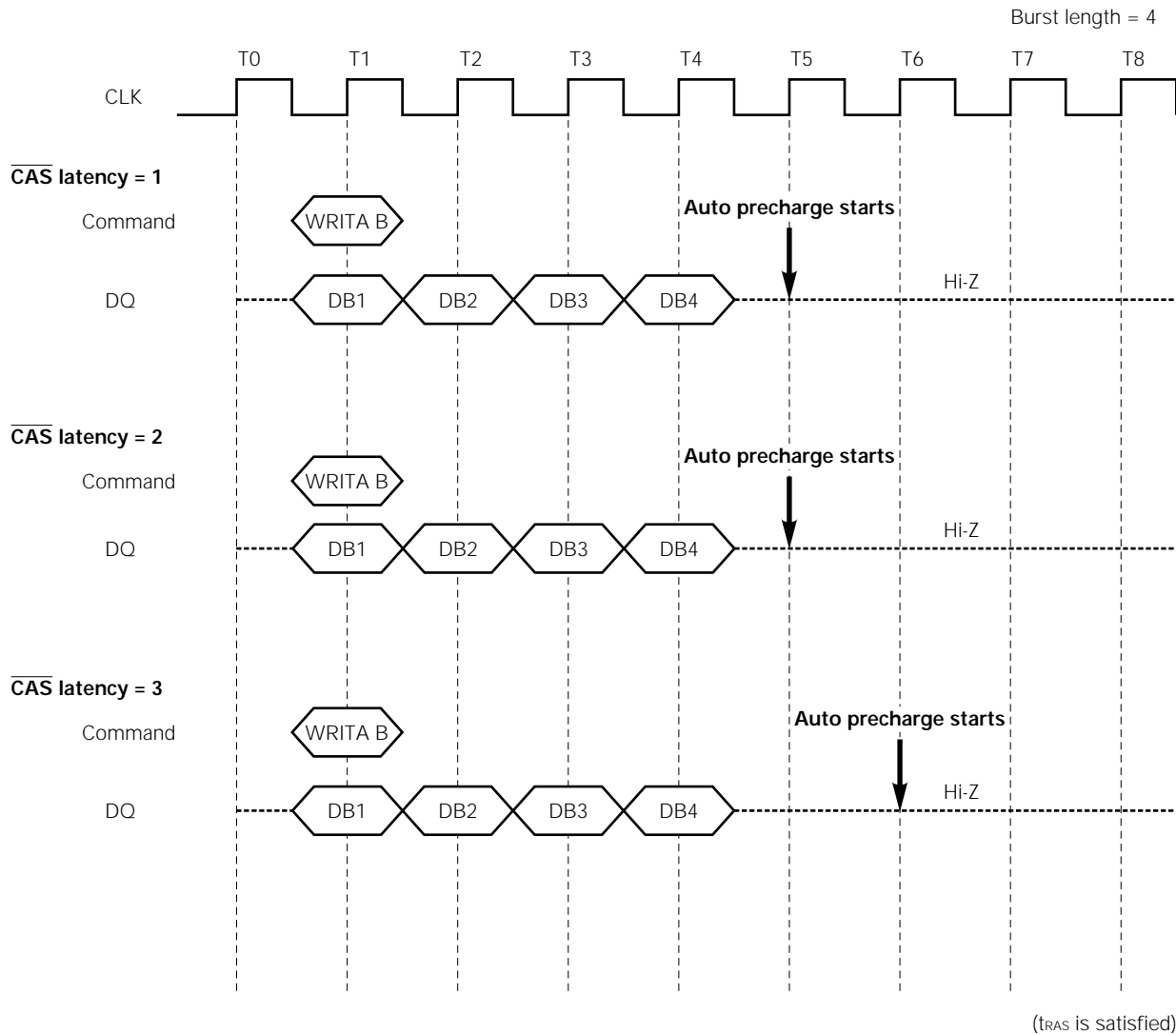


Remark READA means Read with Auto precharge

11.2 Write with Auto Precharge

In write cycle, the t_{DAL} must be satisfied to assert the all commands to the bank being precharged. And it is not necessary to know when the precharge starts. In block write cycle, the t_{BAL} must be satisfied to assert the all commands to the bank being precharged. And it is not necessary to know the precharge starts.

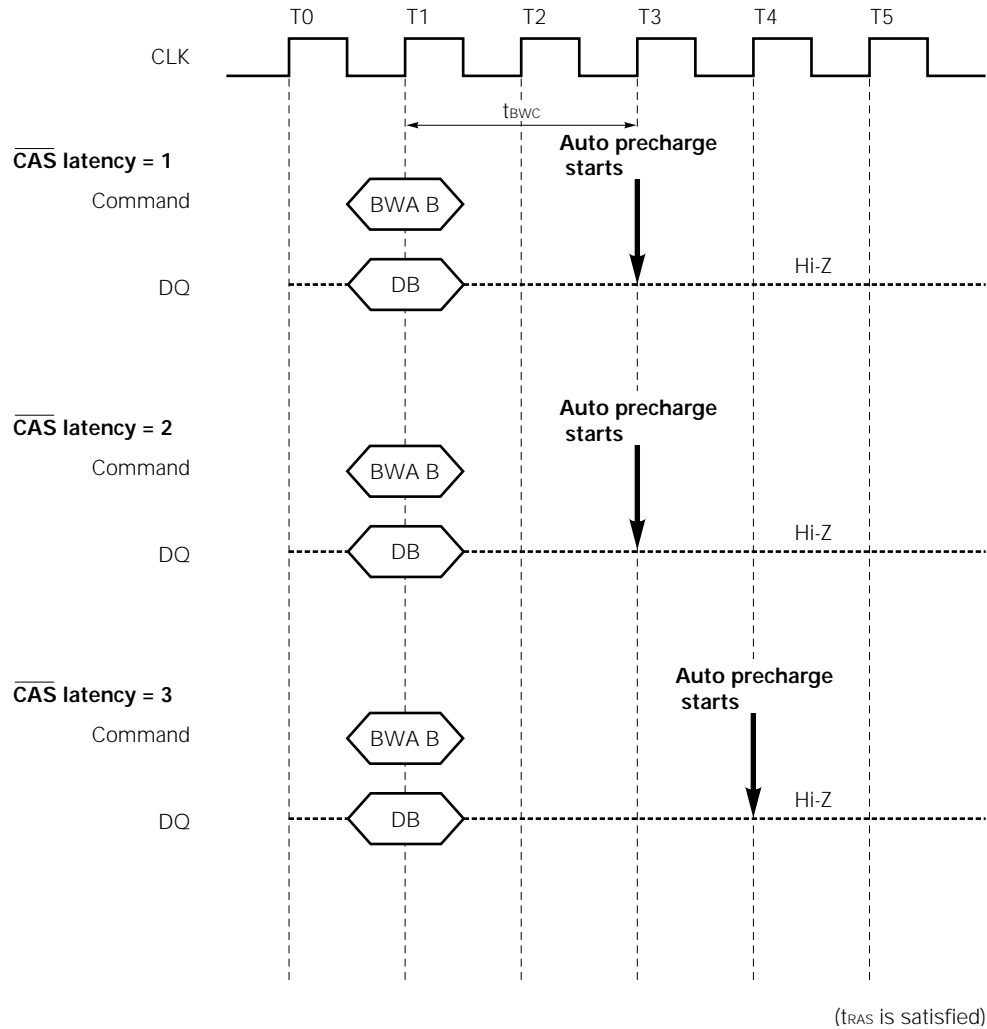
During WRITE cycle, the auto precharge begins after t_{RAS} and begins one clock after the last data word input to the device (\overline{CAS} latency of 1 or 2) or two clocks after (\overline{CAS} latency of 3).



Remark WRITA means Write with Auto precharge

11.3 Block Write with Auto Precharge

During BLOCK WRITE cycle, the auto precharge begins one clock after the block write command to the device ($\overline{\text{CAS}}$ latency of 1) or two clocks after ($\overline{\text{CAS}}$ latency of 2) or three clocks after ($\overline{\text{CAS}}$ latency of 3).



In summary, the auto precharge cycle begins relative to a reference clock that indicates the last data word is valid.

In the table below, minus means clocks before the reference; plus means clocks after the reference.

$\overline{\text{CAS}}$ latency	Read	Write	Block Write
1	0	+1	+2
2	-1	+1	+2
3	-1	+2	+3

12. Write/Block Write with Write Per Bit

To use WPB operation

- (1) Execute Special register set command and set WPB data (32 bits) to mask register.
- (2) Execute Bank Activate with WPB enable command (ACTWPB) after t_{RSC} (20 ns) period from Special register set command (SRS).
- (3) Execute Write/Block write command after t_{RCD} period from ACTWPB.

In case SRS command is executed in activate state to set new WPB data, it is necessary to take t_{RSC} (20 ns) interval between SRS and Write/Block write command.

Remark Mask data = Mask register's data (WPB) + DQMi
DQMi is prior to Mask register's data (WPB)

13. Block Write

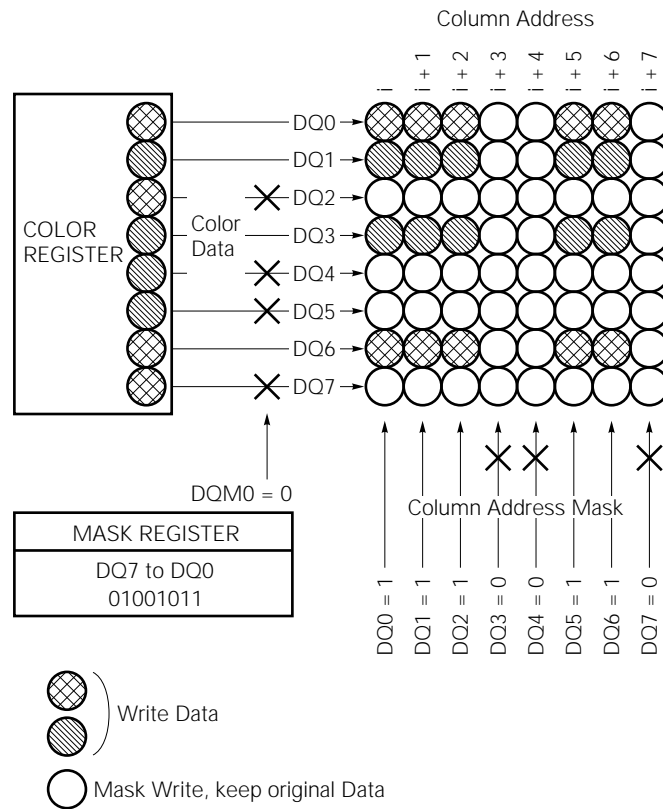
In block write cycle, write data from color register can be written in 8 columns at one write cycle. It is also possible to execute Block write cycle with write per bit. Column Mask by DQi is available.

To use Block write operation

- (1) Execute Special register set command and set color data (32 bits) to color register.
- (2) Execute Bank Activate (ACT) or Bank Activate with WPB enable command (ACTWPB) after t_{RSC} (20 ns) period from SRS.
- (3) Execute Block write command after t_{RCD} period from ACT or ACTWPB.

In case new Write/Block write is executed or, it is necessary to take t_{BWC} interval from Block Write command to new Write/Block write command.

Block Write Function



- Remarks**
1. *i* is times of 8 numeric.
 2. This diagram shows only for DQ0 - 7. The other DQ is similar as this.

Column Mask

- DQ0 - 7 : Column Mask for DQ0 - 7
- DQ8 - 15 : Column Mask for DQ8 - 15
- DQ16 - 23: Column Mask for DQ16 - 23
- DQ24 - 31: Column Mask for DQ24 - 31

Write per Bit

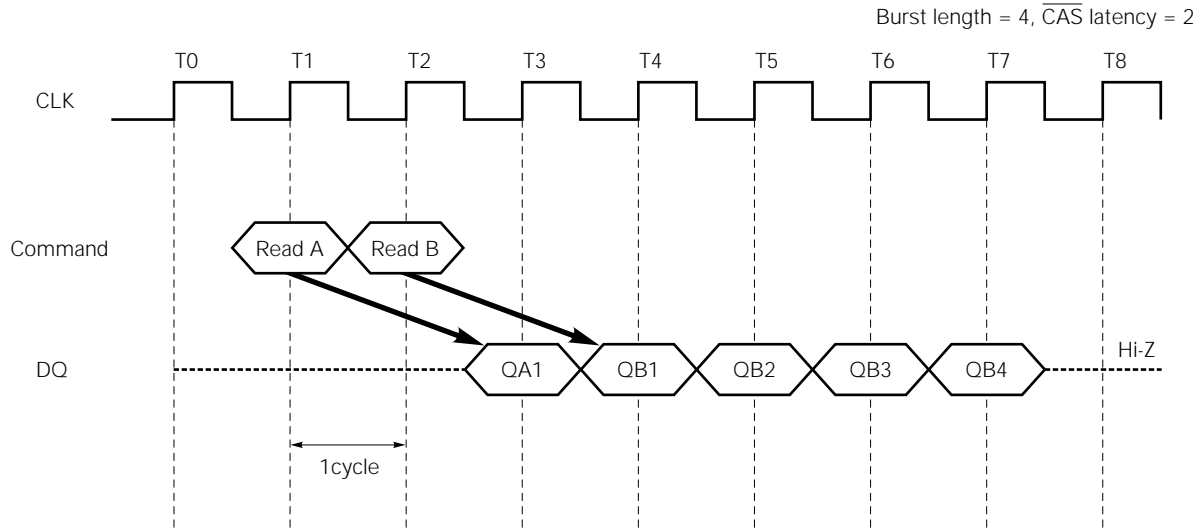
Mask data = Mask Register + DQM_i
 DQM_i is prior to data of Mask Register.

14. Read/Write Command Interval

14.1 Read to Read Command Interval

During READ cycle, when new Read command is asserted, it will be effective after $\overline{\text{CAS}}$ latency, even if the previous READ operation does not completed. READ will be interrupted by another READ.

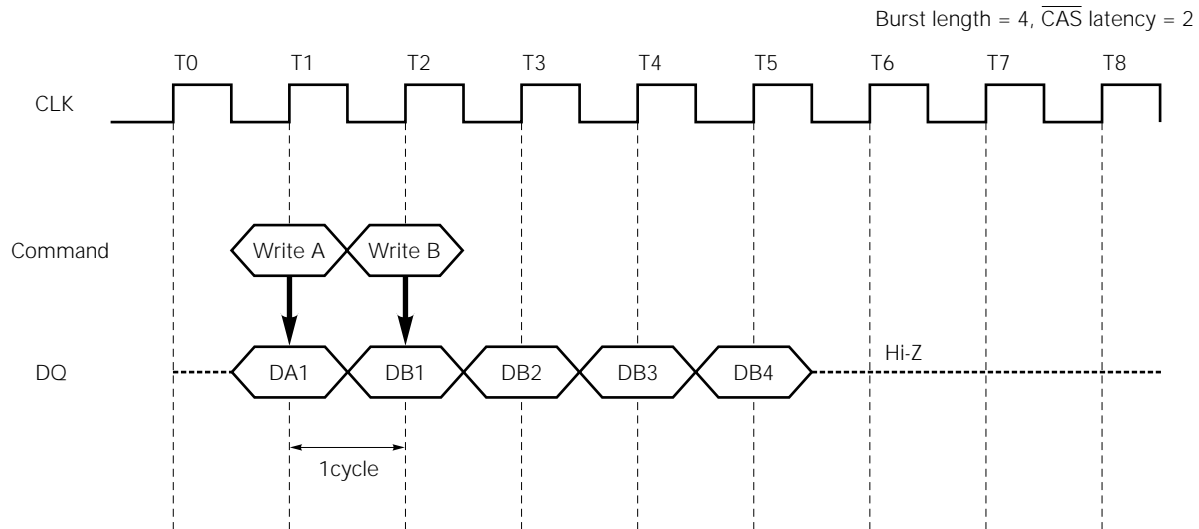
The interval between the commands is minimum 1 cycle. Each Read command can be asserted in every clock without any restriction.



14.2 Write to Write Command Interval

During WRITE cycle, when new Write command is asserted, the previous burst will terminate and the new burst will begin with a new Write command. WRITE will be interrupted by another WRITE.

The interval between the commands is minimum 1 cycle. Each Write command can be asserted in every clock without any restriction.

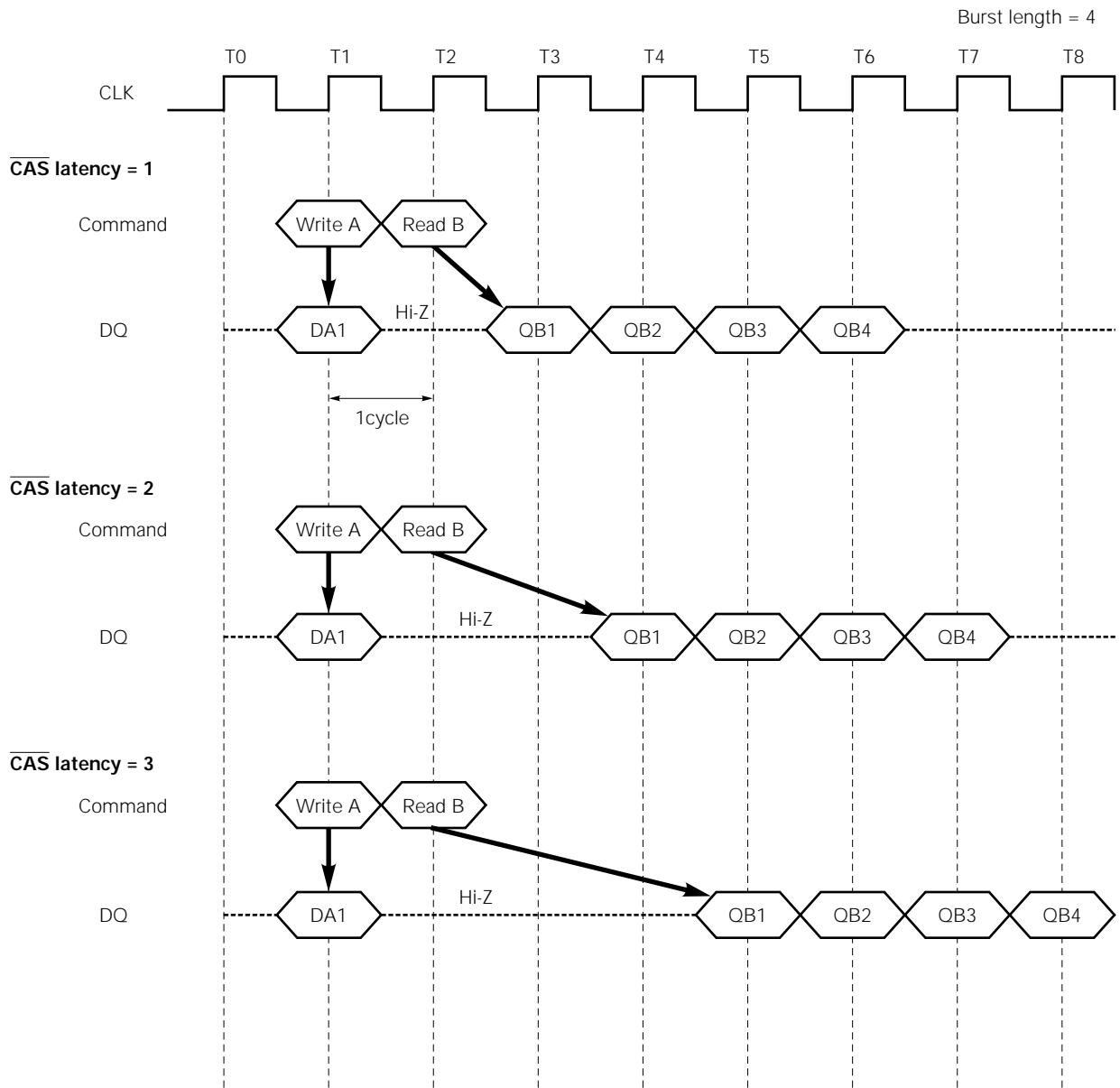


14.3 Write to Read Command Interval

Write command and Read command interval is also 1 cycle.

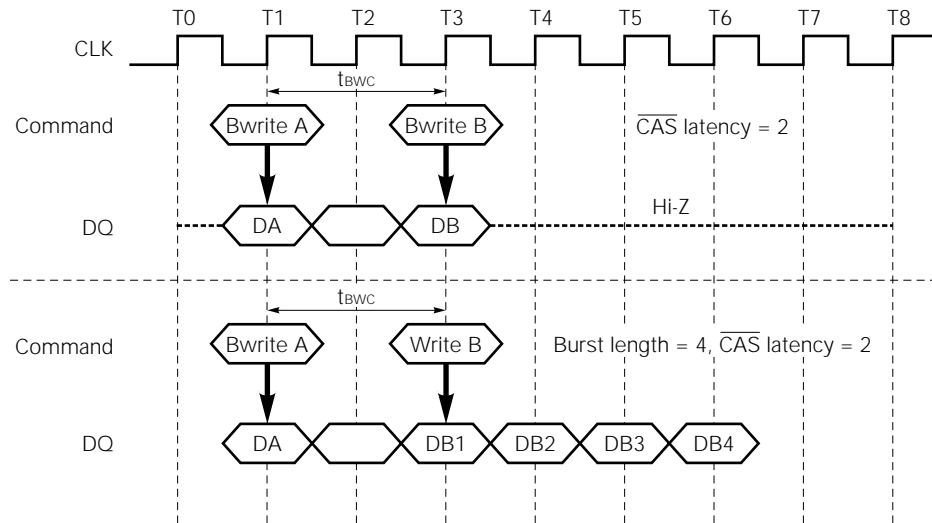
Only the write data before Read command will be written.

The data bus must be Hi-Z at least one cycle prior to the first Dout.



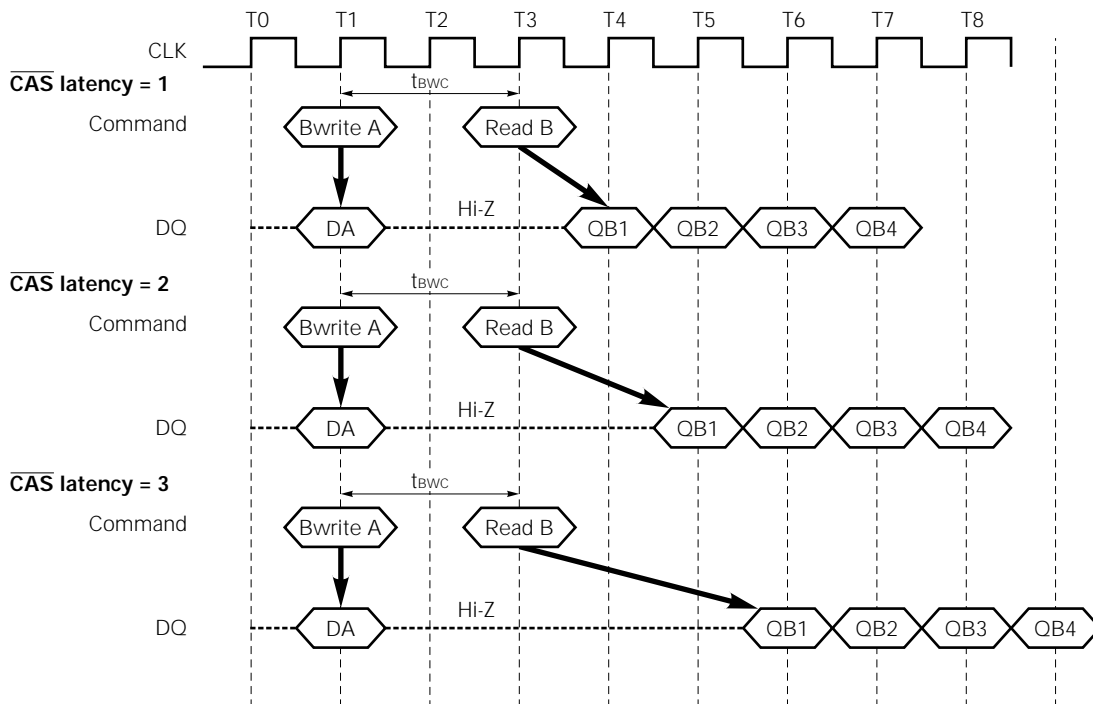
14.4 Block Write to Write or Write/Block Write Command Interval

The interval between BLOCK WRITE and new BLOCK WRITE or WRITE is t_{bwc} or minimum 1 cycle. If t_{clk} is less than t_{bwc} , NOP command should be issued for the cycle between BLOCK WRITE and the following WRITE or new BLOCK WRITE.



14.5 Block Write to Read Command Interval

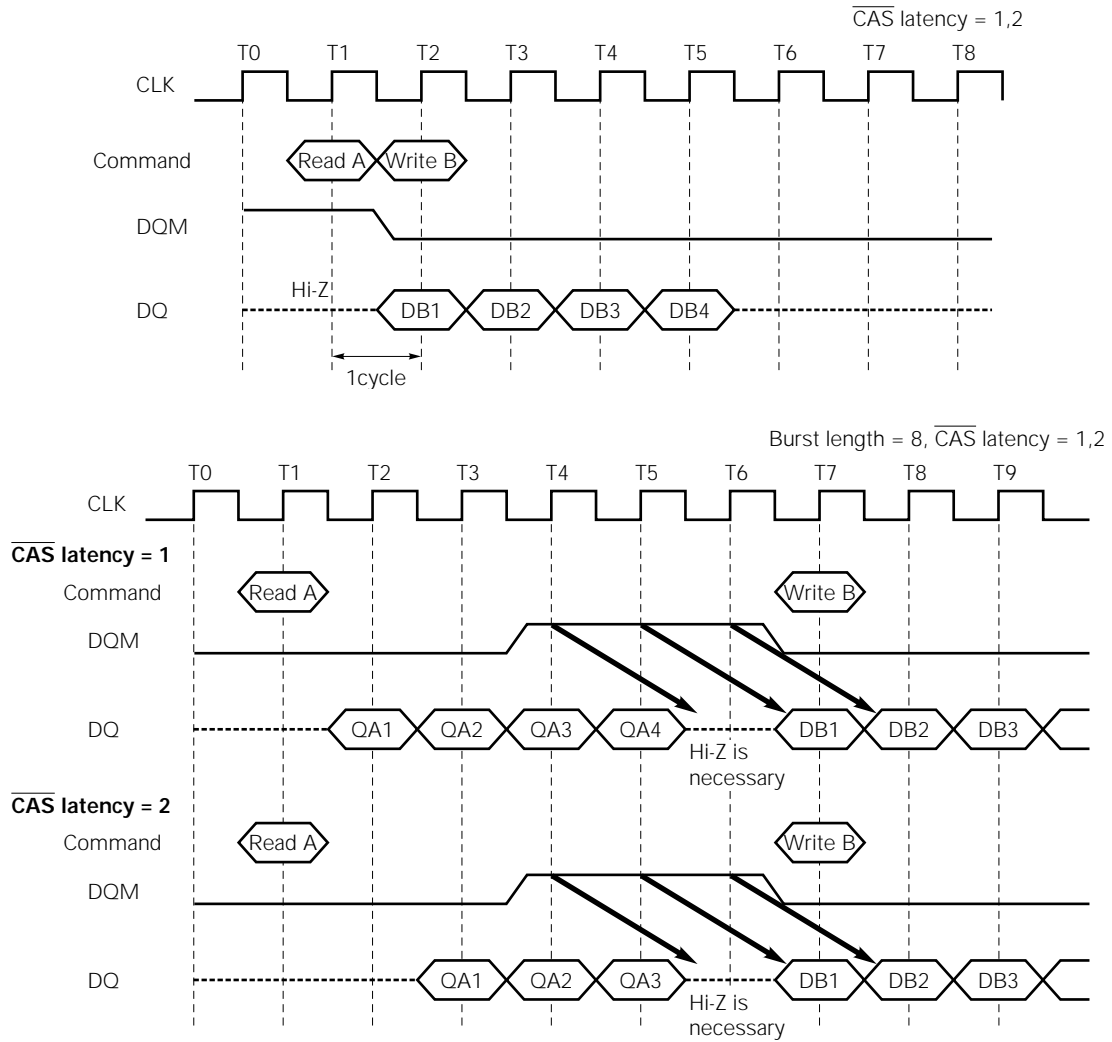
BLOCK WRITE command and READ command is also t_{bwc} or minimum 1 cycle. The data bus must be Hi-Z at least one cycle prior to the first Dout.



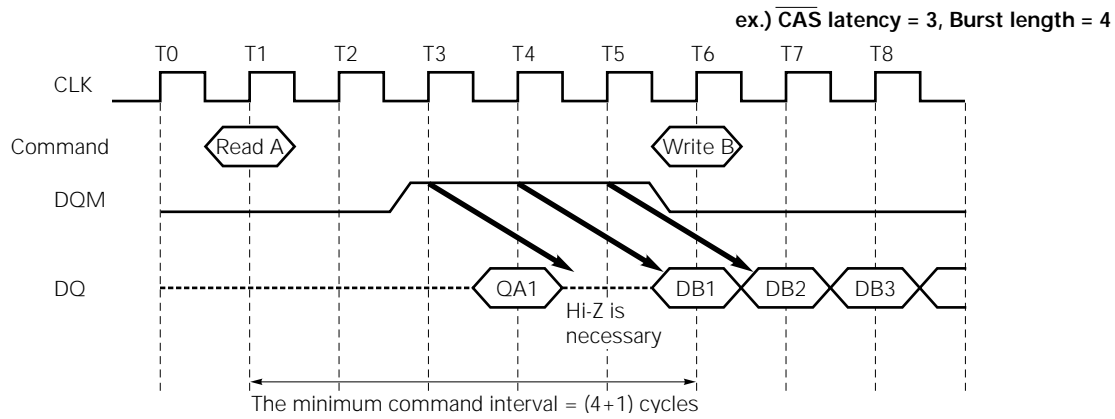
14.6 Read to Write/Block Write Command Interval

During READ cycle, Read can be interrupted by WRITE. But full page burst read can not be interrupted by WRITE. Full page burst read can be interrupted by Burst Stop command (BST) or Precharge command (Burst termination).

For $\overline{\text{CAS}}$ latency of 1 or 2, the READ and WRITE command interval is minimum 1 cycle. The data bus must be Hi-Z using DQM before WRITE to avoid data conflict. And DQM must be kept being High from at least 3 clocks to 1 clock before the Write command.



For $\overline{\text{CAS}}$ latency of 3, the READ and WRITE command interval is [Burst length + 1] cycles. The data bus must be Hi-Z using DQM before WRITE to avoid data conflict. And DQM must be kept being High from at least 3 clocks to 1 clock before the WRITE command.



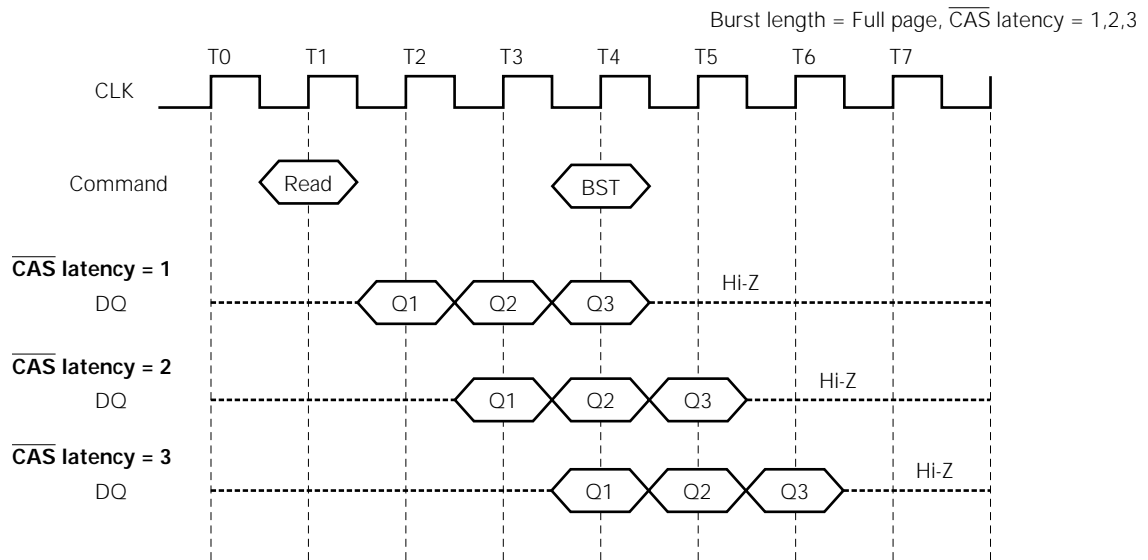
15. Burst Termination

Burst termination is to terminate a burst operation other than using a read or write command.

15.1 Burst Stop Command in Full Page

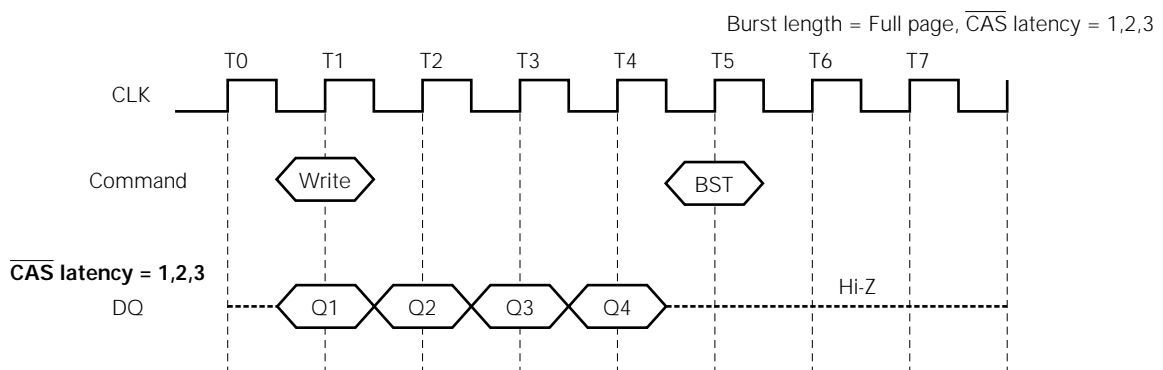
Burst Stop command is operated only in case full page burst mode. During the other burst mode, Burst Stop command is NOP.

During full page burst read cycle, when the burst stop command is asserted, the burst read data are terminated and the data bus goes to high-impedance after the $\overline{\text{CAS}}$ latency from the burst stop command.



Remark BST: Burst stop command

During full page burst write cycle, when the burst stop command is asserted, the burst read data are terminated and data bus goes to high-impedance at the same clock with the burst stop command.



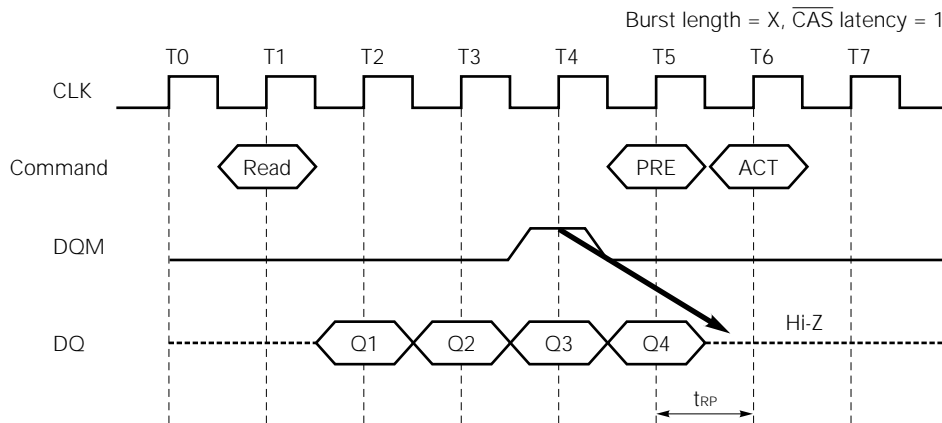
Remark BST: Burst stop command

15.2 Precharge Termination

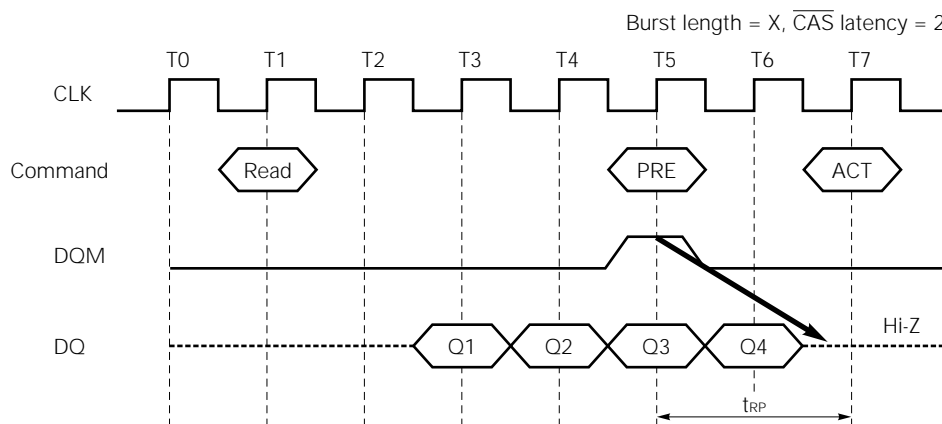
15.2.1 Precharge Termination in READ Cycle

During READ cycle, the burst read operation is terminated by a precharge command. When the precharge command is asserted, the burst read operation is terminated and precharge starts. The same bank can be activated again after t_{RP} from the precharge command. The DQM must be high to mask the invalid data.

When \overline{CAS} latency is 1, the read data will remain valid until the precharge command is asserted. Invalid data may appear one clock after valid data out. The DQM may be high to mask the invalid data.

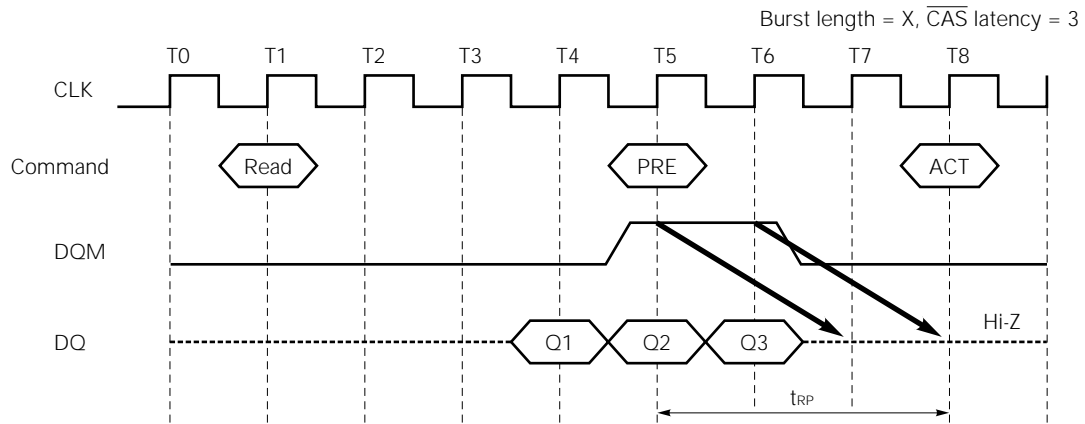


When \overline{CAS} latency is 2, the read data will remain valid until one clock after the precharge command. Invalid data may appear one clock after valid data out. The DQM may be high to mask the invalid data.



When $\overline{\text{CAS}}$ latency is 3, the read data will remain valid until one clock after the precharge command. Invalid data may appear one and two clocks after valid data out.

The DQM may be high to mask the invalid data.



15.2.2 Precharge Termination in WRITE Cycle

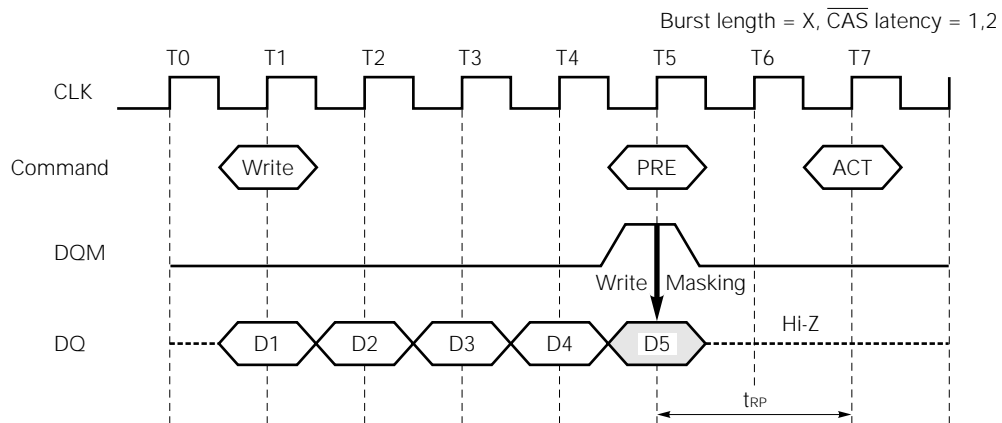
During WRITE cycle, the burst write operation is terminated by a precharge command.

When the precharge command is asserted, the burst write operation is terminated and precharge starts.

The same bank can be activated again after t_{RP} from the precharge command.

The DQM must be high to mask invalid data in.

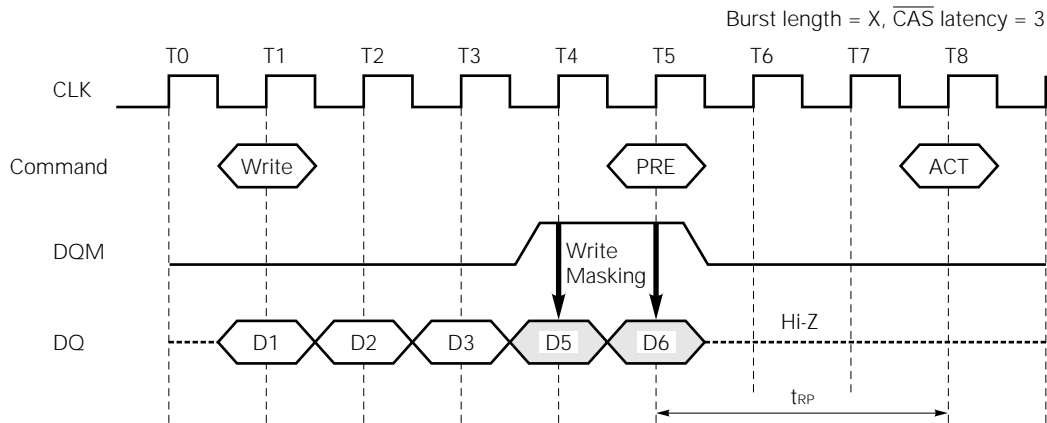
When $\overline{\text{CAS}}$ latency is 1 or 2, the write data written prior to the precharge command will be correctly stored. However, invalid data may be written at the same clock as the precharge command. To prevent this from happening, DQM must be high at the same clock as the precharge command. This will mask the invalid data.



When $\overline{\text{CAS}}$ latency is 3, the write data written more than one clock prior to the precharge command will be correctly stored.

However, invalid data may be written at one clock before and the same clock as the precharge command.

To prevent this from happening, DQM must be high from one clock prior to the precharge command until the precharge command. This will mask the invalid data.



16. Electrical Specifications (Preliminary)

- All voltage are referenced to V_{SS} (GND).
- After power up, wait more than 100 μs and then, execute **Power on sequence and Auto Refresh** before proper device operation is achieved.

Absolute Maximum Ratings

Parameter	Symbol	Condition	Rating	Unit
Voltage on power supply pin relative to GND	V _T		-1.0 to +4.6	V
Voltage on input pin relative to GND	V _{CC} , V _{CCQ}		-1.0 to +4.6	V
Short circuit output current	I _o		50	mA
Power dissipation	P _D		1	W
Operating ambient temperature	T _A		0 to 70	°C
Storage temperature	T _{stg}		-55 to +125	°C

Caution Exposing the device to stress above those listed in **Absolute Maximum Ratings** could cause permanent damage. The device is not meant to be operated under conditions outside the limits described in the operational section of this specification. Exposure to **Absolute Maximum Rating** conditions for extended periods may affect device reliability.

Recommended Operating Conditions

Parameter	Symbol	Condition	MIN.	TYP.	MAX.	Unit
Supply voltage	V _{CC}		3.0	3.3	3.6	V
High level input voltage	V _{IH}		2.0		V _{CC} + 0.3	V
Low level input voltage	V _{IL}		-0.3		+0.8	V
Operating ambient temperature	T _A		0		70	°C

Capacitance (T_A=25°C, f=1MHz)

Parameter	Symbol	Condition	MIN.	TYP.	MAX.	Unit
Input capacitance	C _{I1}	A0 to A9	2		4	pF
	C _{I2}	CLK, CKE, \overline{CS} , RAS, \overline{CAS} , \overline{WE} , DSF, DQM	2		4	pF
Data input/output capacitance	C _{I/O}	DQ0 to DQ31	2		5	pF

DC Characteristics 1 (Recommended Operating Conditions unless otherwise noted)

Parameter	Symbol	Test condition	Grade	MAX.	Unit	Notes	
Operating current	I _{CC1}	Burst length=1 t _{RAS} ≥ t _{RAS (MIN.)} t _{RP} ≥ t _{RP (MIN.)} I _O =0mA	-10	105	mA	1	
			-12	90			
			-15	85			
Precharge standby current in Power down mode	I _{CC2P}	CKE ≤ V _{IL (MAX.)} t _{CK} =15ns		7	mA		
	I _{CC2PS}	CKE ≤ V _{IL (MAX.)} t _{CK} =∞		6			
Precharge standby current in Non power down mode	I _{CC2N}	CKE ≥ V _{IH (MIN.)} t _{CK} =15ns CS ≥ V _{IH (MIN.)} Input signals are changed one time during 30ns.		36	mA		
	I _{CC2NS}	CKE ≥ V _{IH (MIN.)} t _{CK} =∞ Input signals are stable.		22			
Active standby current in Power down mode	I _{CC3P}	CKE ≤ V _{IL (MAX.)} t _{CK} =15ns		7	mA		
	I _{CC3PS}	CKE ≤ V _{IL (MAX.)} t _{CK} =∞		6			
Active standby current in Non power down mode	I _{CC3N}	CKE ≥ V _{IH (MIN.)} t _{CK} =15ns CS ≥ V _{IH (MIN.)} Input signals are changed one time during 30 ns.		36	mA		
	I _{CC3NS}	CKE ≥ V _{IH (MIN.)} t _{CK} =∞ Input signals are stable.		22			
Operating current (Burst mode)	I _{CC4}	t _{CK} ≥ t _{CK (MIN.)} I _O =0mA	CS latency = 1	-10	210	mA	2
				-12	180		
				-15	165		
			CS latency = 2	-10	280		
				-12	235		
				-15	220		
			CS latency = 3	-10	365		
				-12	310		
				-15	285		
Refresh current	I _{CC5}	t _{RC} ≥ t _{RC (MIN.)}	-10	85	mA	3	
			-12	80			
			-15	75			
Self refresh Current	I _{CC6}	CKE ≤ 0.2V		6	mA		
Operating Current (Block Write Mode)	I _{CC7}	t _{CK} ≥ t _{CK (MIN.)} , I _O = 0 mA, CS cycle = 20 ns		250	mA		

- Notes**
- I_{CC1} depends on output loading and cycle rates. Specified values are obtained with the output open. In addition to this, I_{CC1} is measured on condition that addresses are changed only one time during t_{CK(MIN.)}.
 - I_{CC4} depends on output loading and cycle rates. Specified values are obtained with the output open. In addition to this, I_{CC4} is measured on condition that addresses are changed only one time during t_{CK(MIN.)}.
 - I_{CC5} is measured on condition that addresses are changed only one time during t_{CK(MIN.)}.

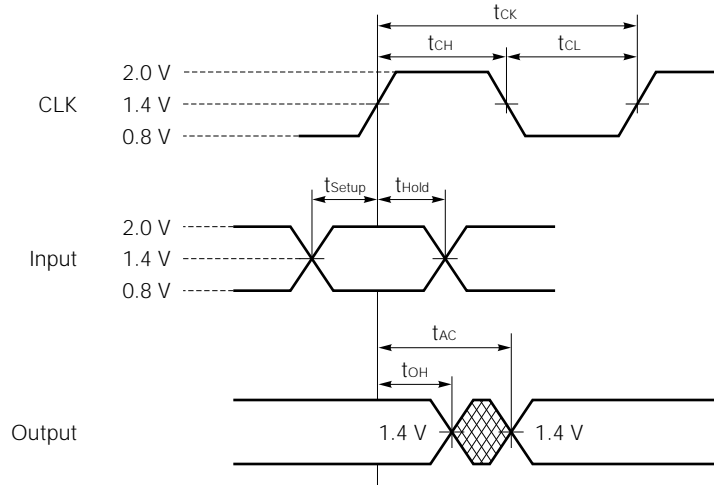
DC Characteristics 2 (Recommended Operating Conditions unless otherwise noted)

Parameter	Symbol	Test condition	MIN.	TYP.	MAX.	Unit
Input leakage current	$I_{I(L)}$	$V_I=0$ to 3.6V, all other pins not under test =0V	-1.0		+1.0	μ A
Output leakage current	$I_{O(L)}$	D_{OUT} is disabled, $V_O=0$ to 3.6V	-1.0		+1.0	μ A
High level output voltage	V_{OH}	$I_O=-2$ mA	2.4			V
Low level output voltage	V_{OL}	$I_O=+2$ mA			0.4	V

AC Characteristics (Recommended Operating Conditions unless otherwise noted)

Test Conditions

- AC measurements assume $t_T=1ns$.
- Reference level for measuring timing of input signals is 1.4V. Transition times are measured between V_{IH} and V_{IL} .
- If t_T is longer than 1 ns, reference level for measuring timing of input signals is $V_{IH(MIN.)}$ and $V_{IL(MAX.)}$.
- An access time is measured at 1.4V.



Synchronous Characteristics

(1/2)

Parameter	Symbol	-10		-12		-15		Unit	Note
		MIN.	MAX.	MIN.	MAX.	MIN.	MAX.		
Clock cycle time	\overline{CAS} latency=3	t_{CK3}	10 (100MHz)	12 (83MHz)	15 (66MHz)	19.5 (50MHz)	ns		
	\overline{CAS} latency=2	t_{CK2}	15 (66MHz)	18 (55MHz)	19.5 (50MHz)	ns			
	\overline{CAS} latency=1	t_{CK1}	30 (33MHz)	36 (28MHz)	39 (25MHz)	ns			
Access time from CLK	\overline{CAS} latency=3	t_{AC3}	9	11	14	ns	1		
	\overline{CAS} latency=2	t_{AC2}	12	15	16.5	ns	1		
	\overline{CAS} latency=1	t_{AC1}	27	33	36	ns	1		
CLK high level width	t_{CH}	3.5	4	5	ns				
CLK low level width	t_{CL}	3.5	4	5	ns				
Data-out hold time	t_{OH}	4	4	4	ns				
Data-out low-impedance time	t_{LZ}	0	0	0	ns				
Data-out high-impedance time	\overline{CAS} latency = 3	t_{HZ3}	4	8	4	10	ns		
	\overline{CAS} latency = 2	t_{HZ2}	4	11	4	11	ns		
	\overline{CAS} latency = 1	t_{HZ1}	4	27	4	27	ns		
Data-in setup time	t_{DS}	3	3.5	3.5	ns				
Data-in hold time	t_{DH}	1	1.5	1.5	ns				
Address setup time	t_{AS}	3	3.5	3.5	ns				
Address hold time	t_{AH}	1	1.5	1.5	ns				
CKE setup time	t_{CKS}	3	3.5	3.5	ns				
CKE hold time	t_{CKH}	1	1.5	1.5	ns				
CKE setup time (Power down exit)	t_{CKSP}	3	3.5	3.5	ns				

Note 1. Loading capacitance is 30 pF.

Synchronous Characteristics

(2/2)

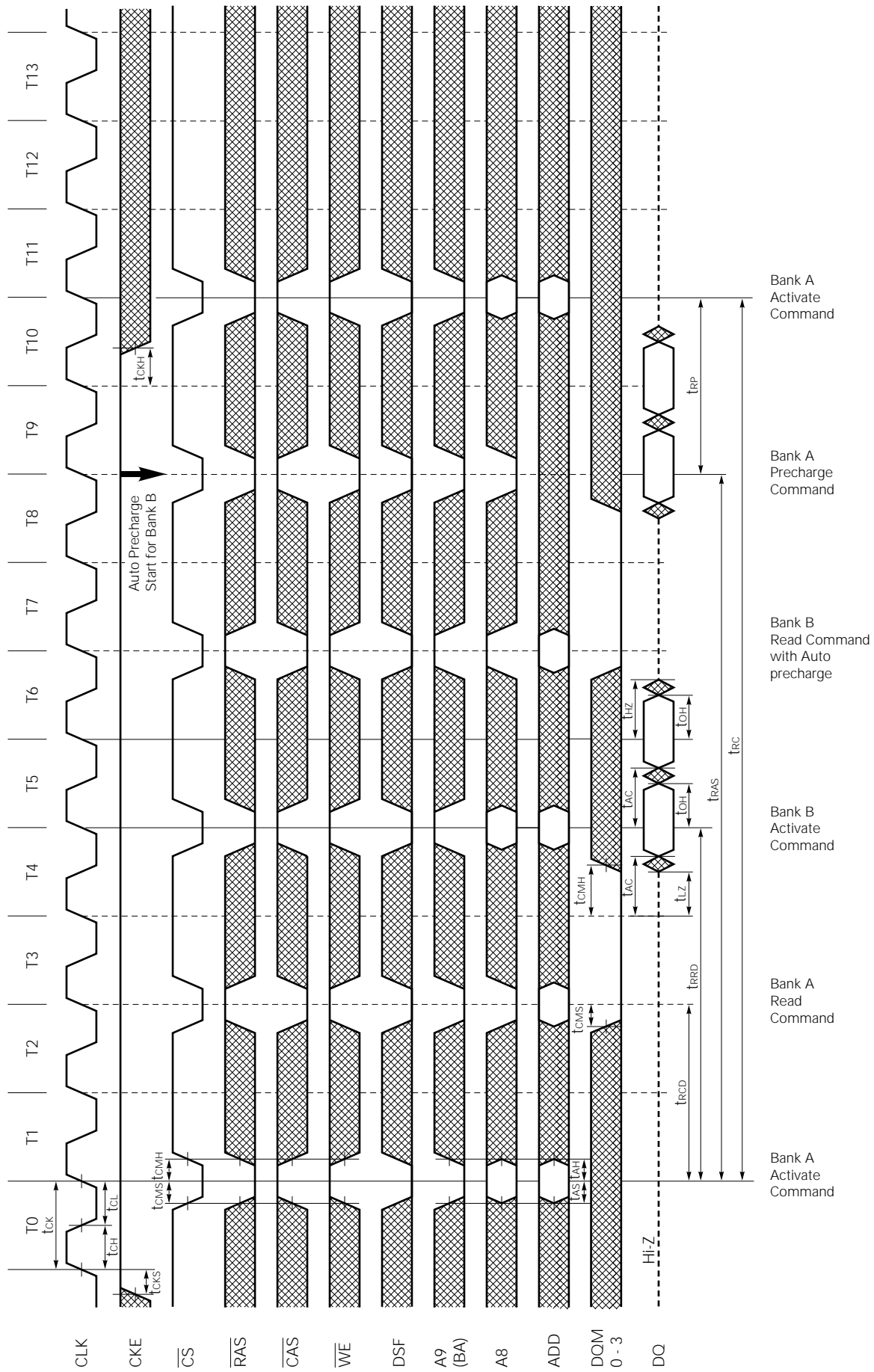
Parameter	Symbol	-10		-12		-15		Unit	Note
		MIN.	MAX.	MIN.	MAX.	MIN.	MAX.		
Command (\overline{CS} , \overline{RAS} , \overline{CAS} , \overline{WE} , DSF, DQM) setup time	t_{CMS}	3		3.5		3.5		ns	
Command (\overline{CS} , \overline{RAS} , \overline{CAS} , \overline{WE} , DSF, DQM) hold time	t_{CMH}	1		1.5		1.5		ns	

Asynchronous Characteristics

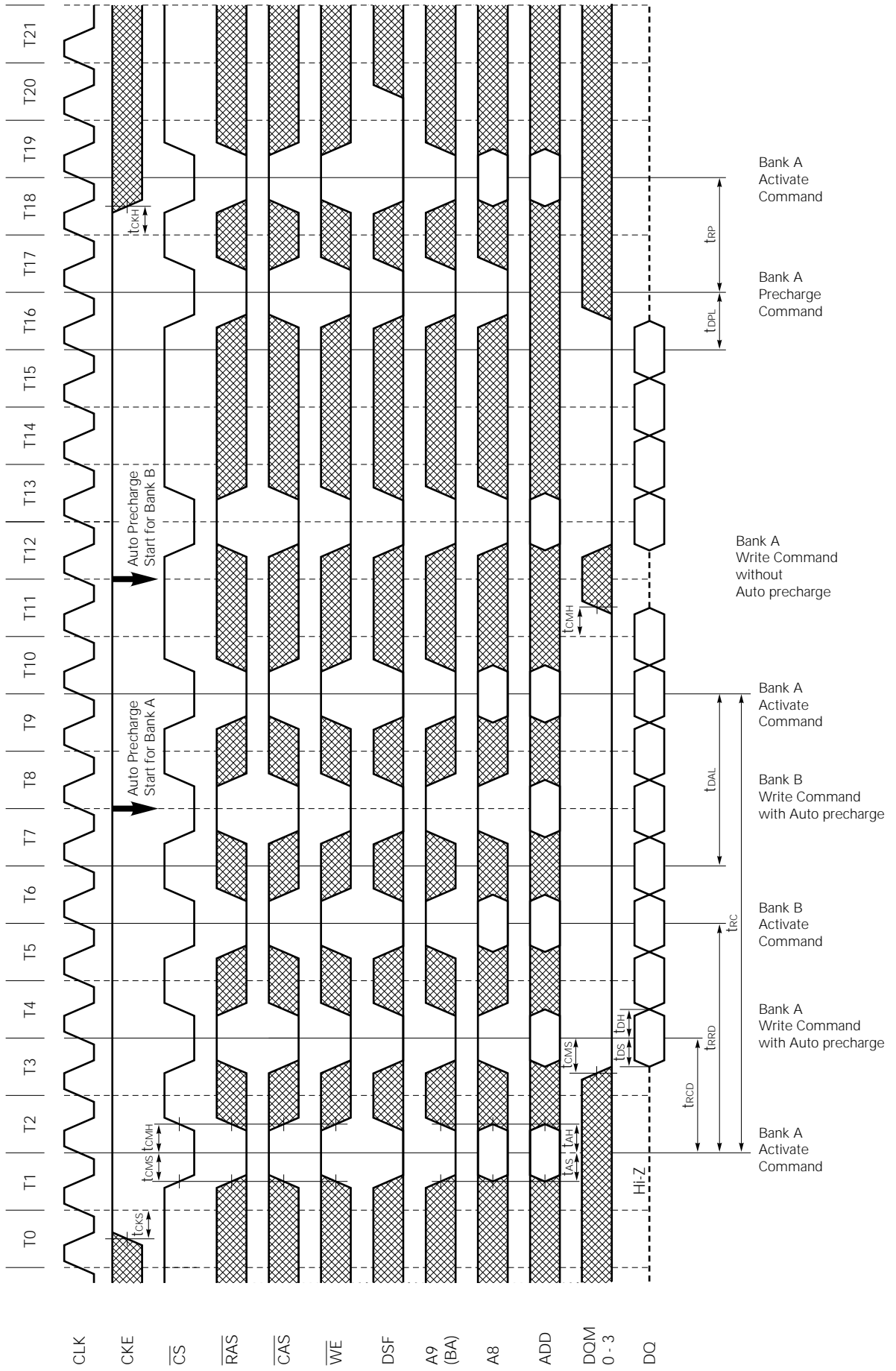
Parameter	Symbol	-10		-12		-15		Unit	Note
		MIN.	MAX.	MIN.	MAX.	MIN.	MAX.		
REF to REF/ACT Command period	t_{RC}	100		120		130		ns	
ACT to PRE Command period	t_{RAS}	70	120,000	84	120,000	90	120,000	ns	
PRE to ACT Command period	t_{RP}	30		36		39		ns	
Delay time ACT to READ/WRITE Command	t_{RCD}	30		36		39		ns	
ACT(0) to ACT(1) Command period	t_{RRD}	30		36		39		ns	
Data-in to PRE Command period	\overline{CAS} latency=3	t_{DPL3}	1CLK+10		1CLK+12		1CLK+15	ns	
	\overline{CAS} latency=2	t_{DPL2}	15		18		19.5	ns	
	\overline{CAS} latency=1	t_{DPL1}	15		18		19.5	ns	
Data-in to ACT (REF) Command period (Auto precharge)	\overline{CAS} latency=3	t_{DAL3}	2CLK+30		2CLK+36		2CLK+45	ns	
	\overline{CAS} latency=2	t_{DAL2}	1CLK+30		1CLK+36		1CLK+39	ns	
	\overline{CAS} latency=1	t_{DAL1}	1CLK+30		1CLK+36		1CLK+39	ns	
Block write cycle time	t_{BWC}	20		24		30		ns	
Block write data-in to PRE Command period	\overline{CAS} latency=3	t_{BPL3}	1CLK+20		1CLK+24		1CLK+30	ns	
	\overline{CAS} latency=2	t_{BPL2}	30		36		39	ns	
	\overline{CAS} latency=1	t_{BPL1}	30		36		36	ns	
Block write data-in Active (REF) Command Period (Auto Precharge)	\overline{CAS} latency=3	t_{BAL3}	2CLK+40		2CLK+48		2CLK+60	ns	
	\overline{CAS} latency=2	t_{BAL2}	1CLK+40		1CLK+48		1CLK+52	ns	
	\overline{CAS} latency=1	t_{BAL1}	1CLK+40		1CLK+48		1CLK+52	ns	
Mode register set cycle time	t_{RSC}	20		20		20		ns	
Transition time	t_T	1	30	1	30	1	30	ns	
Refresh time	t_{REF}		16		16		16	ms	

16.1 AC Parameters for Read/Write Cycles

AC Parameters for Read Timing (Burst length = 2, CAS latency = 2)



AC Parameters for Write Timing (Burst length = 4, CAS latency = 2)

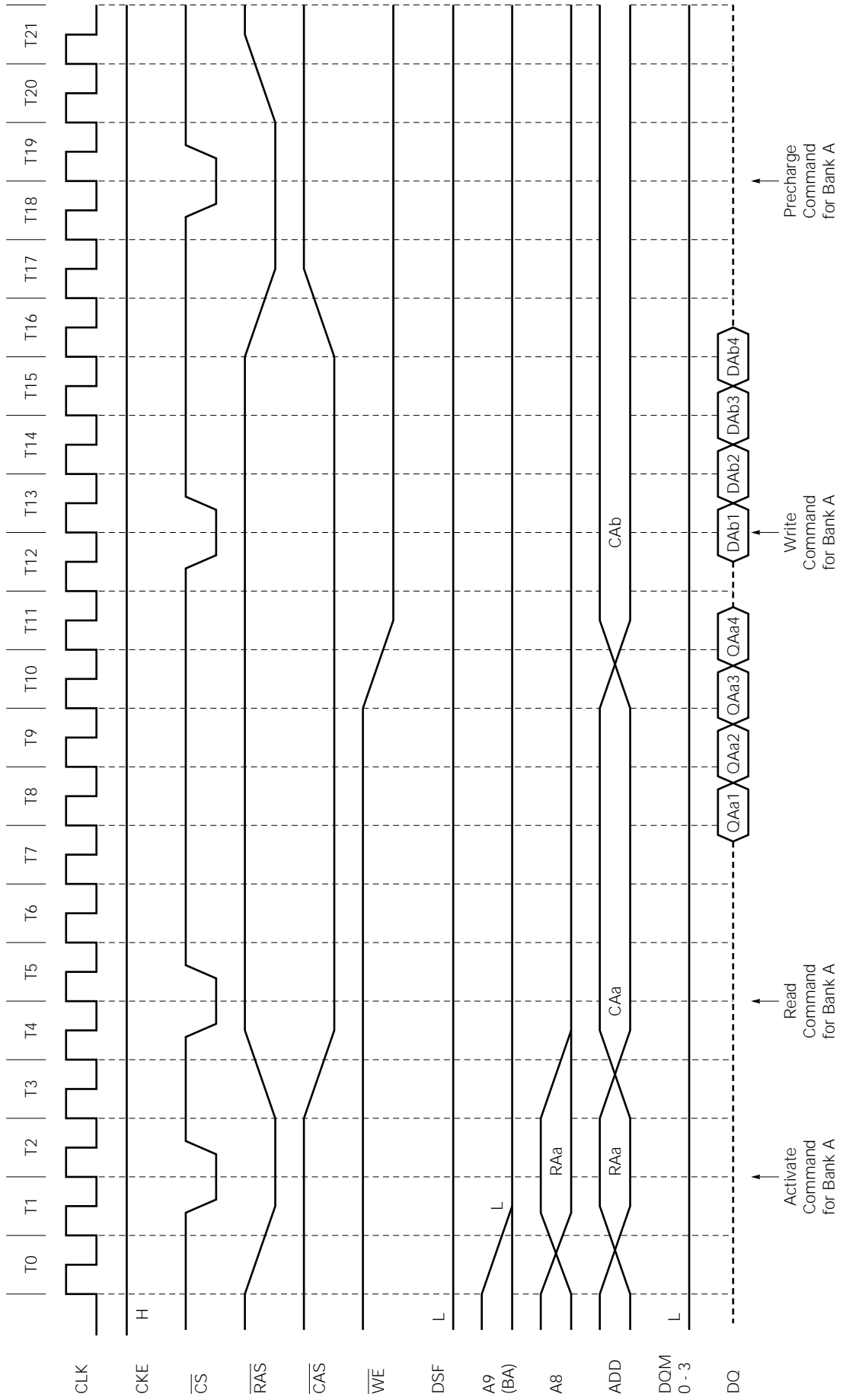


16.2 Relationship between Frequency and Latency

Speed version	-10			-12			-15		
Clock cycle time [ns]	10	15	30	12	18	36	15	19.5	39
Frequency [MHz]	100	66	33	83	55	28	66	50	25
CAS latency	3	2	1	3	2	1	3	2	1
t_{RCD}	3	2	1	3	2	1	3	2	1
$\overline{\text{RAS}}$ latency (CAS latency + t_{RCD})	6	4	2	6	4	2	6	4	2
t_{RC}	10	7	4	10	7	4	10	7	4
t_{RAS}	7	5	3	7	5	3	7	5	3
t_{RRD}	3	2	1	3	2	1	3	2	1
t_{RP}	3	2	1	3	2	1	3	2	1
t_{DPL}	2	1	1	2	1	1	2	1	1
t_{DAL}	5	3	2	5	3	2	5	3	2

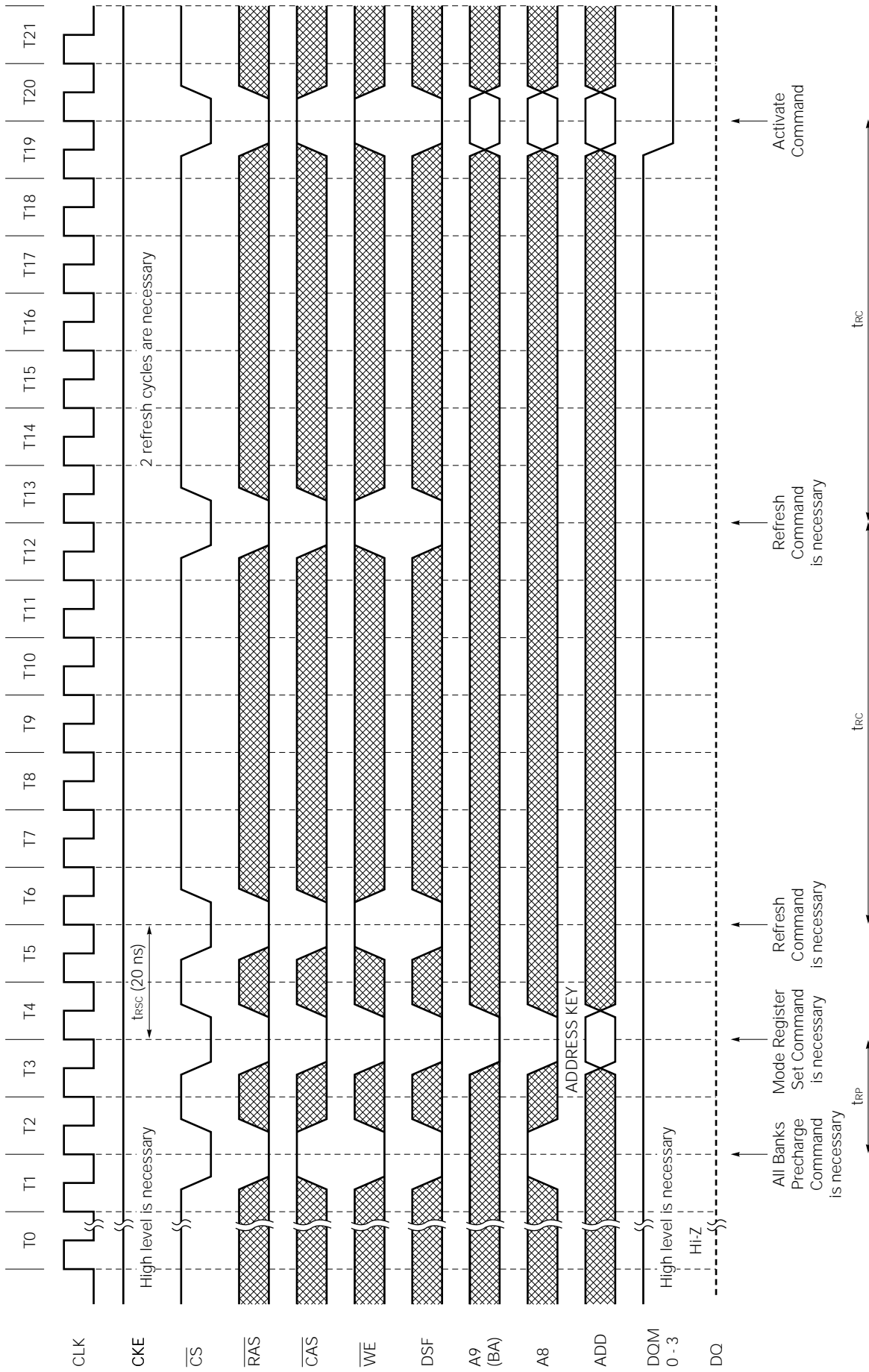
16.3 $\overline{\text{CS}}$ Function

$\overline{\text{CS}}$ Function (Only $\overline{\text{CS}}$ signal needs to be asserted at minimum rate) (at 100 MHz Burst length = 4, $\overline{\text{CAS}}$ latency = 3)

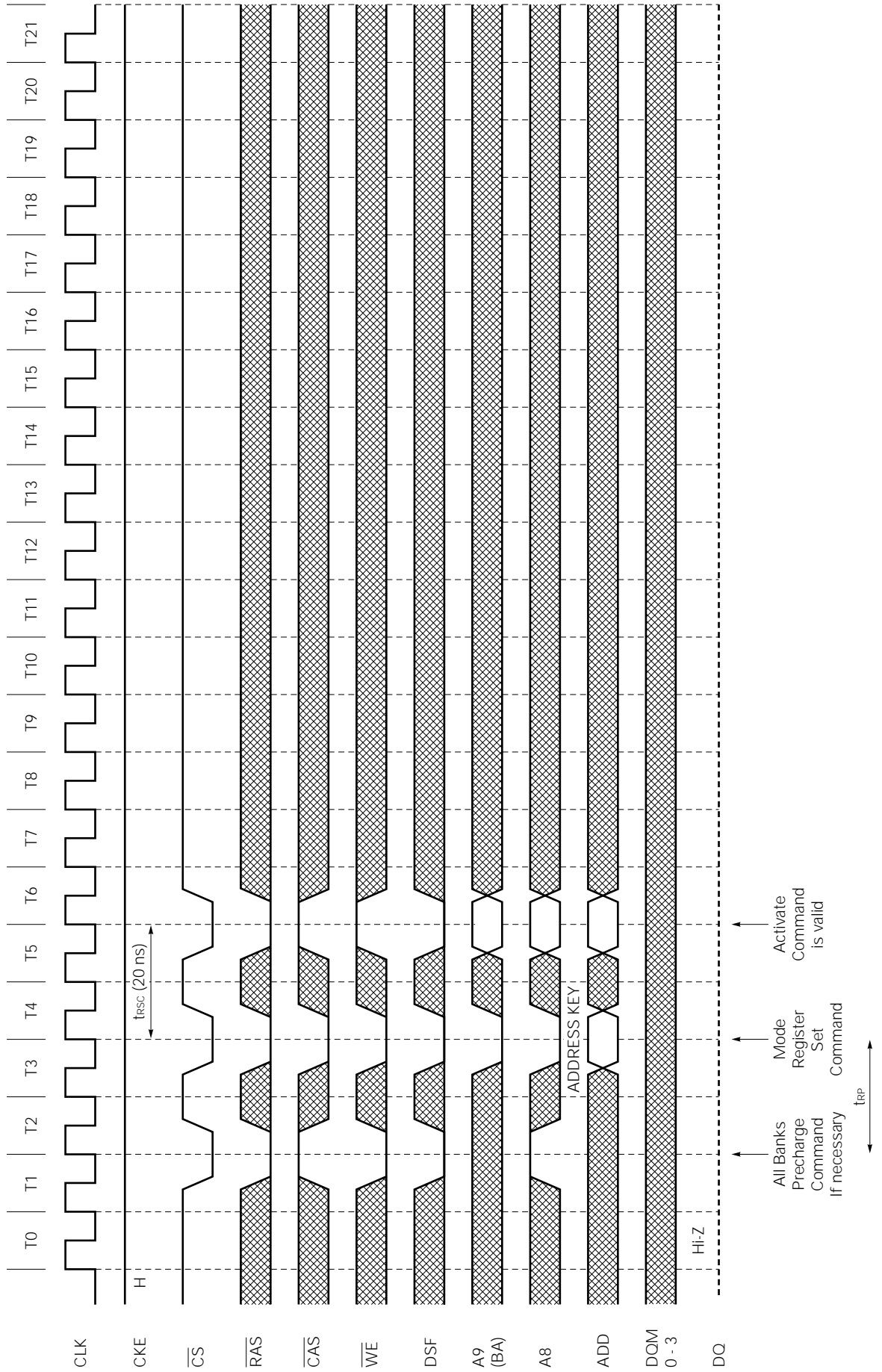


16.4 Basic Cycles
16.4.1 Initialization

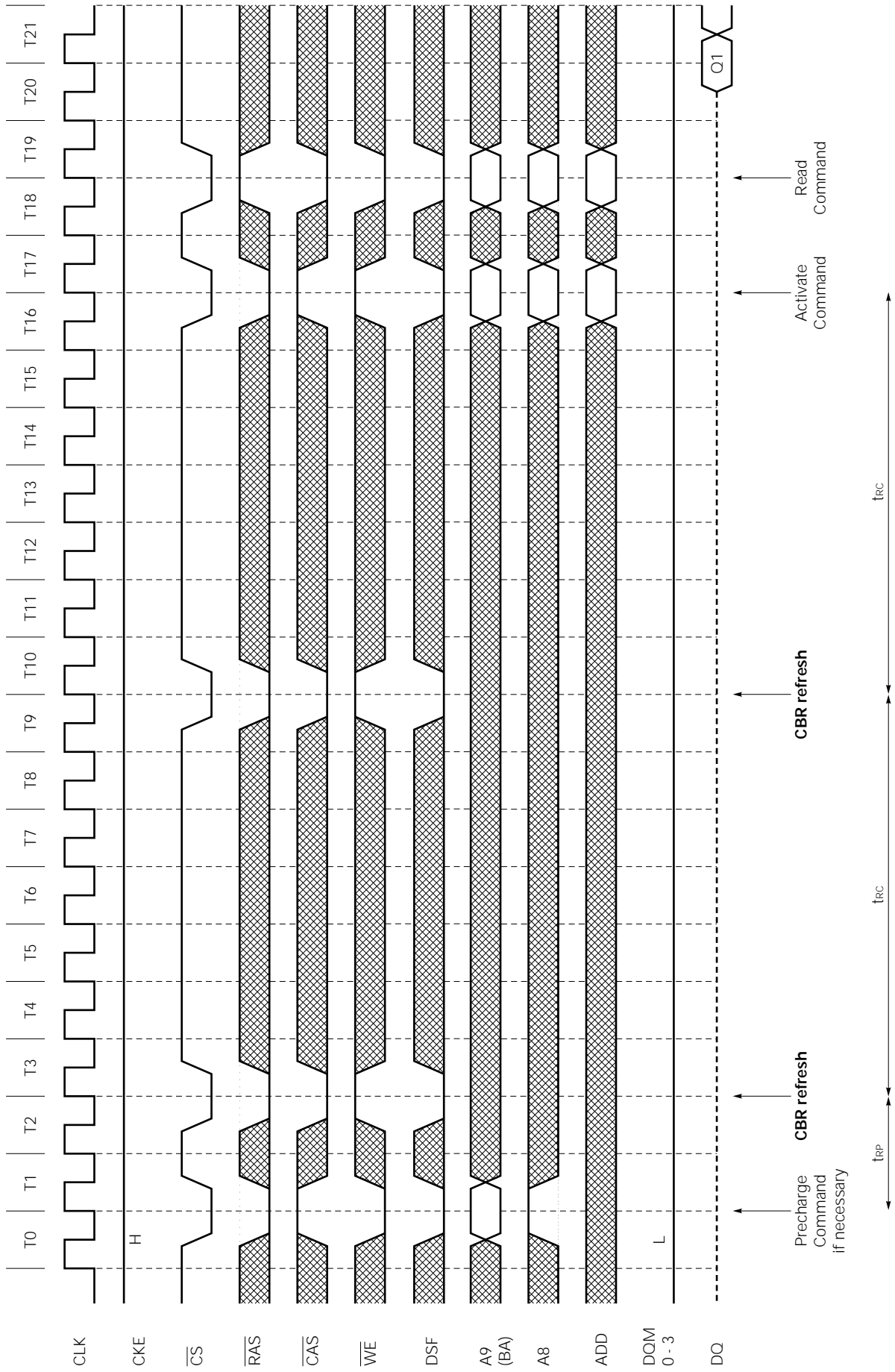
Power on Sequence and Auto Refresh



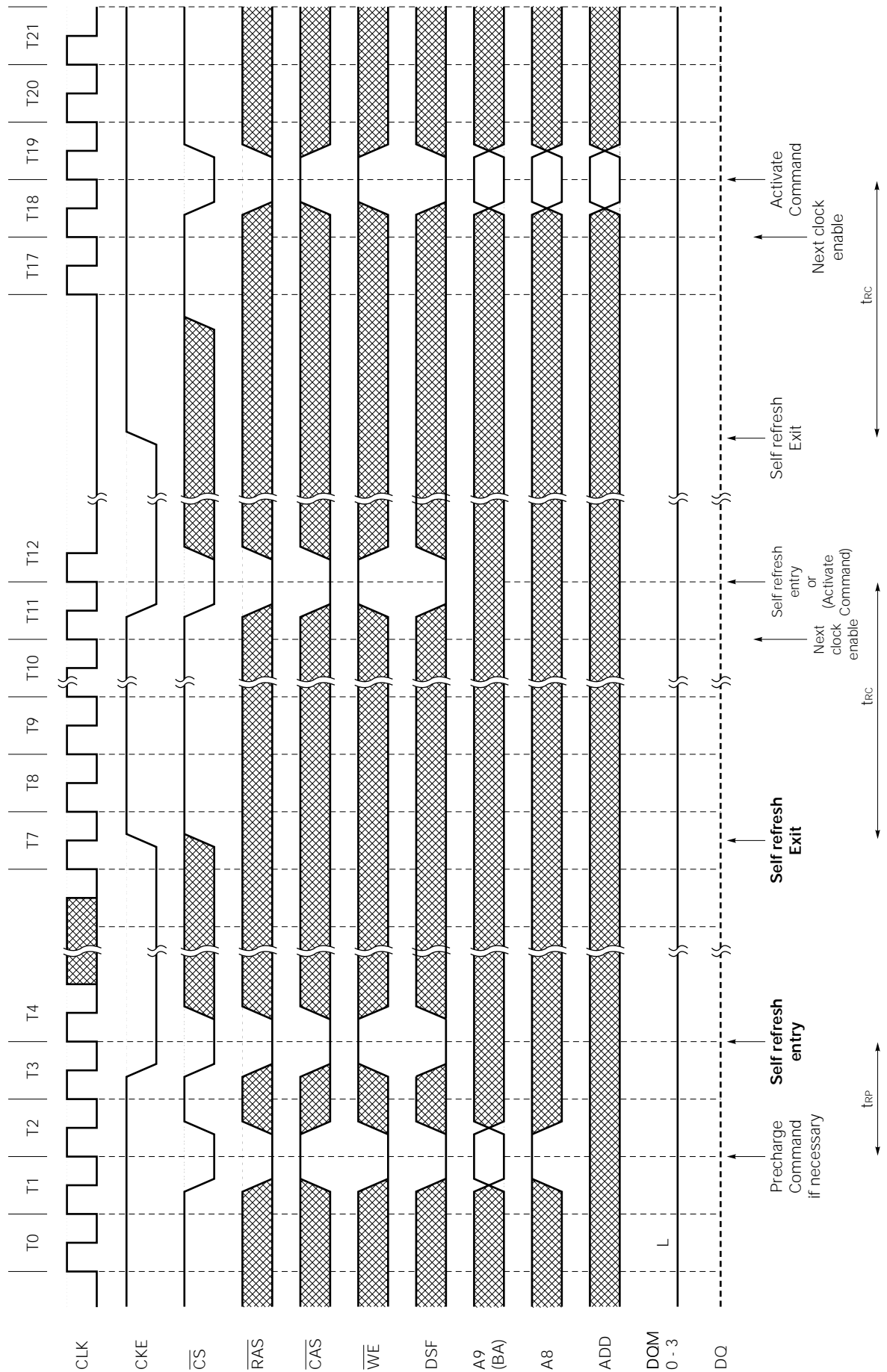
16.4.2 Mode Register Set
Mode Register (Burst length = 4, CAS latency = 2)



16.4.3 Refresh Cycle
 CBR Refresh (CAS latency = 2)

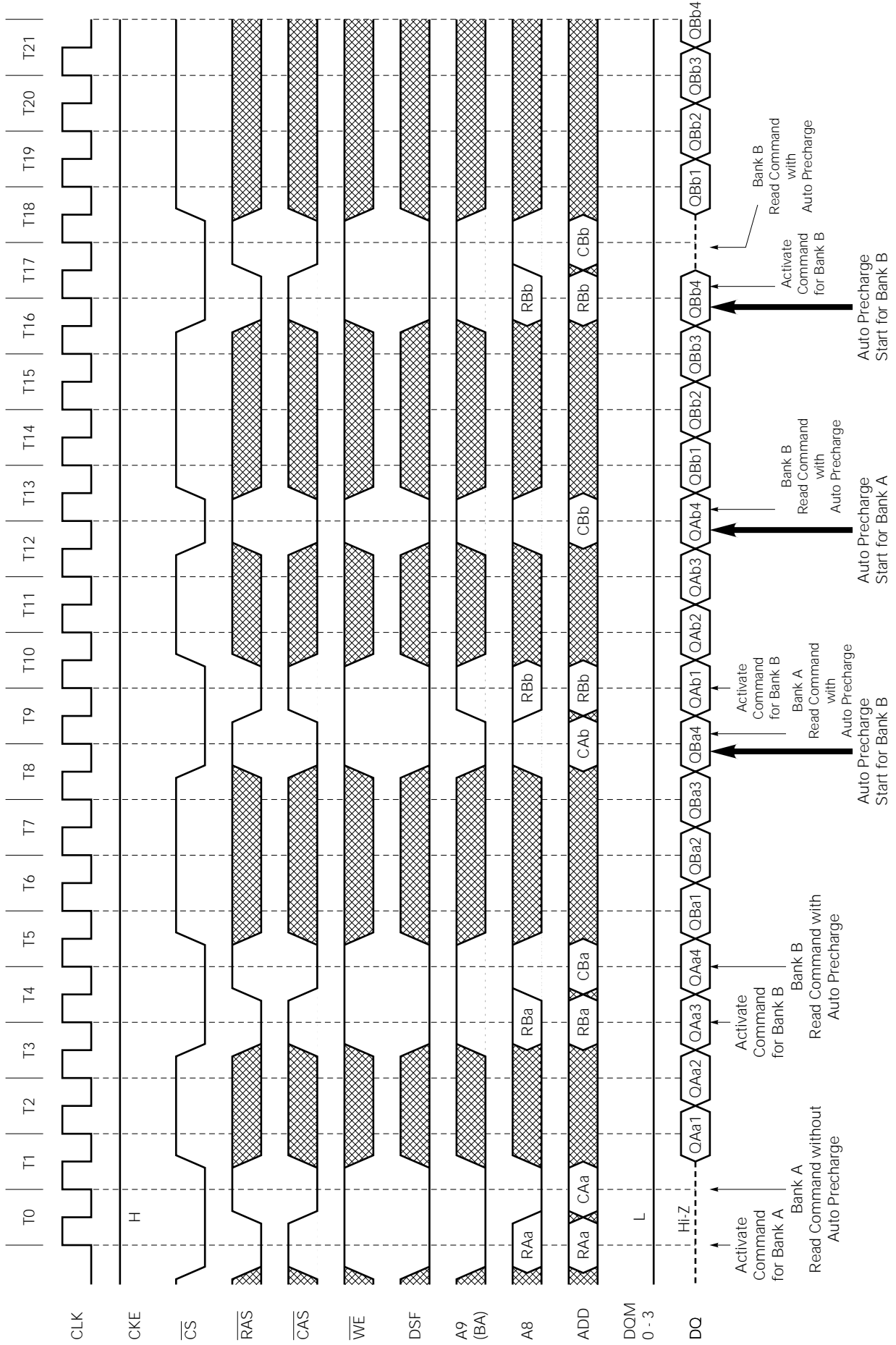


Self Refresh (entry and exit)

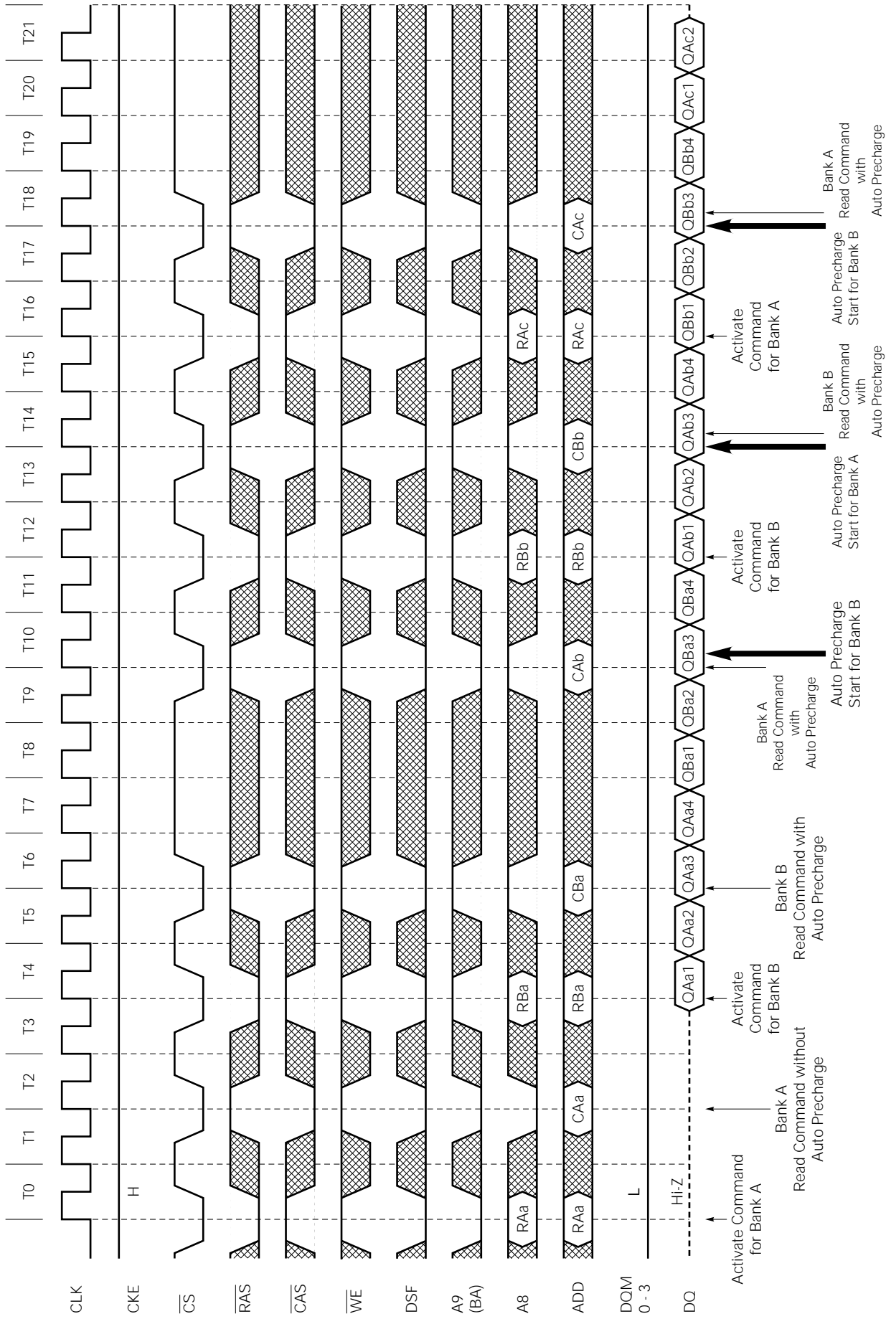


16.4.4 Cycle with Auto Precharge

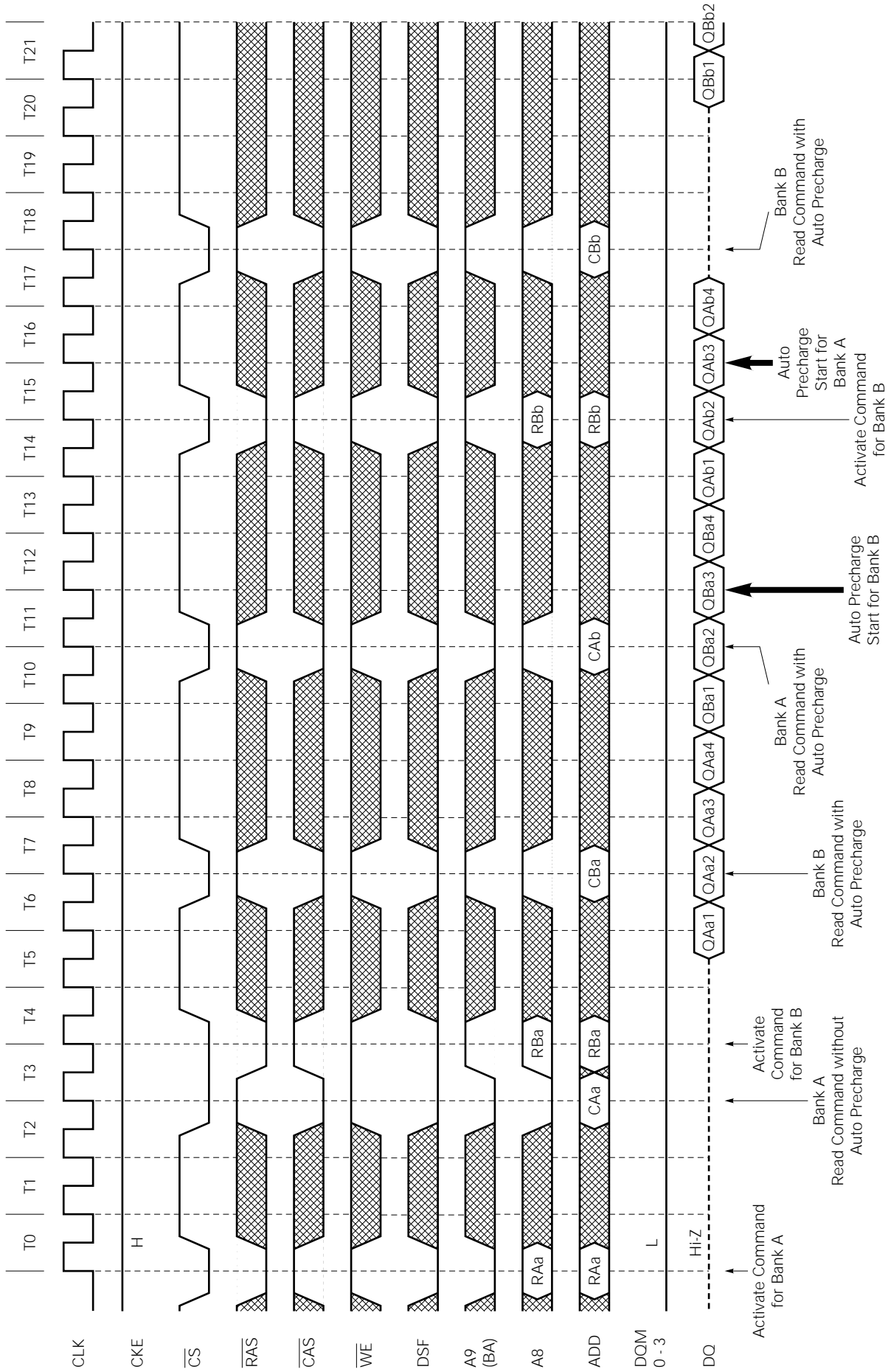
Auto Precharge after Read Burst (1/3) (Burst length = 4, CAS latency = 1)



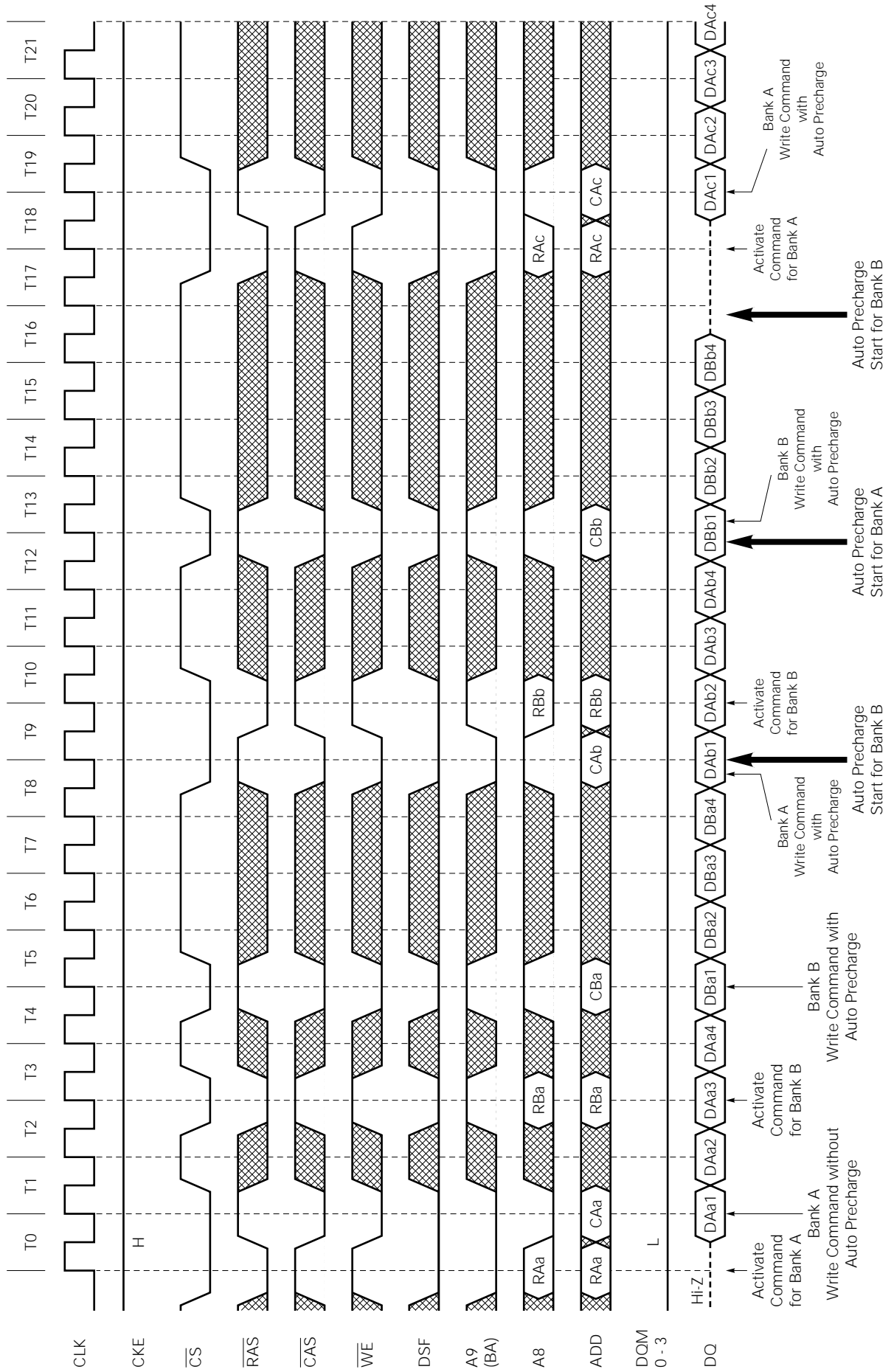
Auto Precharge after Read Burst (2/3) (Burst length = 4, CAS latency = 2)



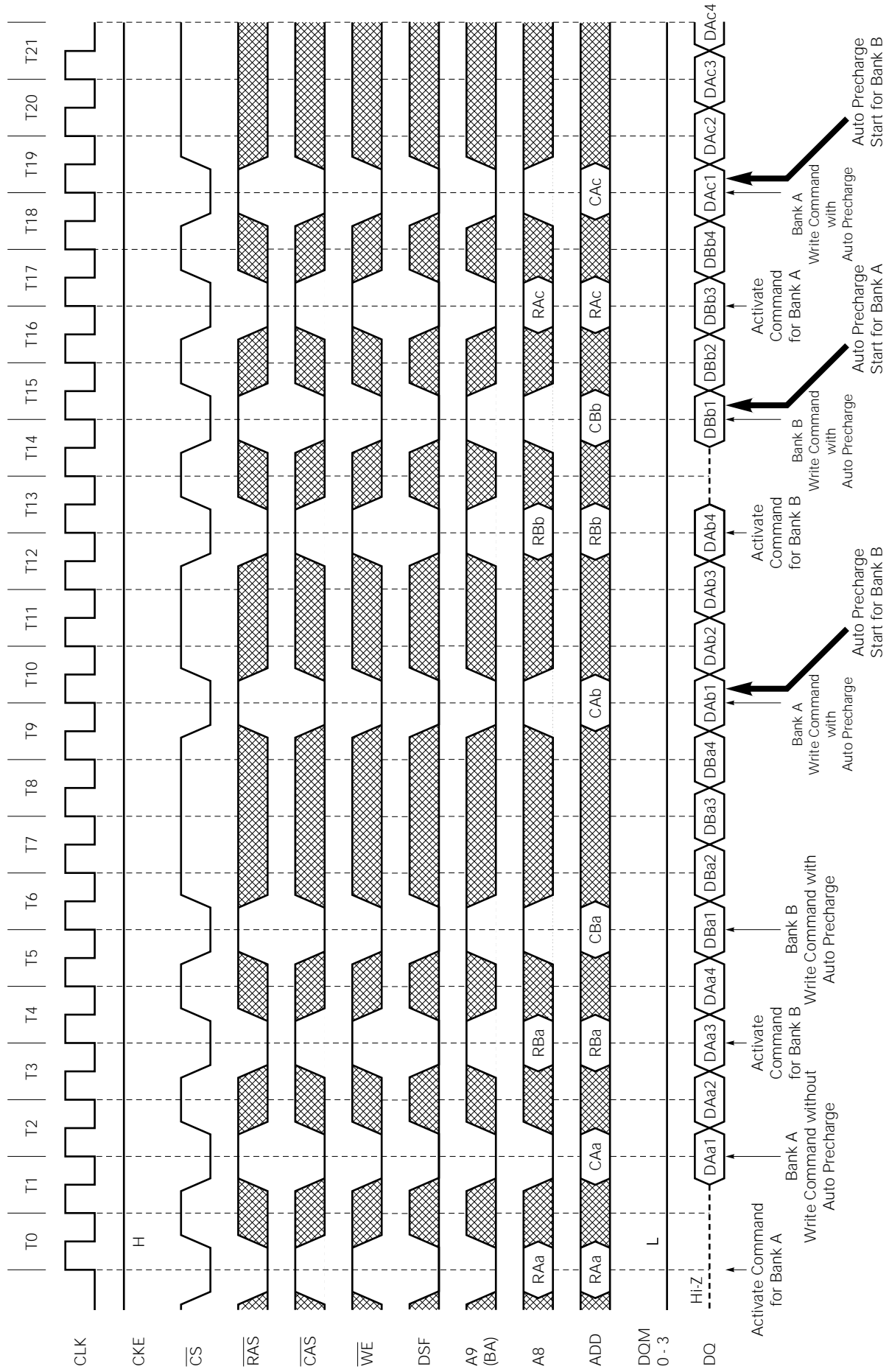
Auto Precharge after Read Burst (3/3) (Burst length = 4, CAS latency = 3)



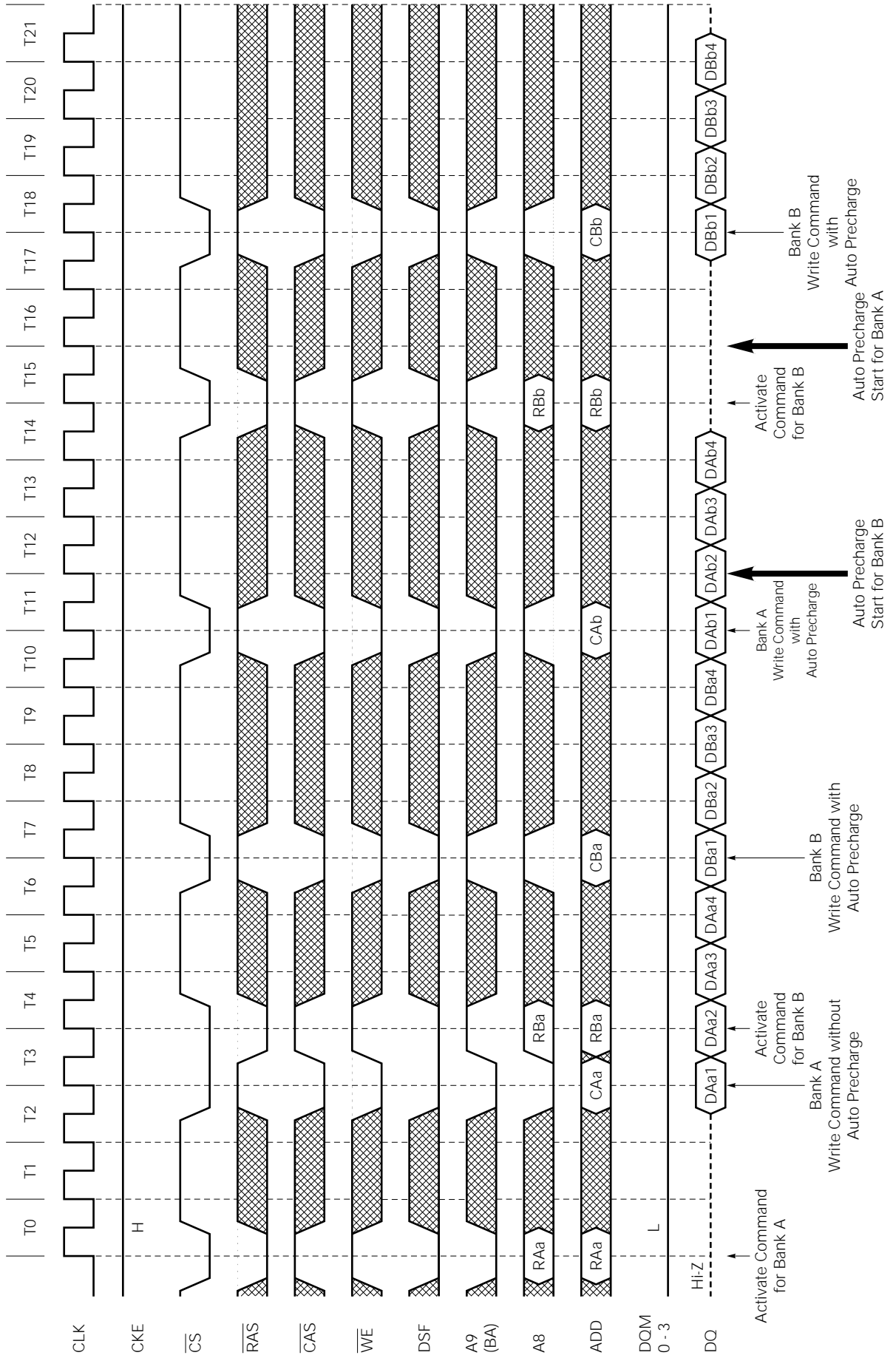
Auto Precharge after Write Burst (1/3) (Burst length = 4, CAS latency = 1)



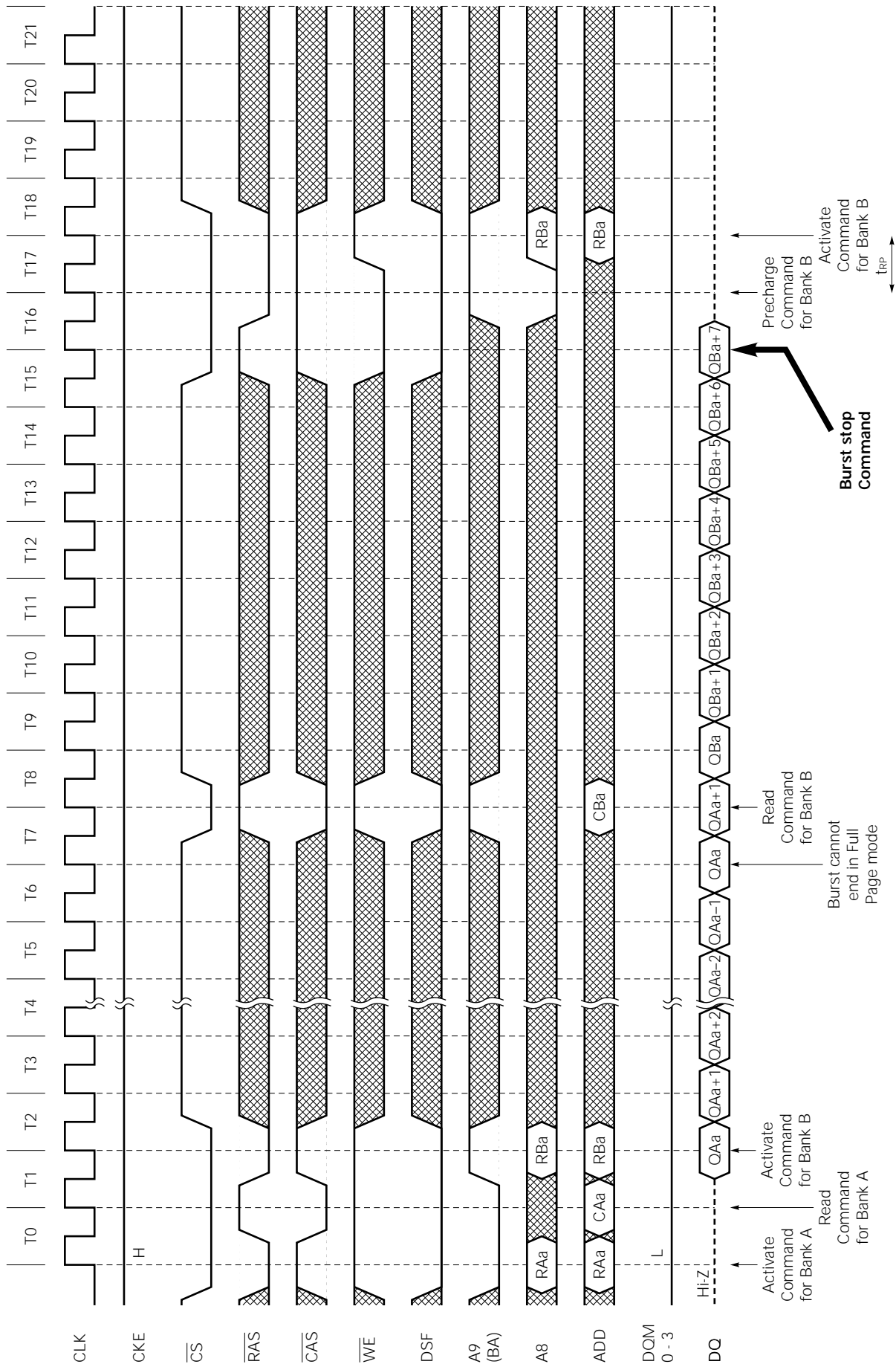
Auto Precharge after Write Burst (2/3) (Burst length = 4, CAS latency = 2)



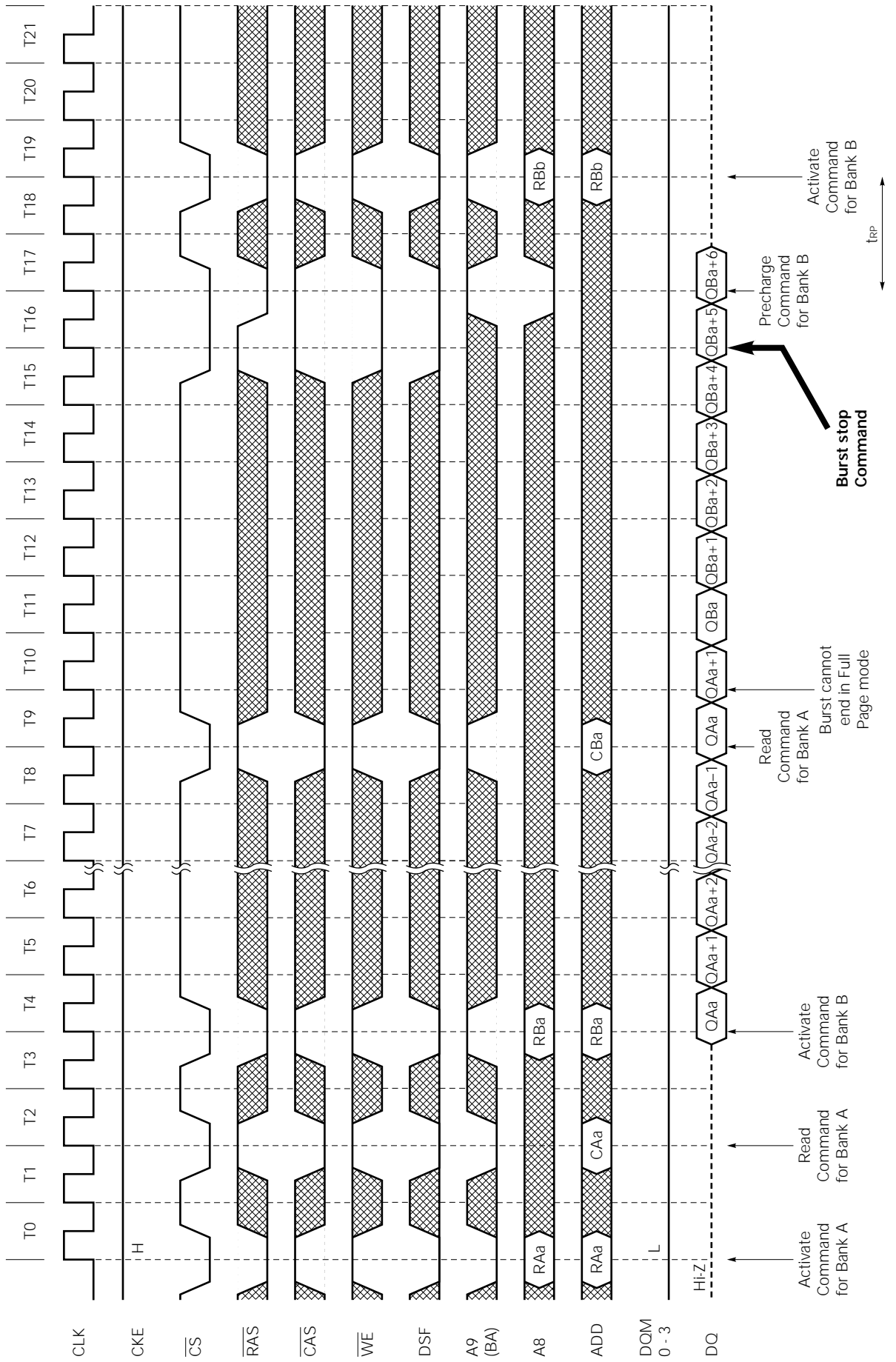
Auto Precharge after Write Burst (3/3) (Burst length = 4, CAS latency = 3)



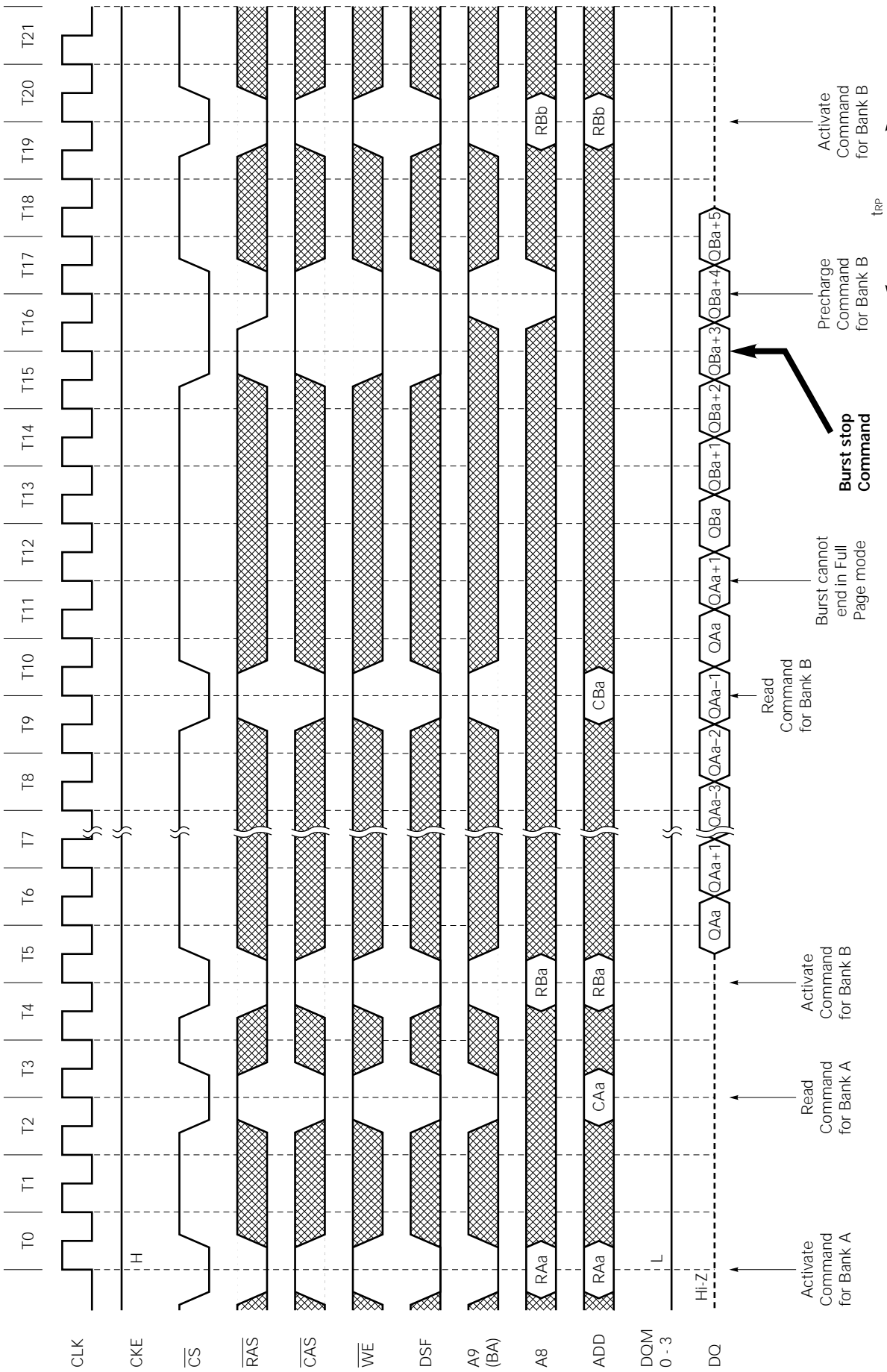
16.4.5 Full Page Mode Cycle
Full Page READ Cycle (1/3) (CAS latency = 1)



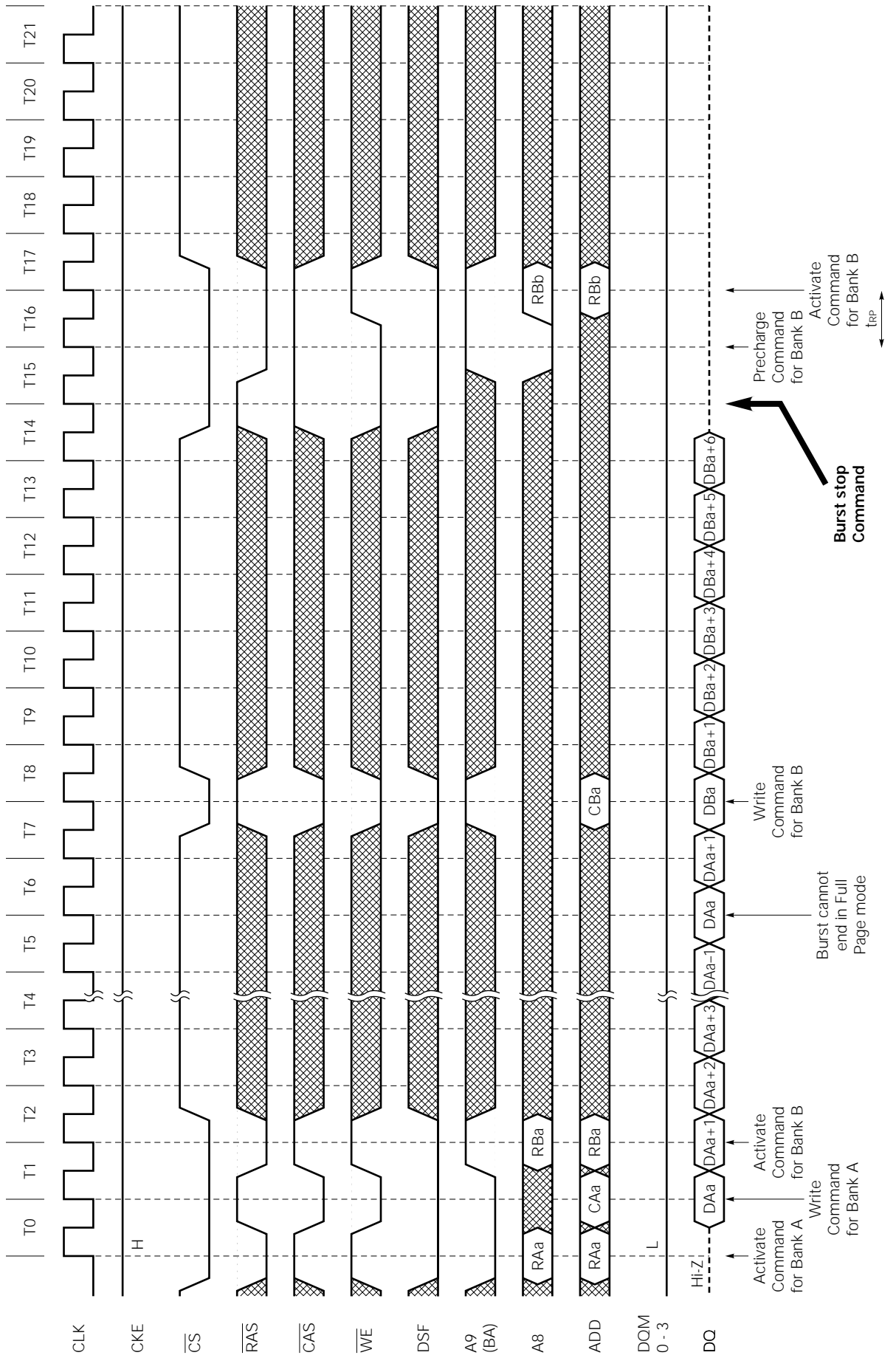
Full Page READ Cycle (2/3) (CAS latency = 2)



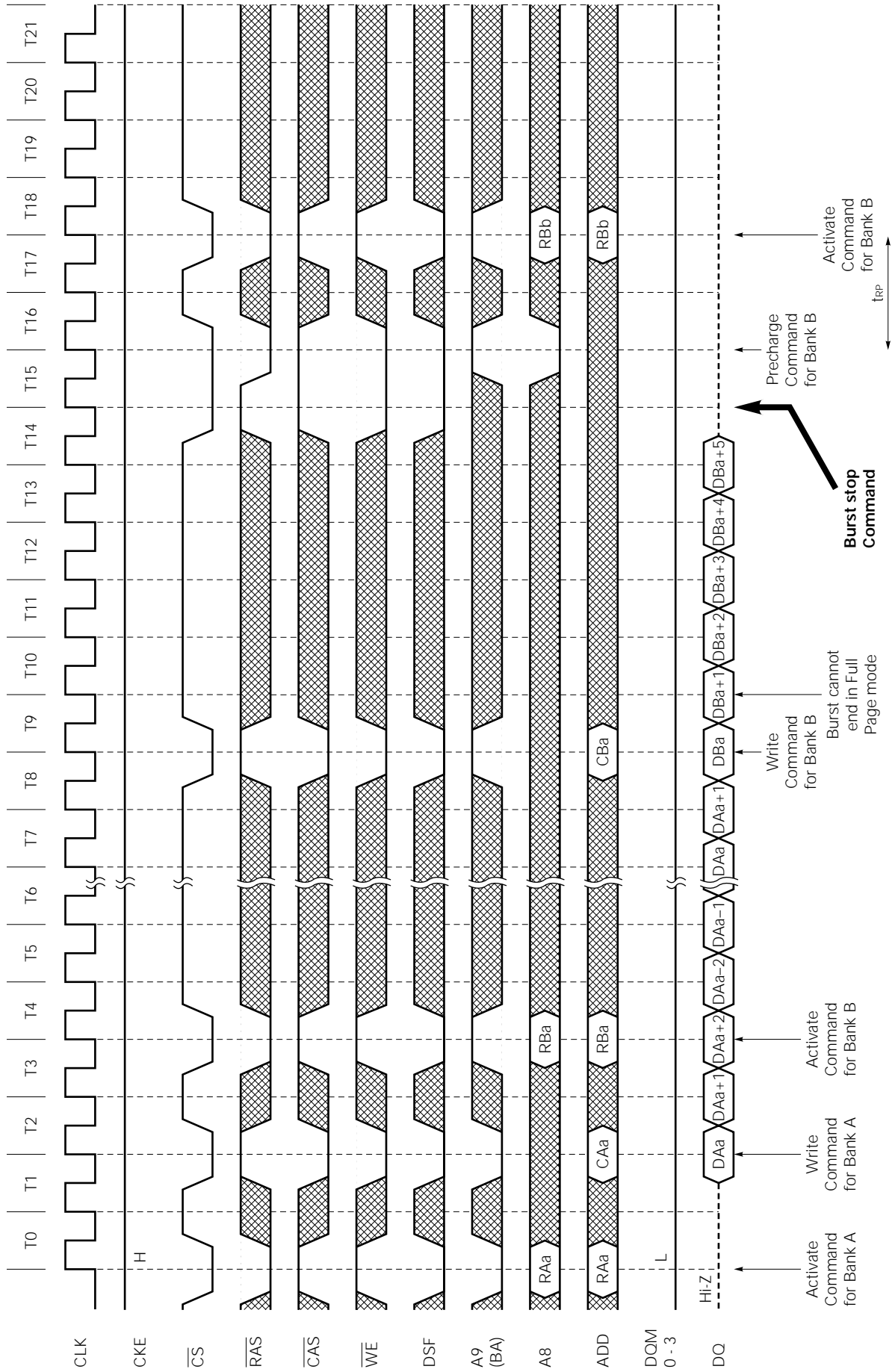
Full Page READ Cycle (3/3) (CAS latency = 3)



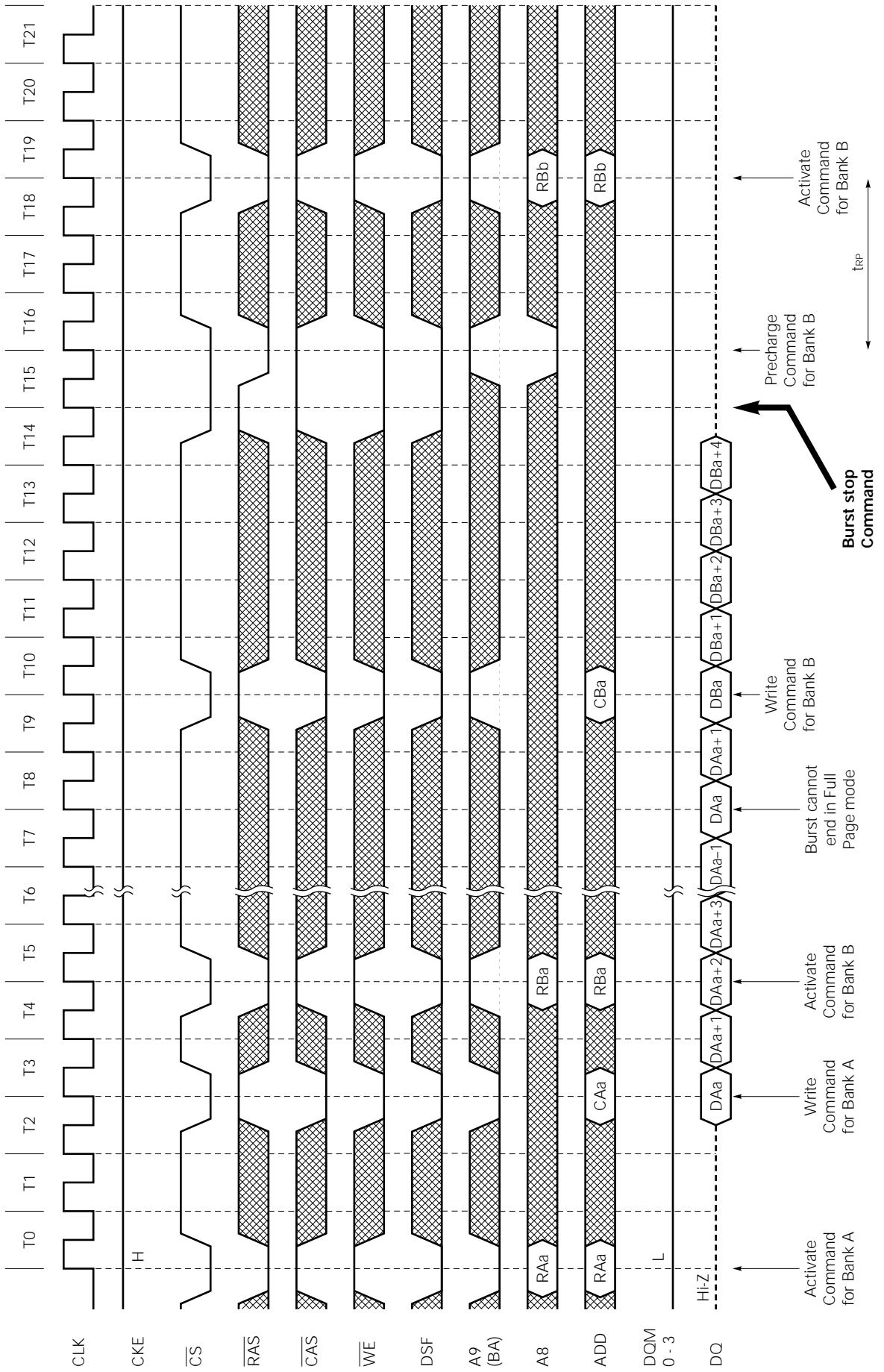
Full Page WRITE Cycle (1/3) (CAS latency = 1)



Full Page WRITE Cycle (2/3) (CAS latency = 2)

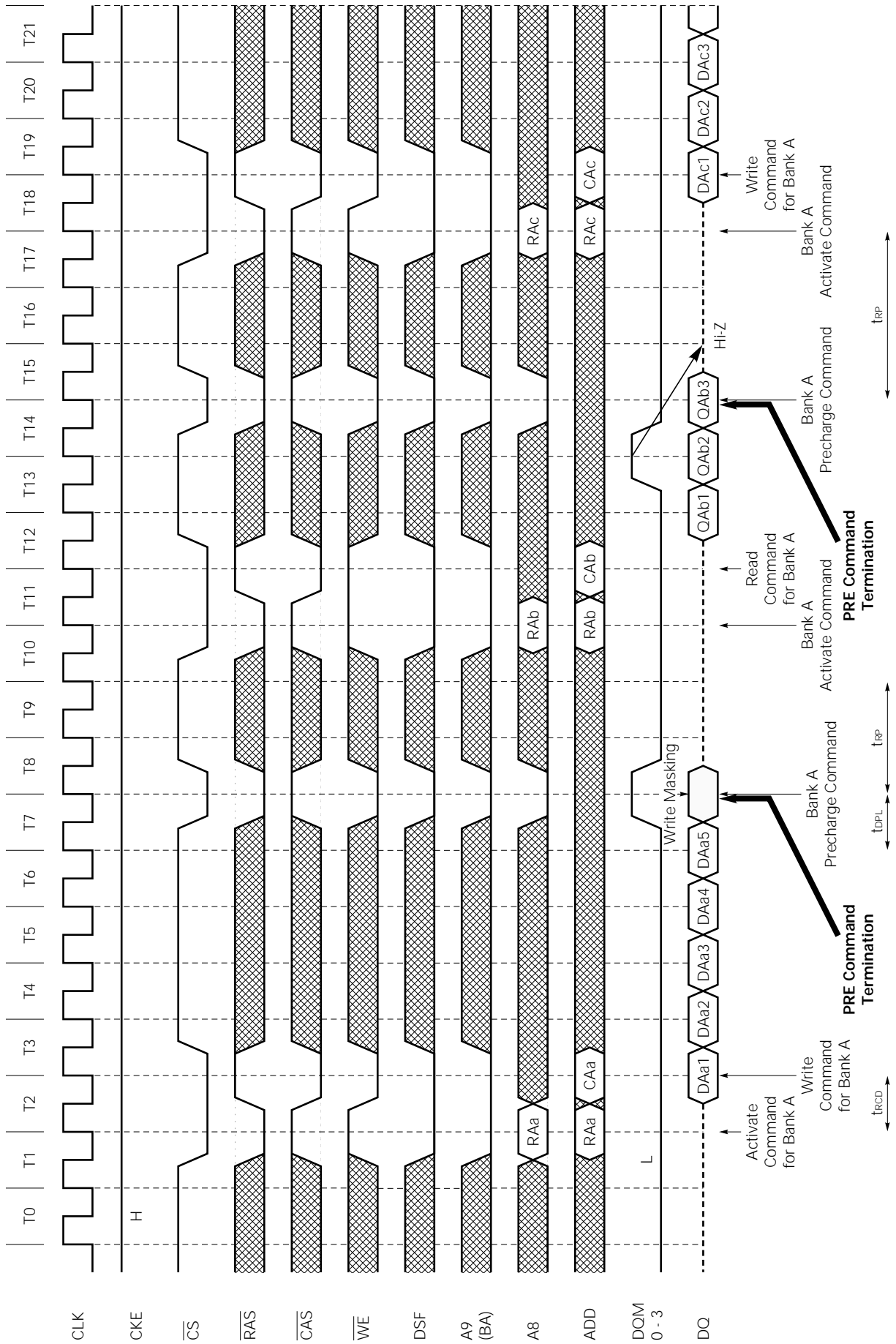


Full Page WRITE Cycle (3/3) (CAS latency = 3)

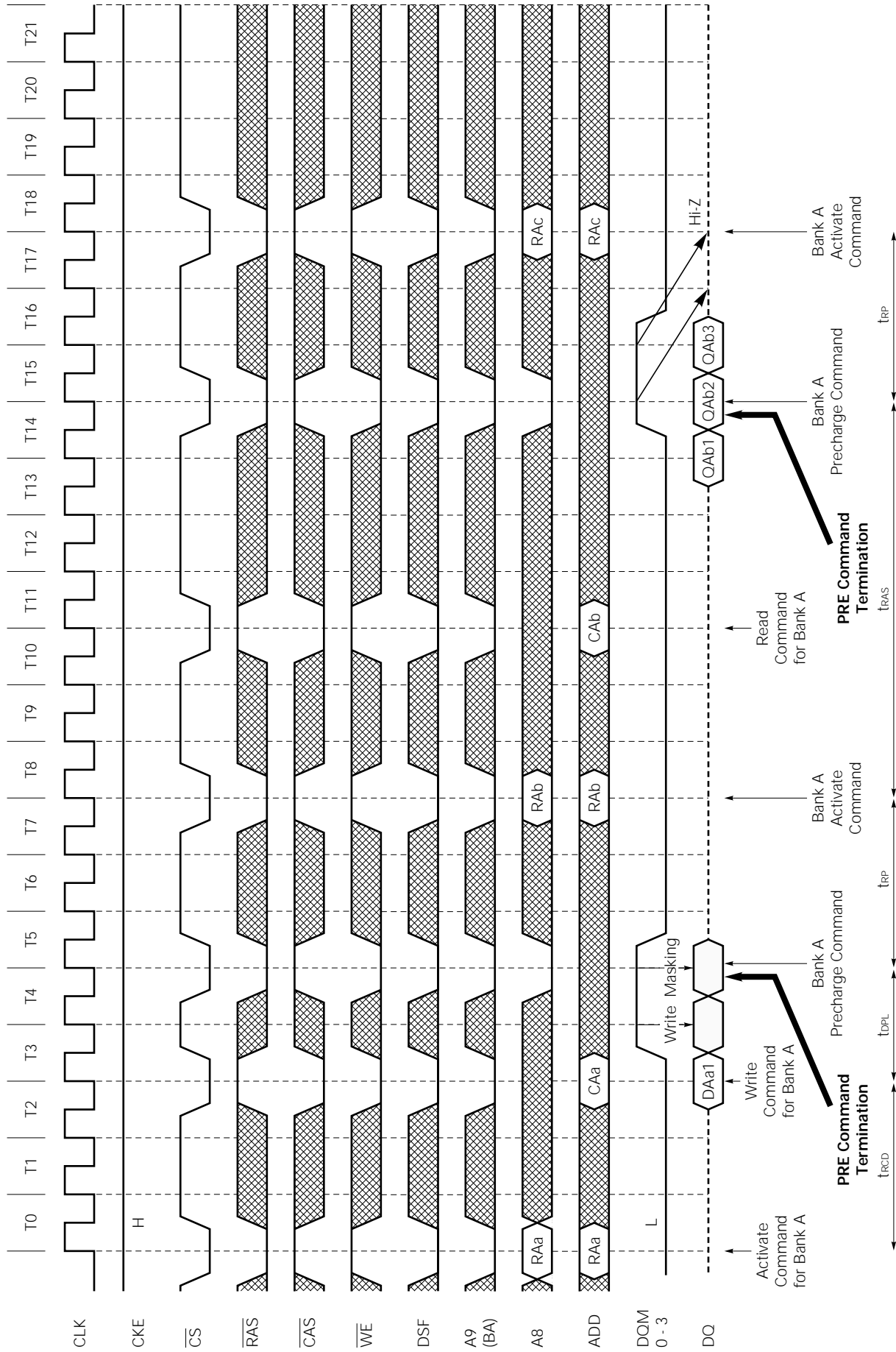


16.4.6 Precharge Termination Cycle

PRE (Precharge) Termination of Burst (1/3) (Burst length = 2, 4, 8, Full, CAS latency = 1)

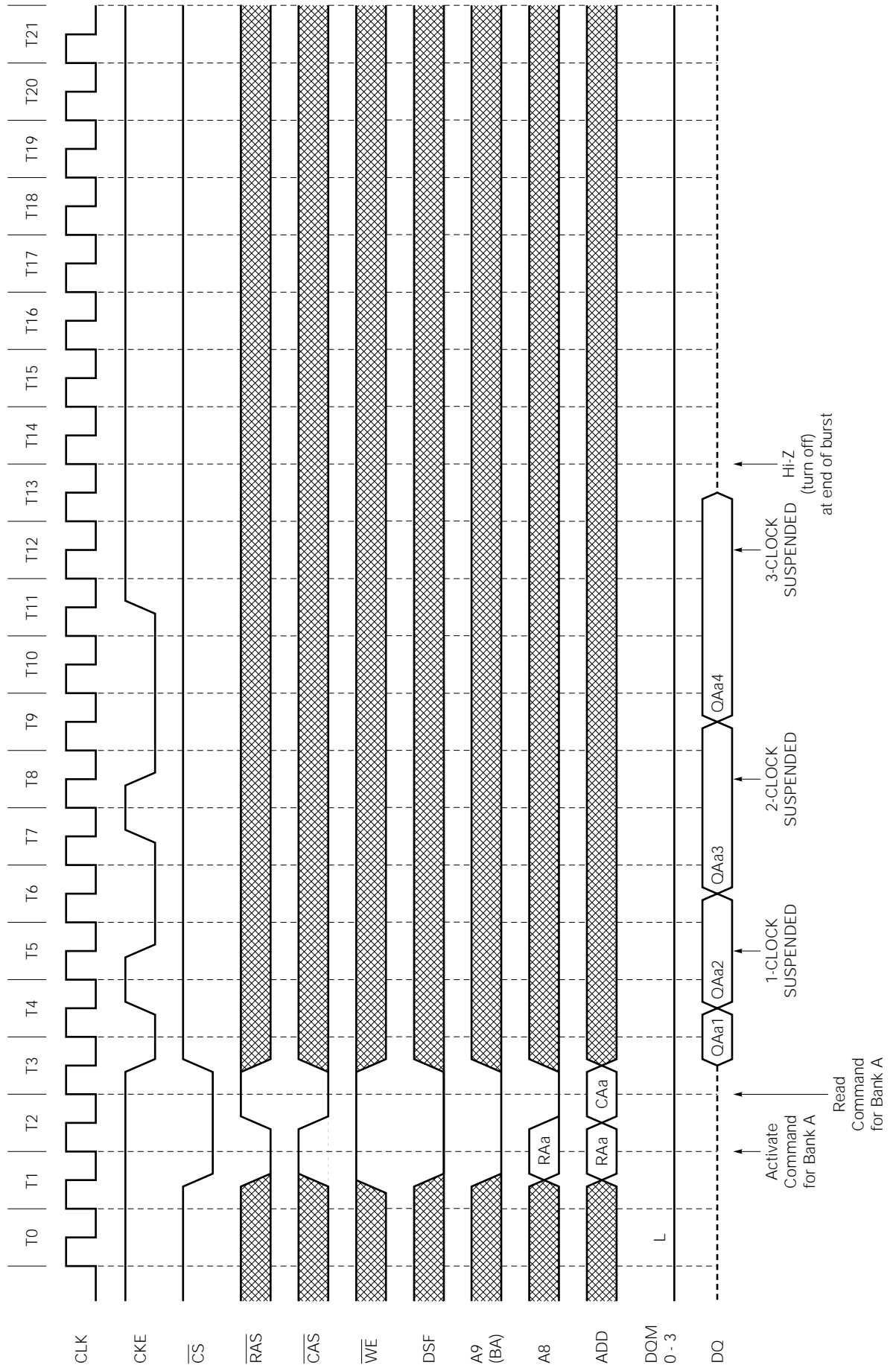


PRE (Precharge) Termination of Burst (3/3) (Burst length = 2, 4, 8, Full, CAS latency = 3)

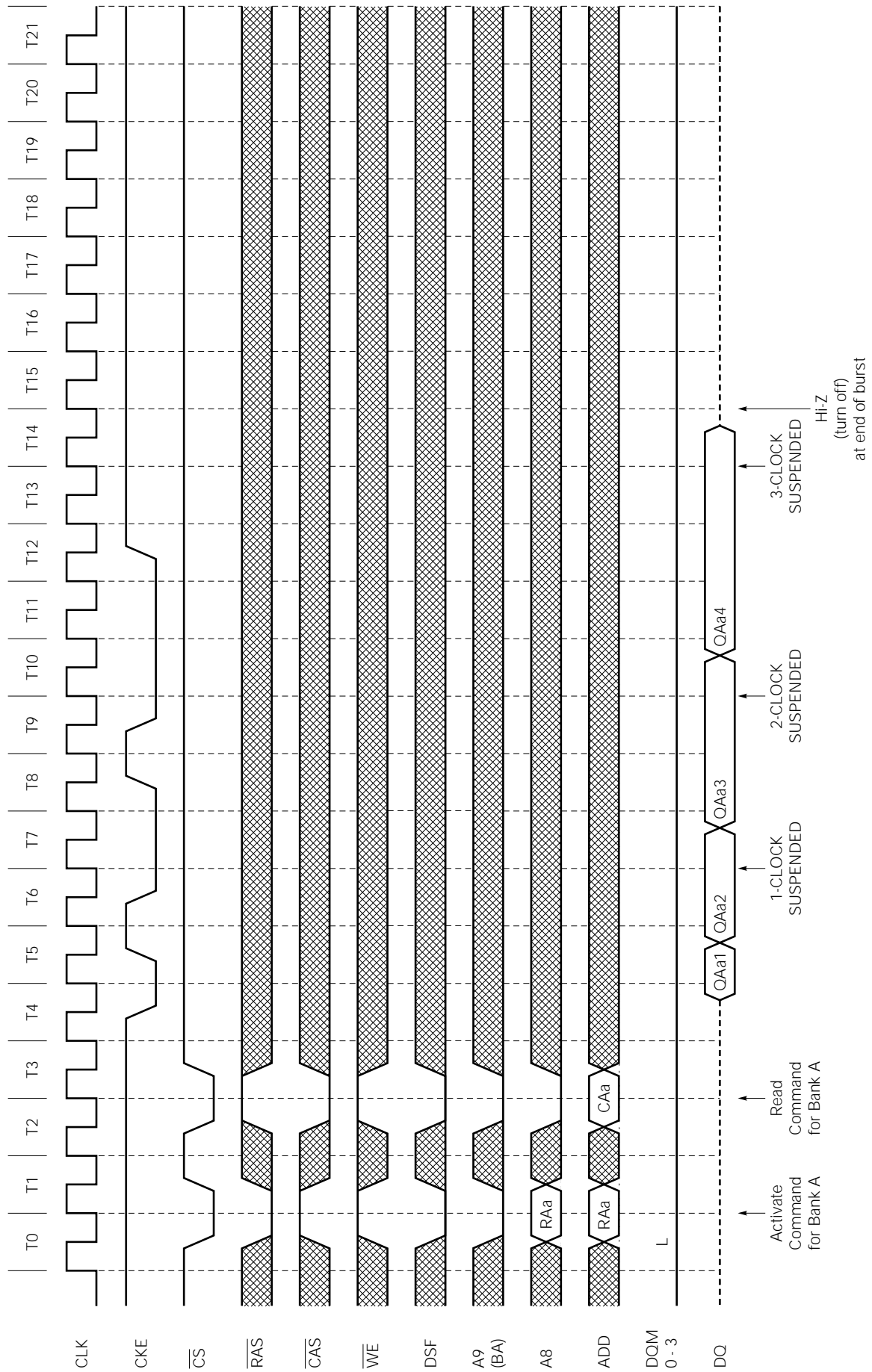


16.4.7 Clock Suspension

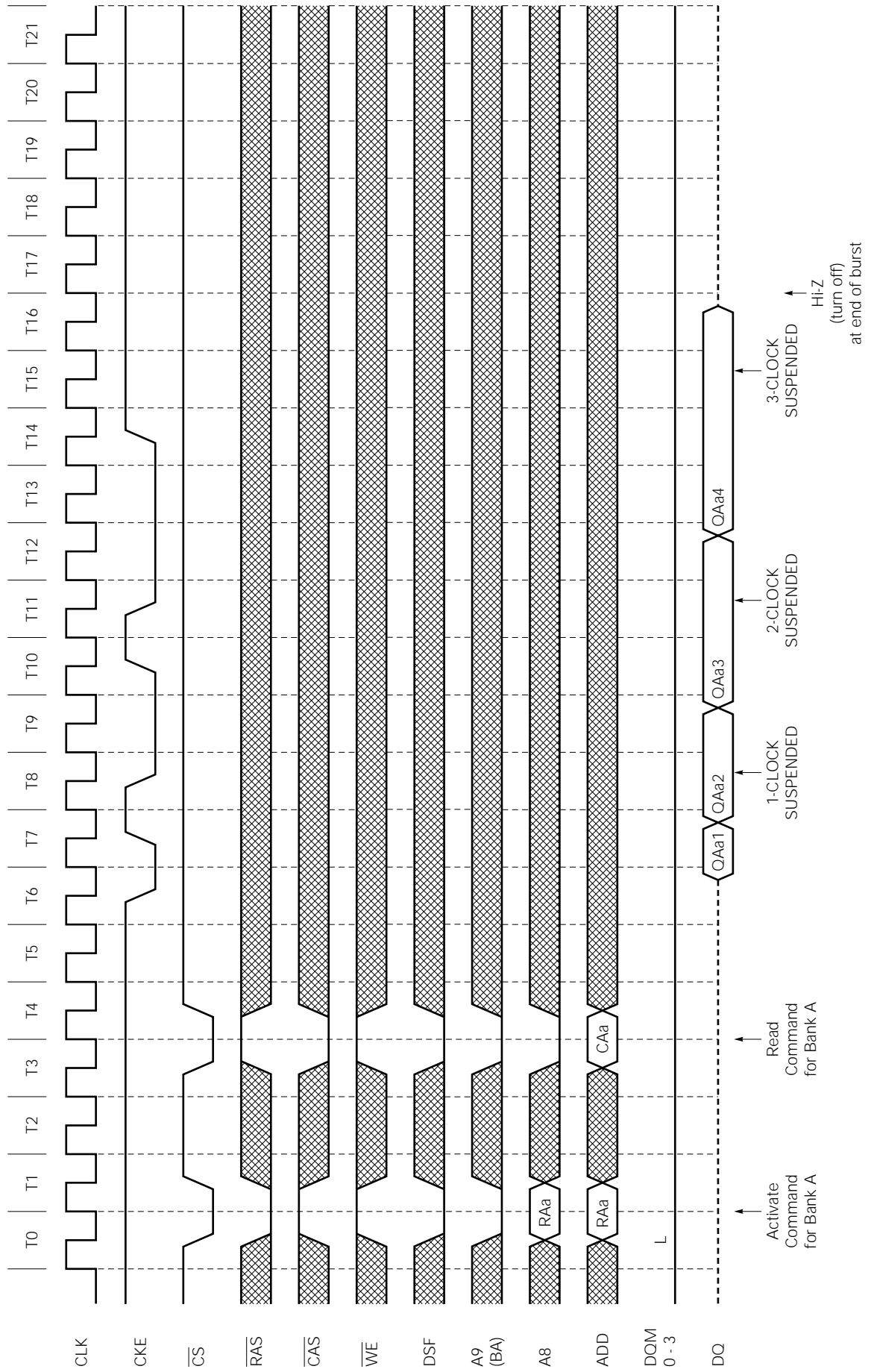
Clock Suspension during Burst Read (using CKE Function) (1/3) (Burst length = 4, CAS latency = 1)



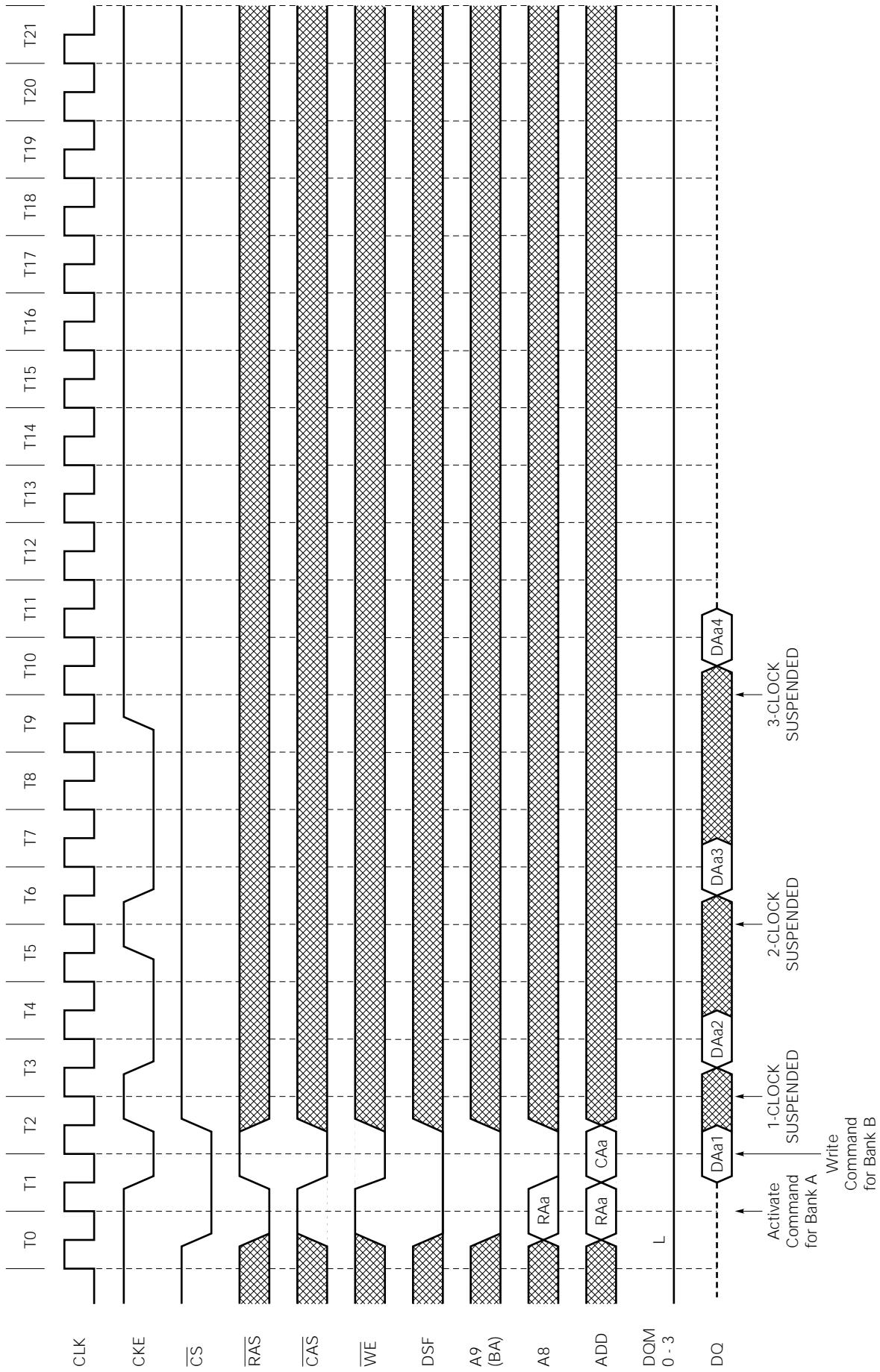
Clock Suspension during Burst Read (using CKE Function) (2/3) (Burst length = 4, CAS latency = 2)



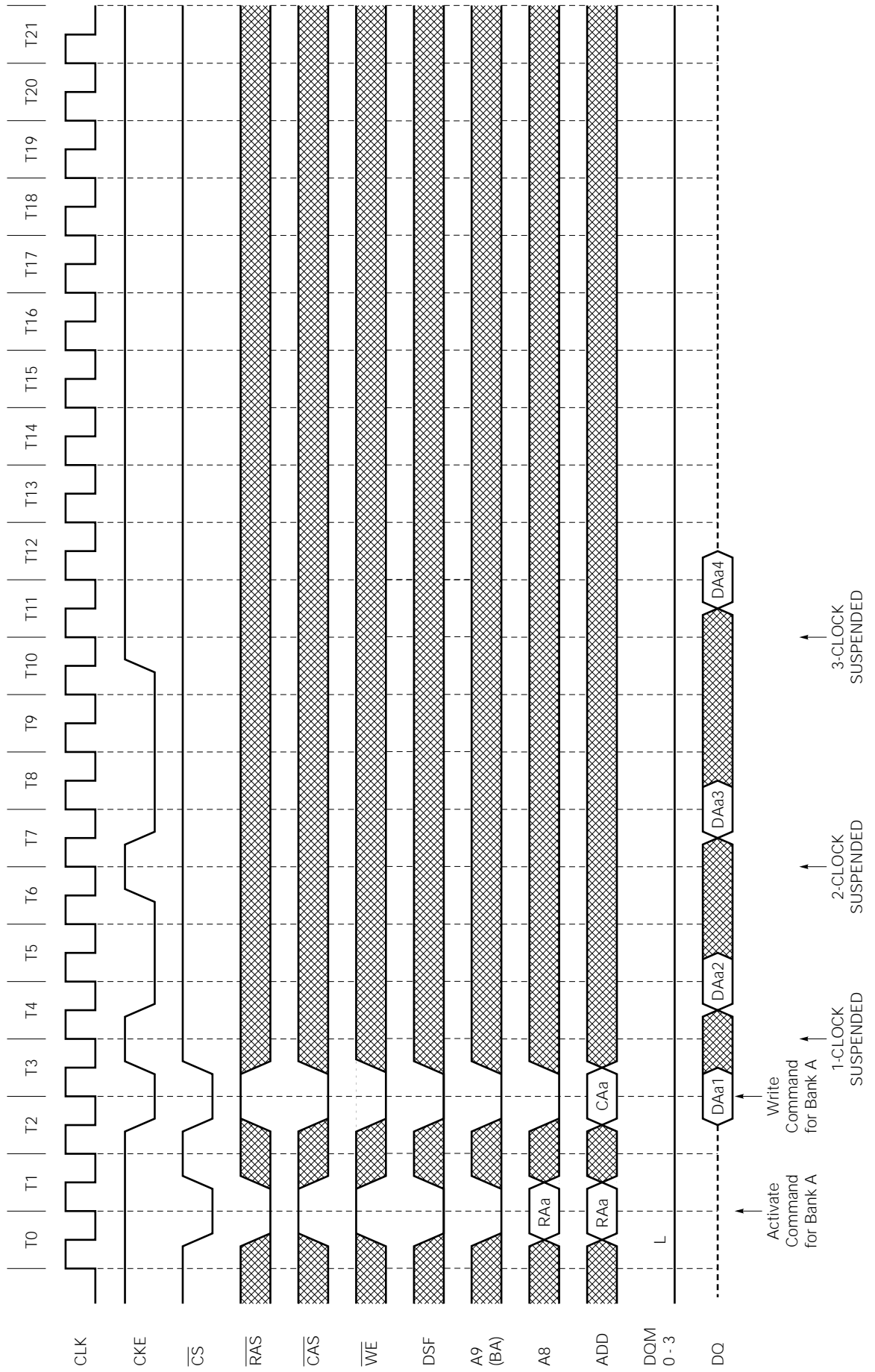
Clock Suspension during Burst Read (using CKE Function) (3/3) (Burst length = 4, CAS latency = 3)



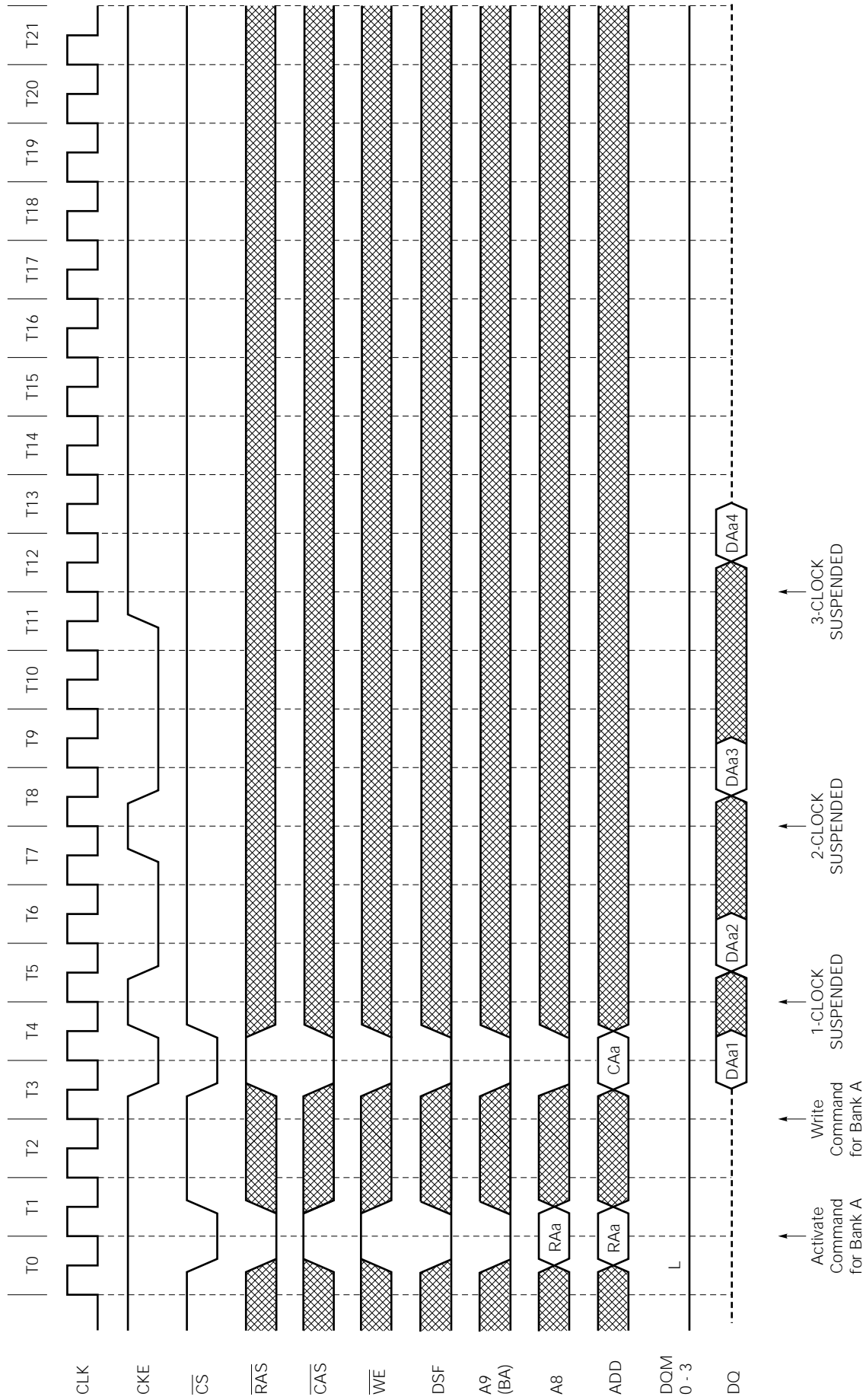
Clock Suspension during Burst Write (using CKE Function) (1/3) (Burst length = 4, CAS latency = 1)



Clock Suspension during Burst Write (using CKE Function) (2/3) (Burst length = 4, CAS latency = 2)

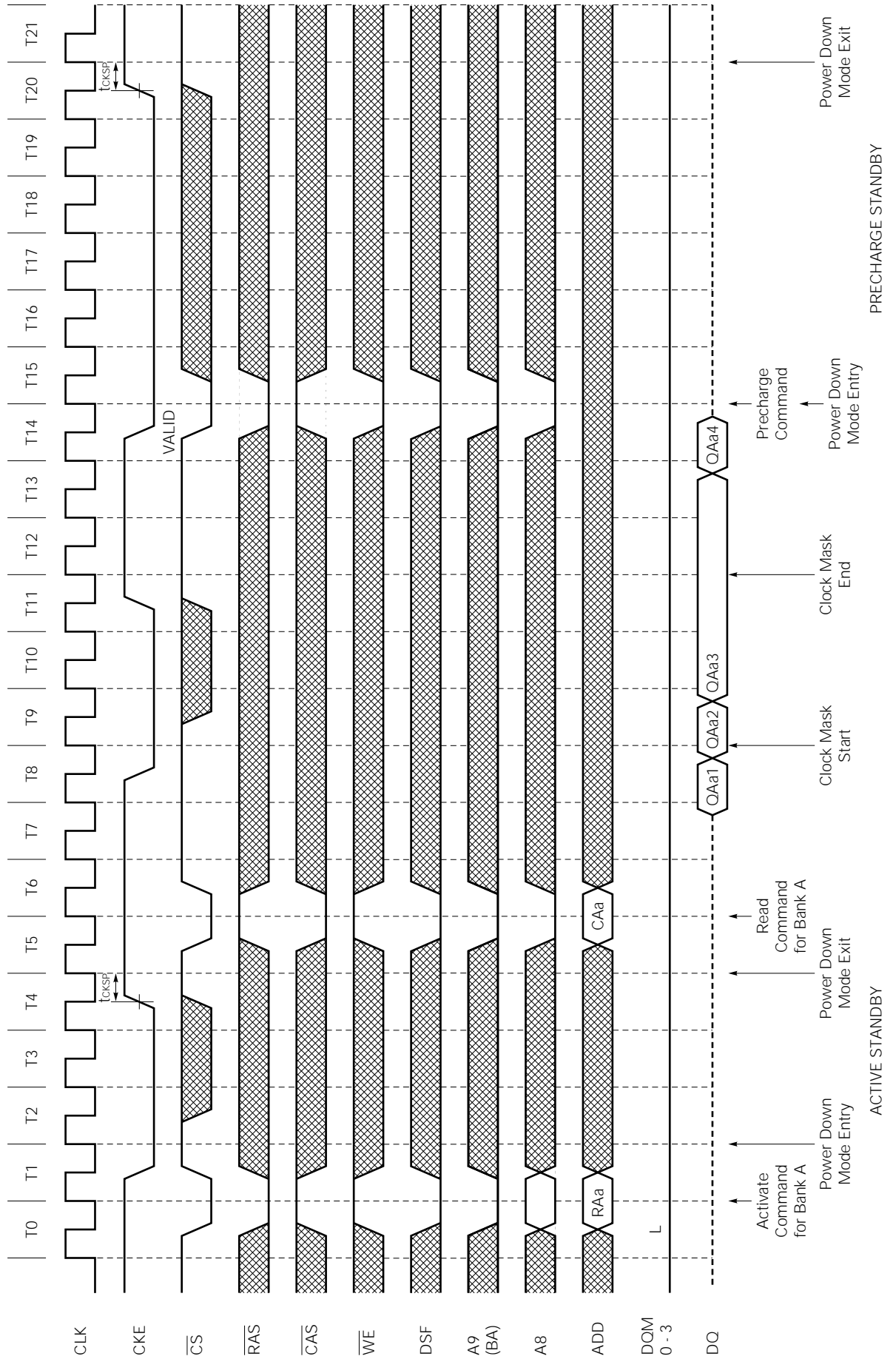


Clock Suspension during Burst Write (using CKE Function) (3/3) (Burst length = 4, CAS latency = 3)



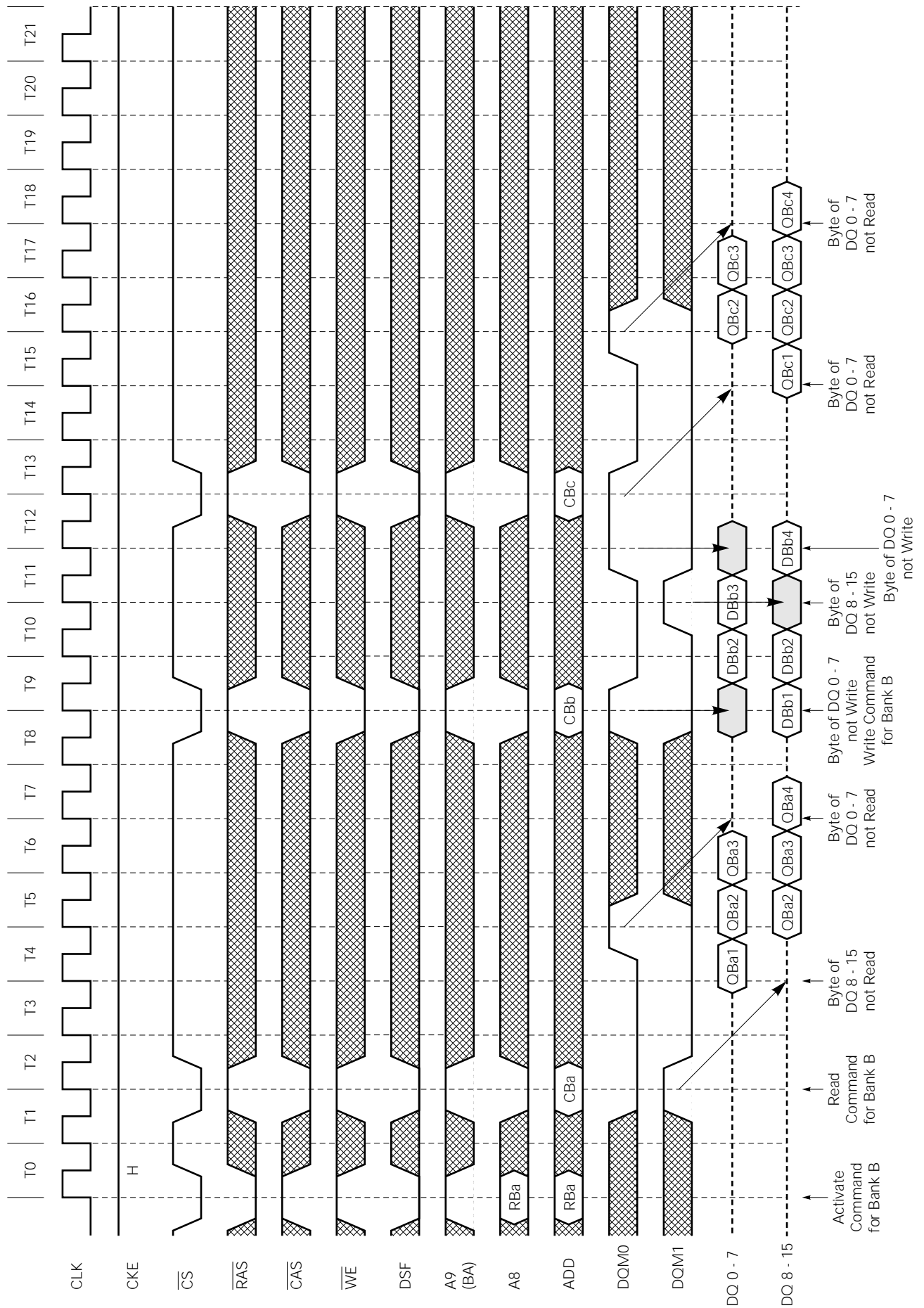
16.4.8 Power Down Mode

Power Down Mode and Clock Suspension (Burst length = 4, CAS latency = 2)

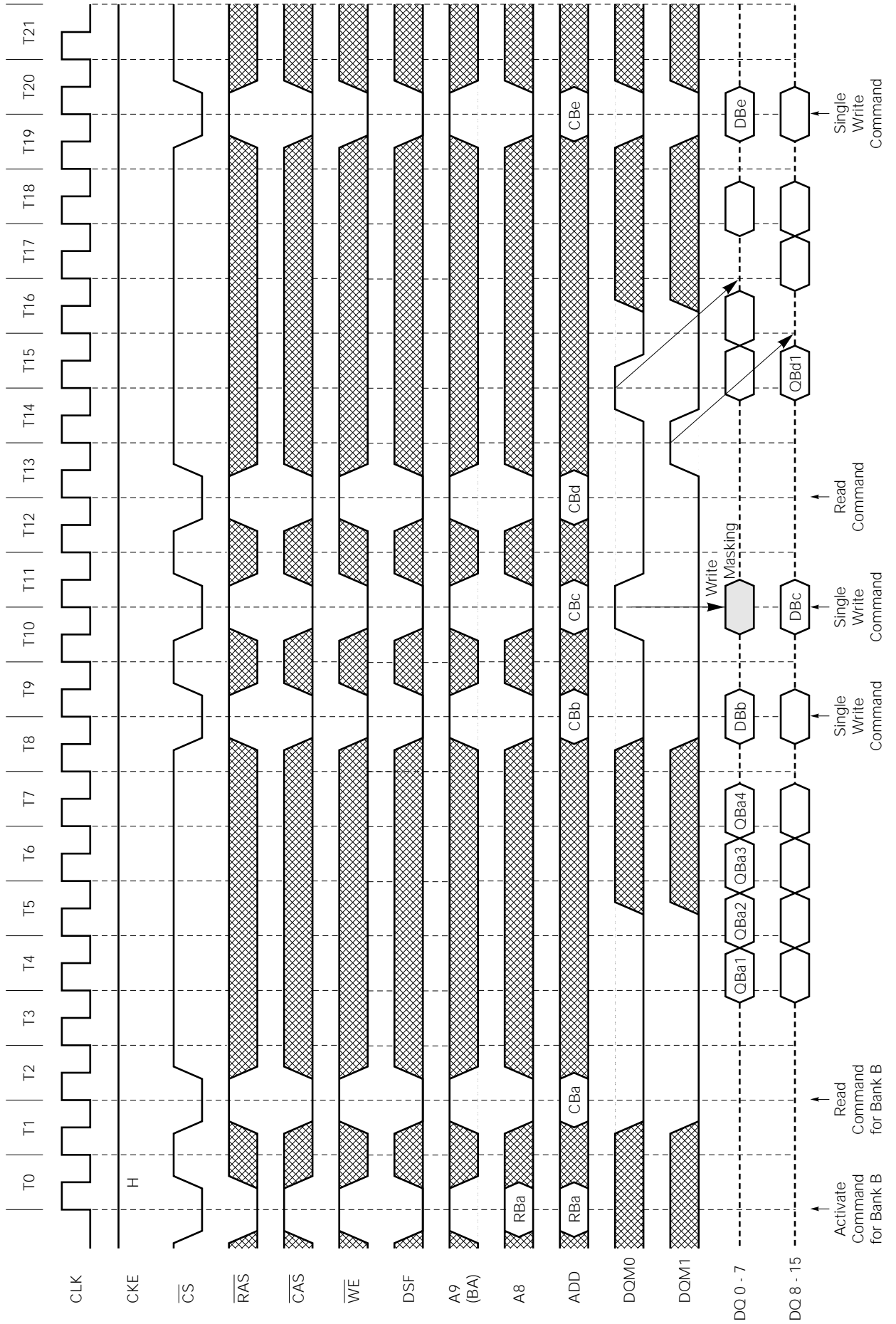


16.4.9 Other Cycles

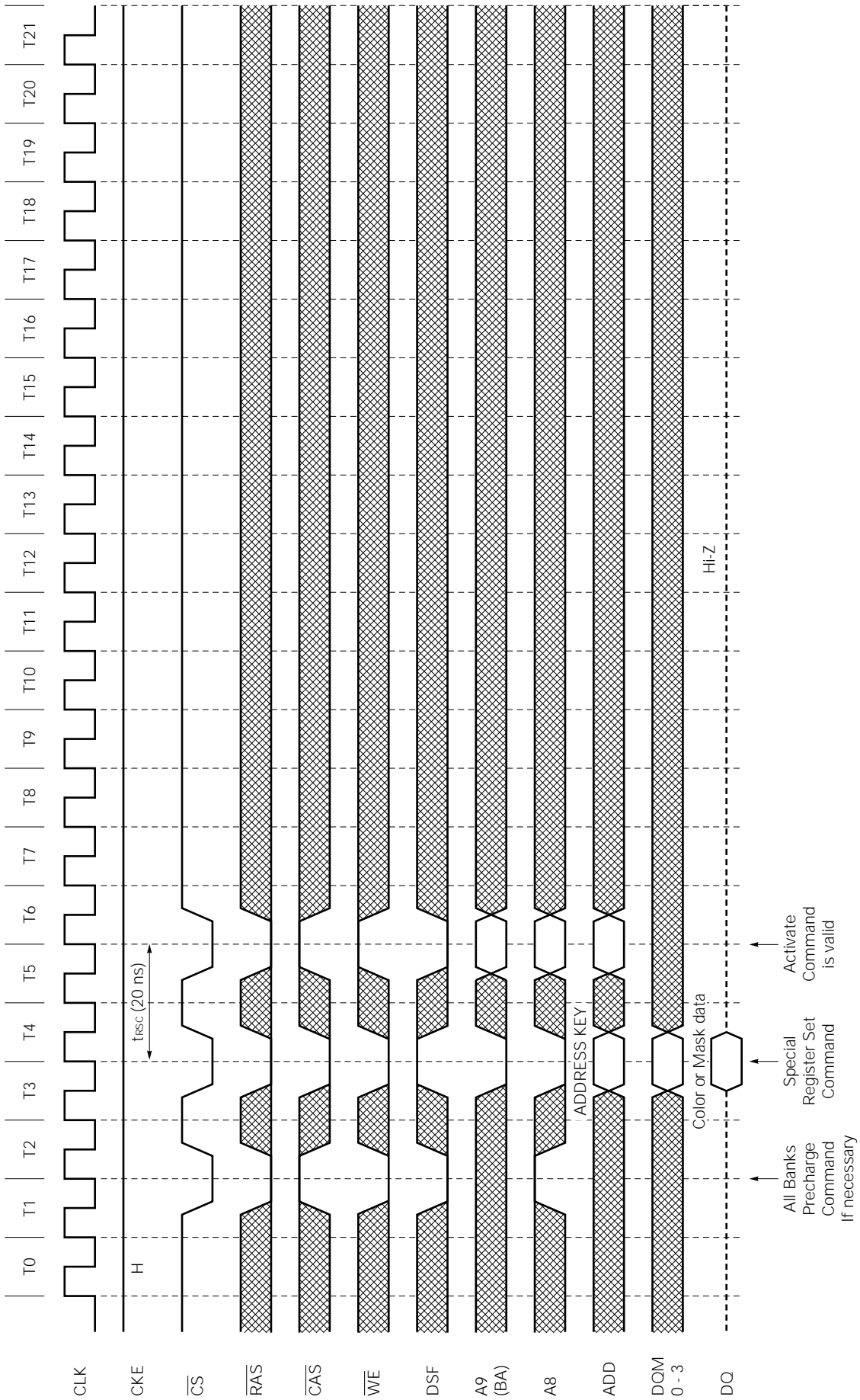
Byte Read/Write Operation (by DQM) (Burst length = 4, CAS latency = 2)



Burst Read and Single Write (Burst length = 4, CAS latency = 2)

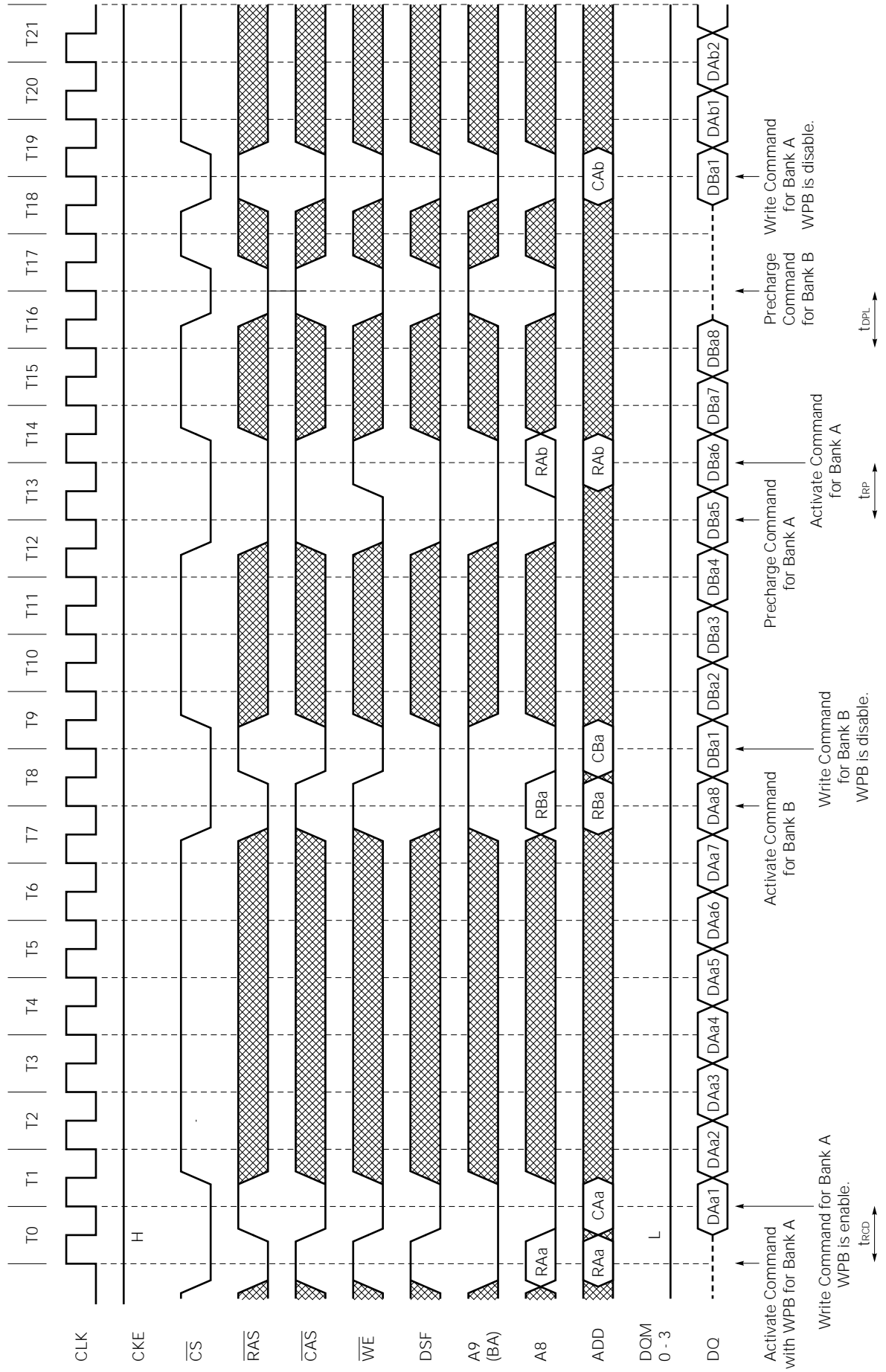


16.5 Graphics Cycles
Special Register Set (Burst length = 4, CAS latency = 2)

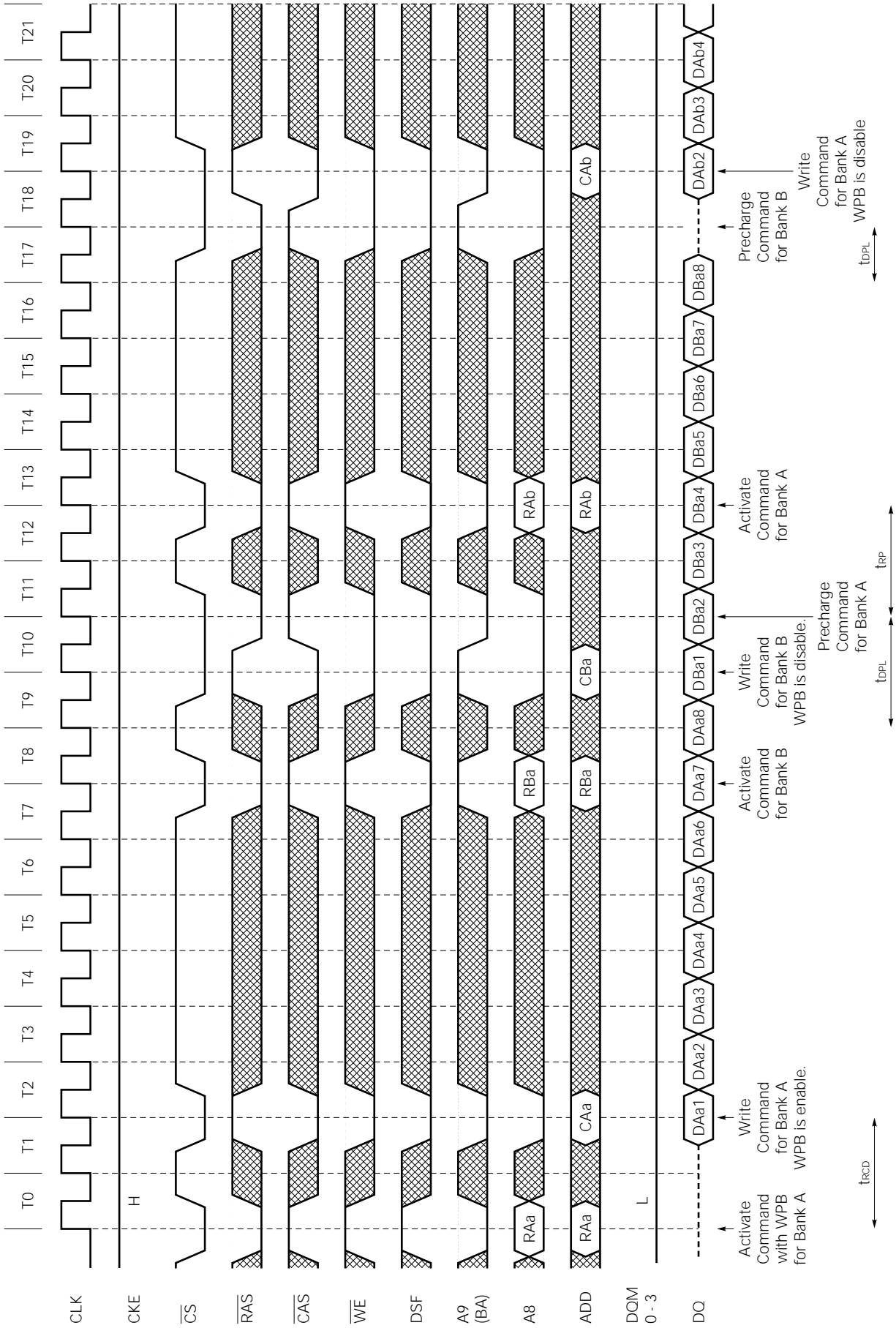


Remark Special Register Set command is able to input at any state.

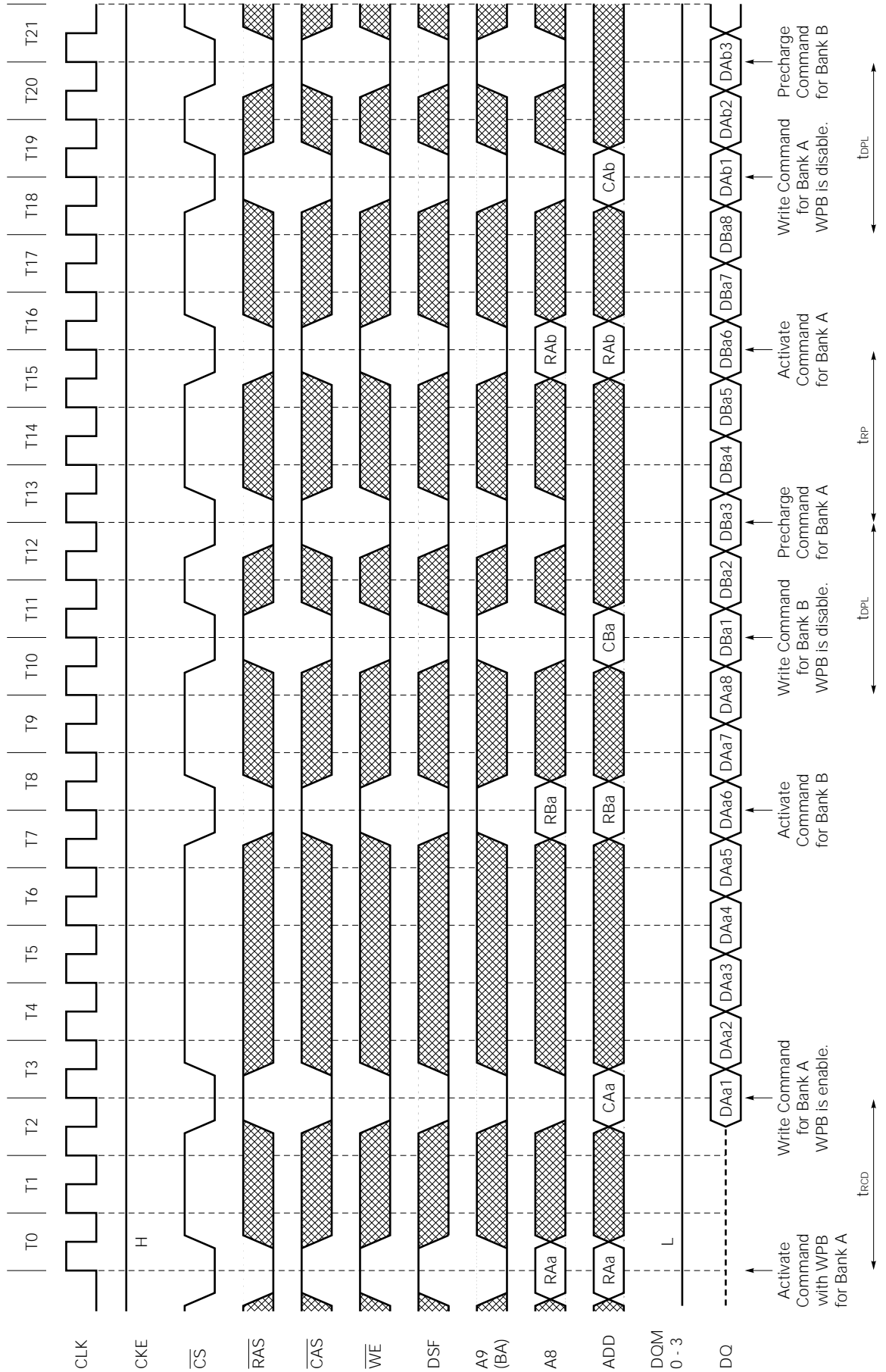
Random Row Write with WPB (Pingpong banks) (1/3) (Burst length = 8, CAS latency = 1)



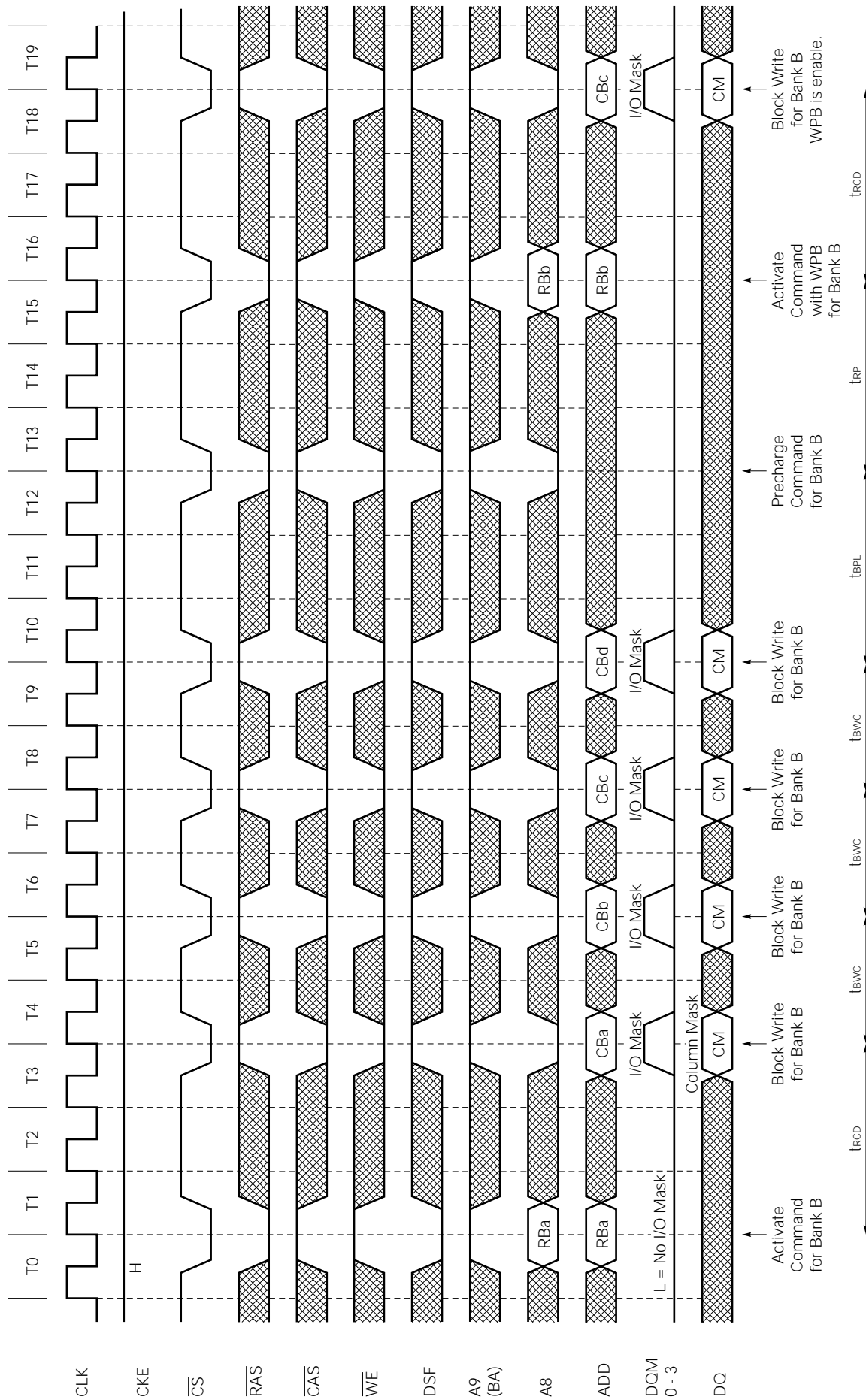
Random Row Write with WPB (Pingpong banks) (2/3) (Burst length = 8, CAS latency = 2)



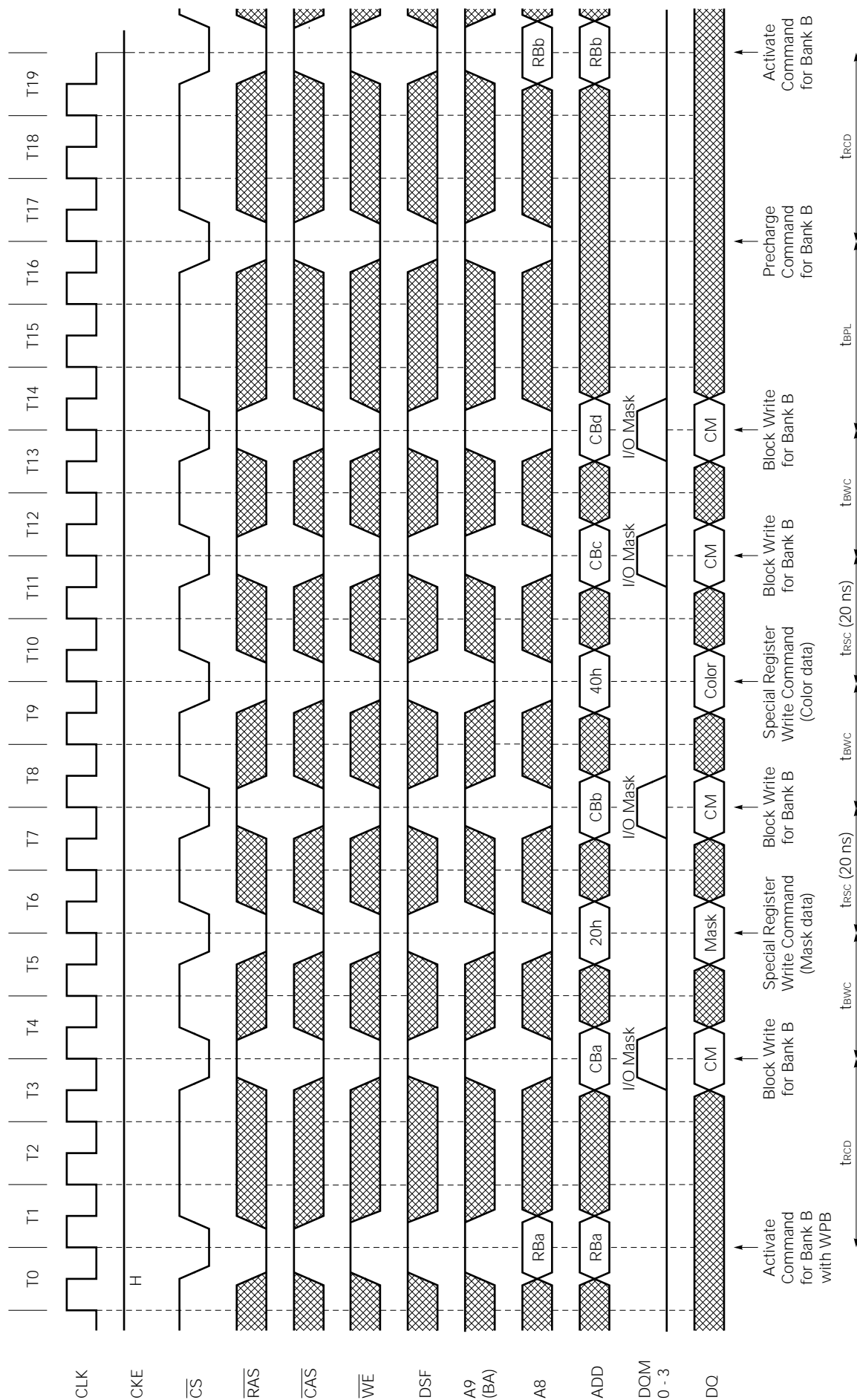
Random Row Write with WPB (Pingpong banks) (3/3) (Burst length = 8, CAS latency = 3)



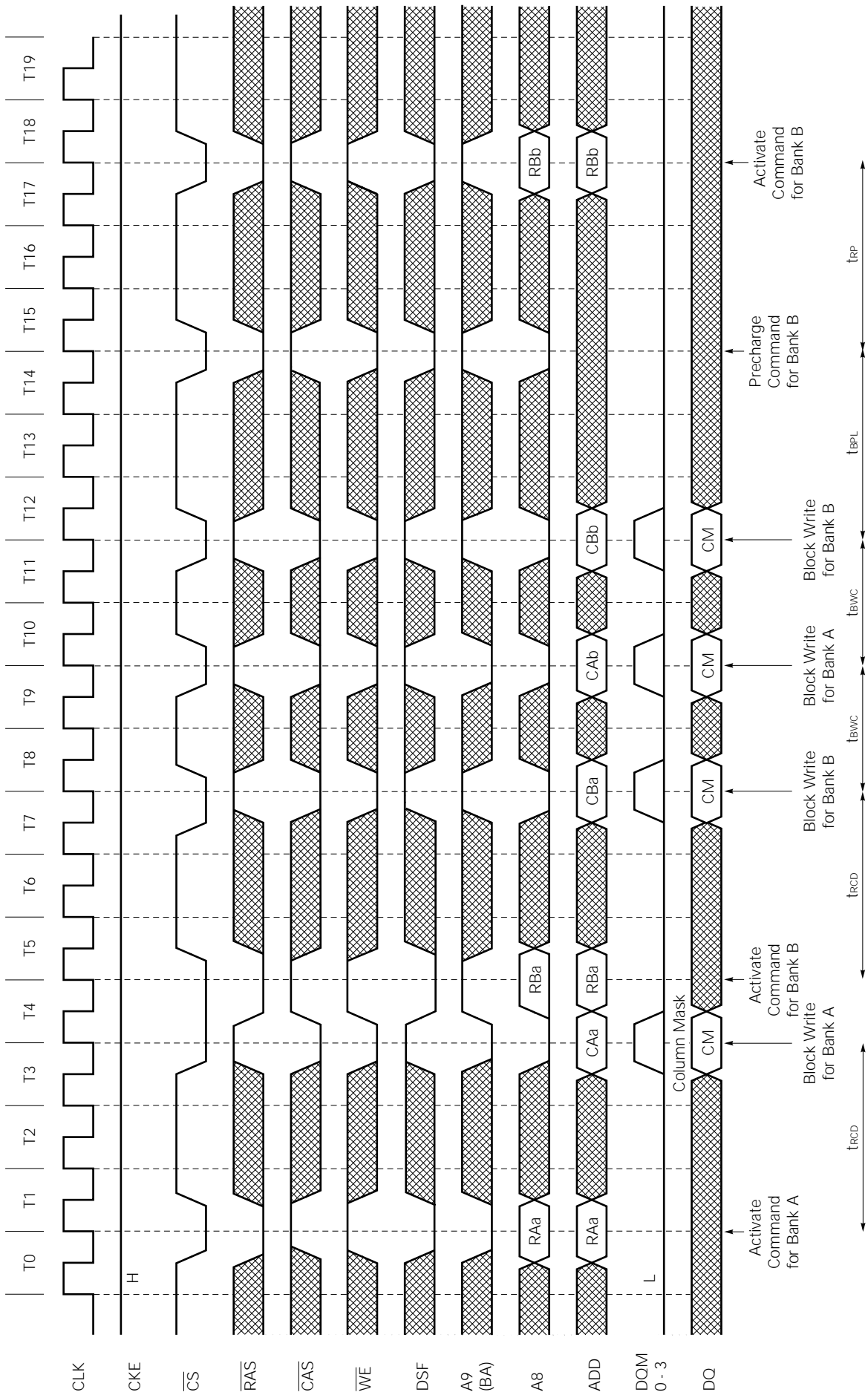
Block Write (page at same bank) ($\overline{\text{CAS}}$ latency = 3)



Block Write (page at same bank) changing color and mask data (CAS latency = 3)

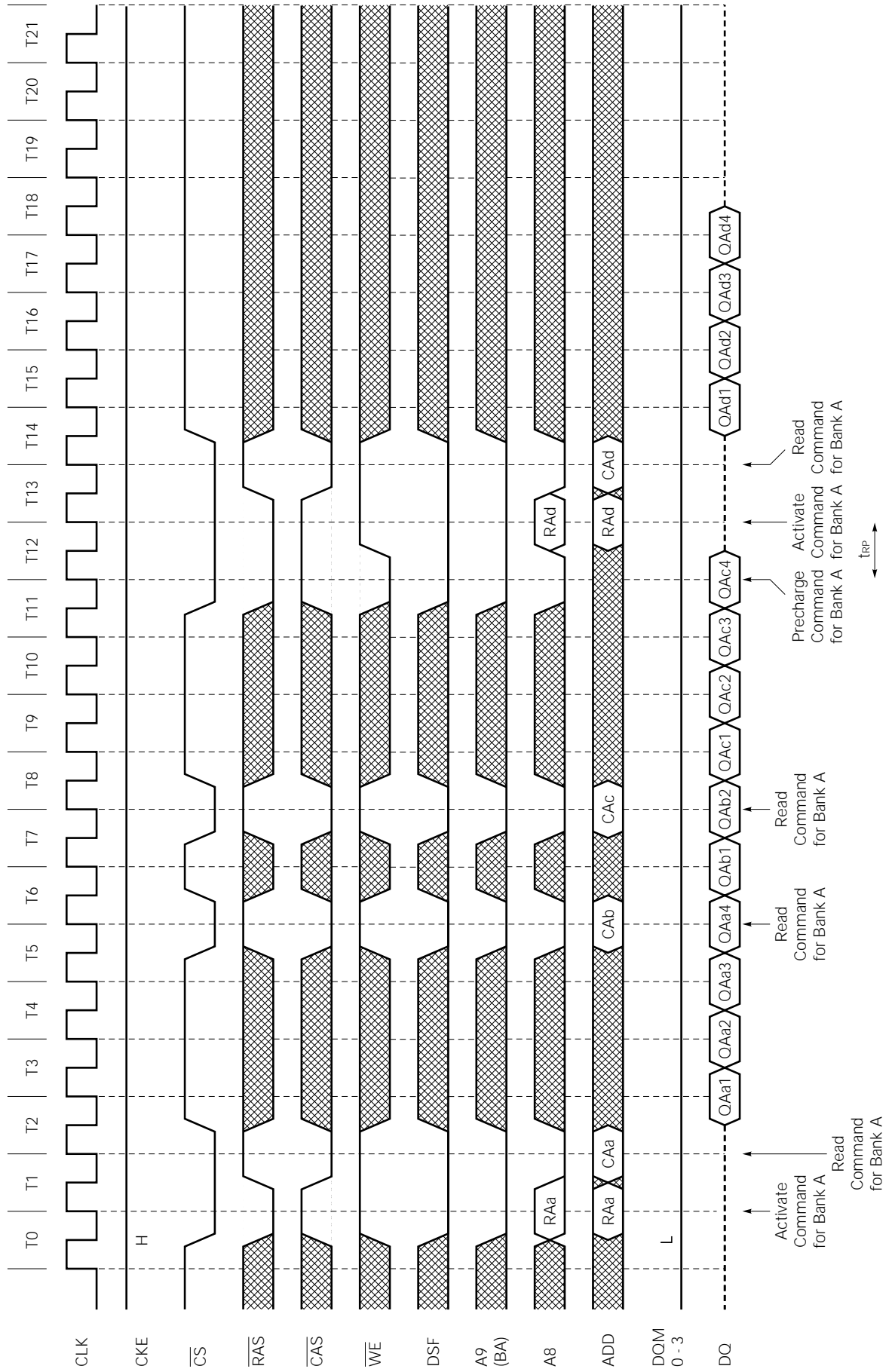


Interleaved Block Write (CAS latency = 3)

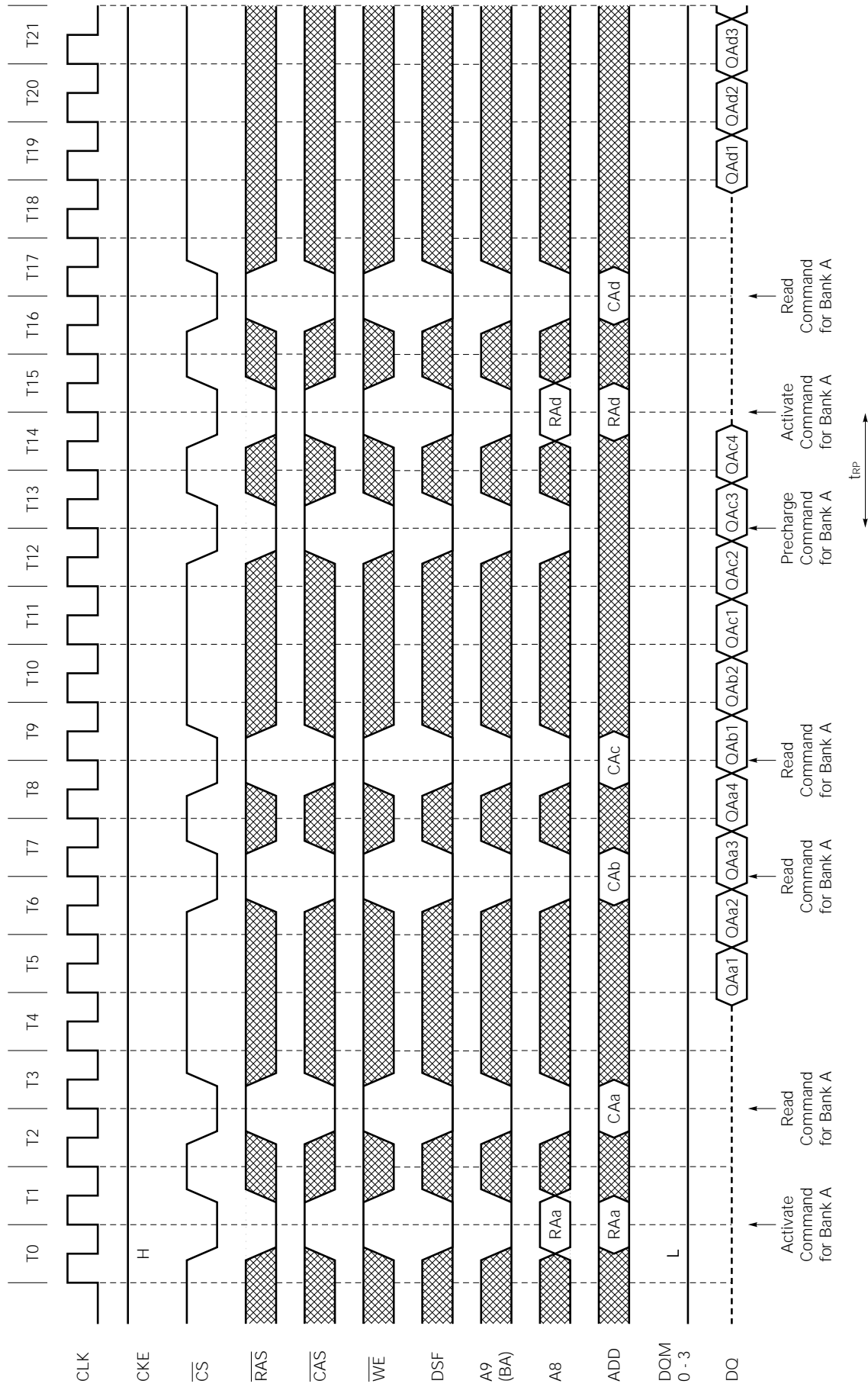


16.6 Application Cycles
 16.6.1 Page Cycles with Same Bank

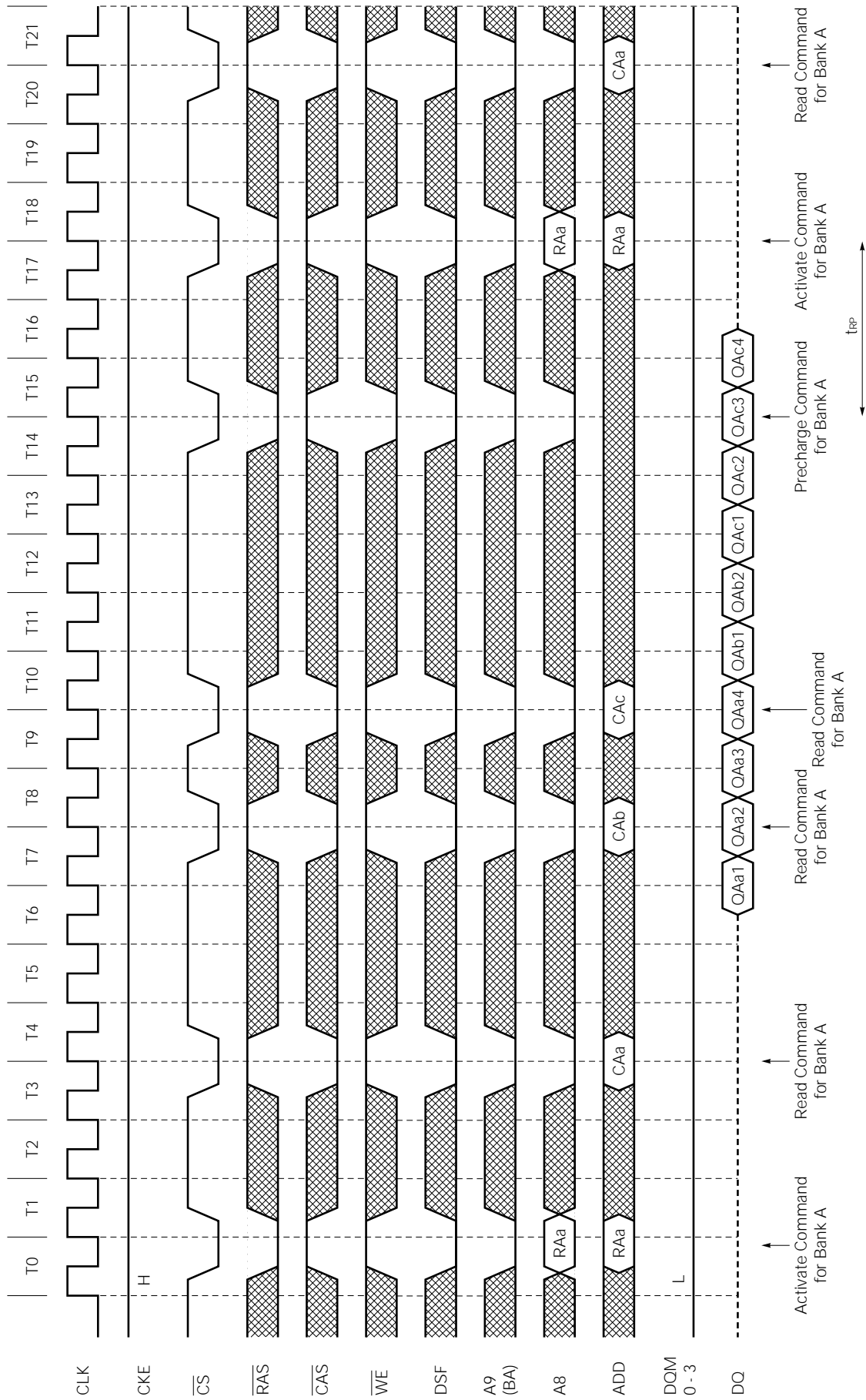
Random Column Read (Page with same bank) (1/3) (Burst length = 4, CAS latency = 1)



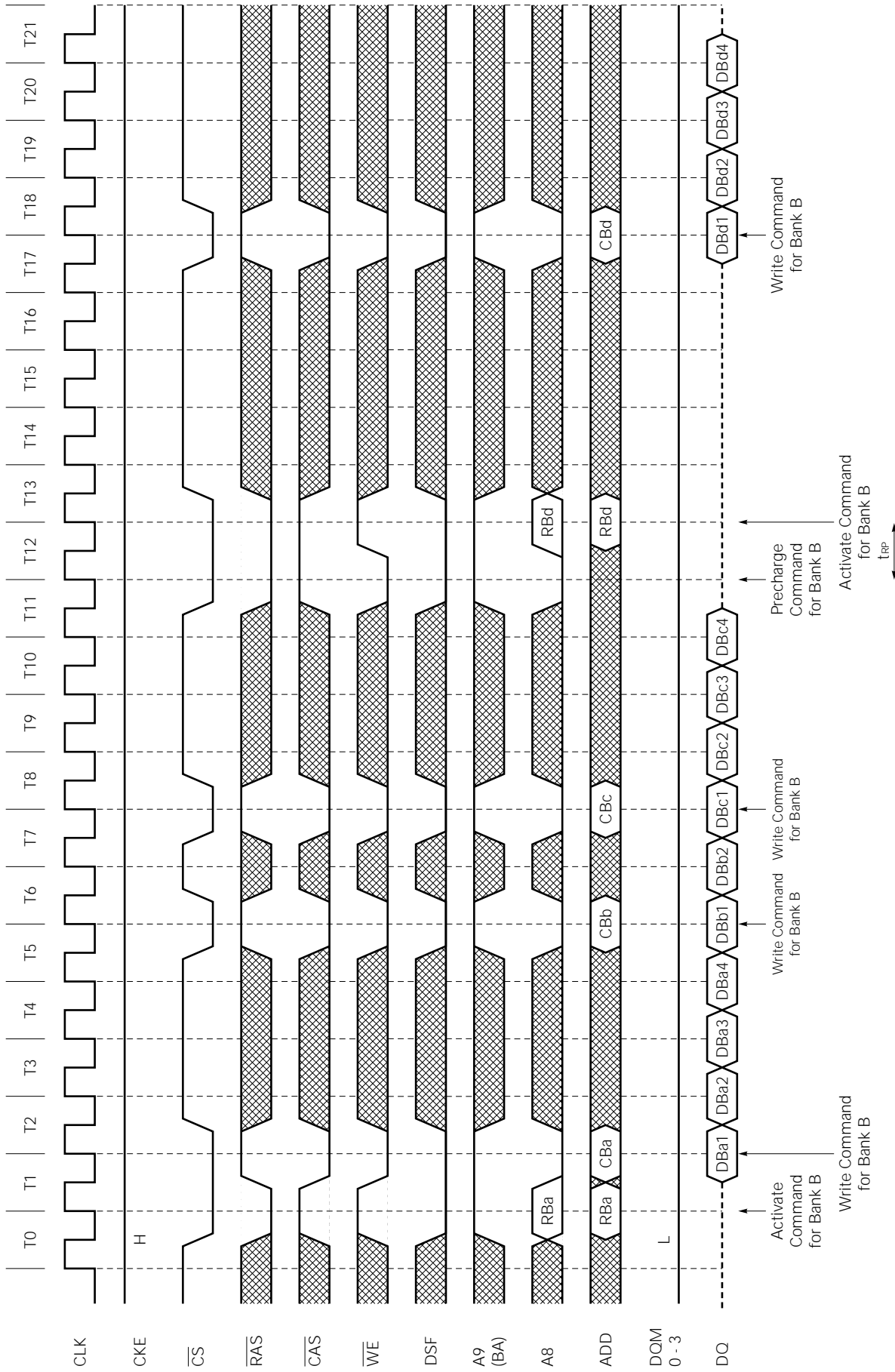
Random Column Read (Page with same bank) (2/3) (Burst length = 4, CAS latency = 2)



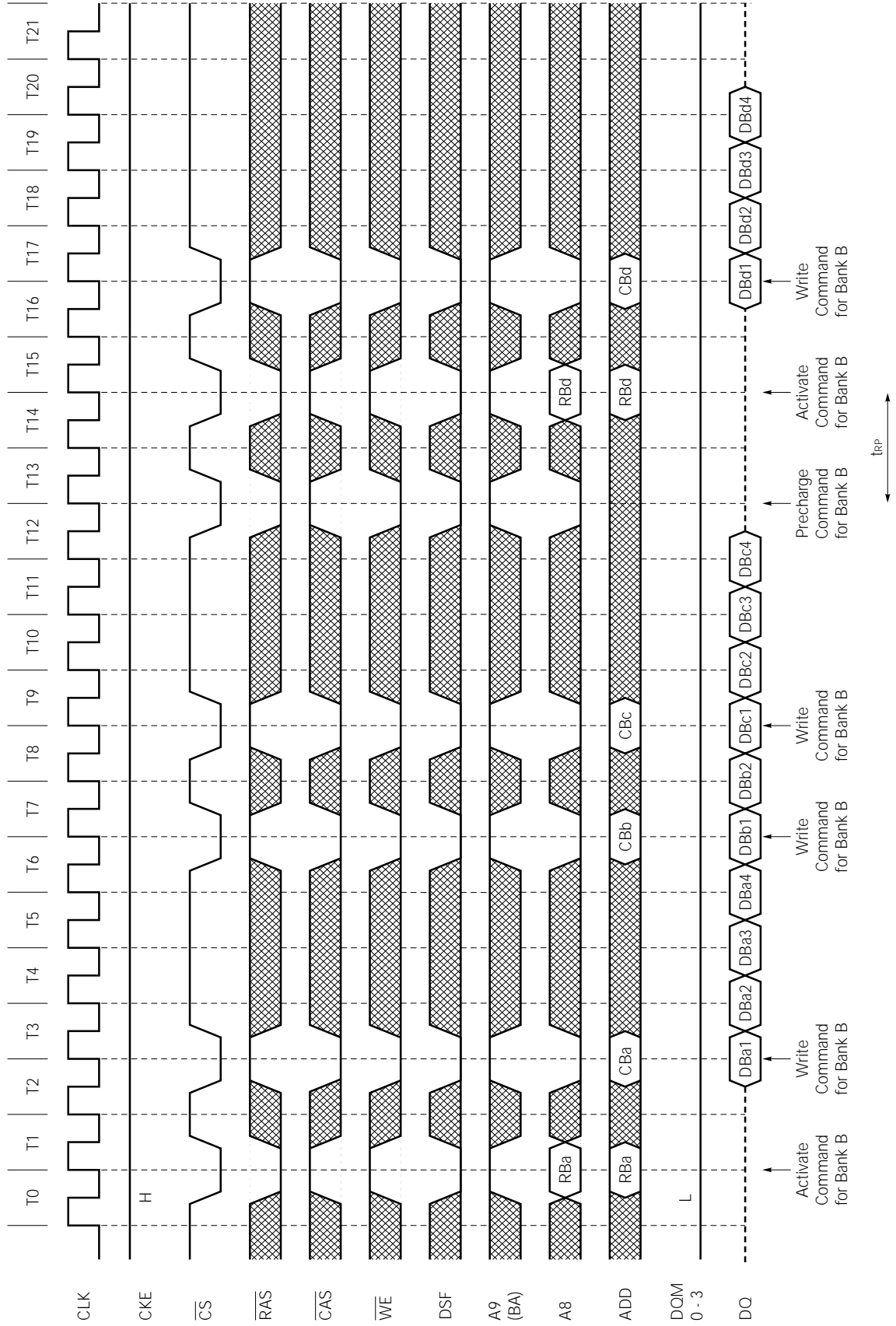
Random Column Read (Page with same bank) (3/3) (Burst length = 4, CAS latency = 3)



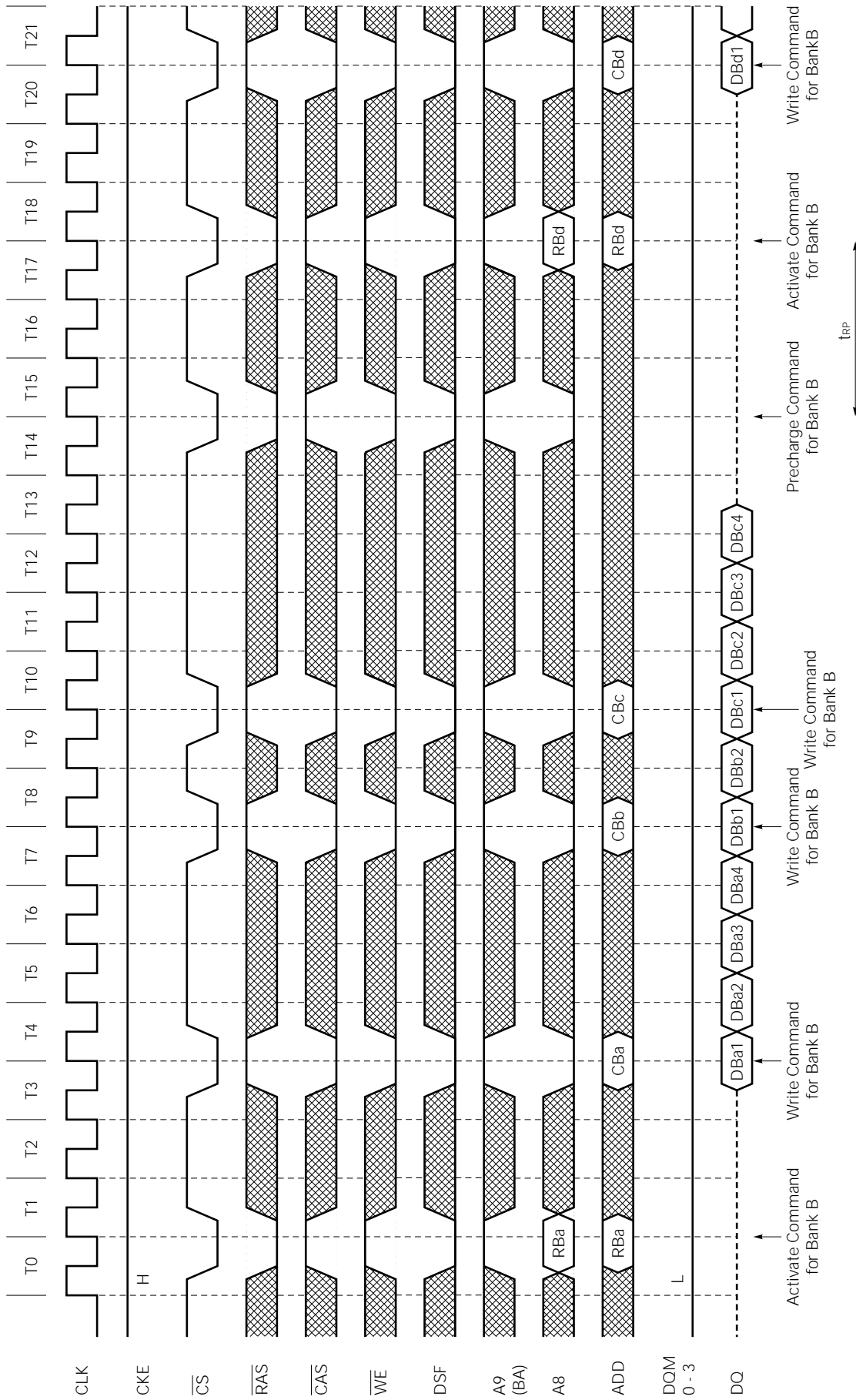
Random Column Write (Page with same bank) (1/3) (Burst length = 4, CAS latency = 1)



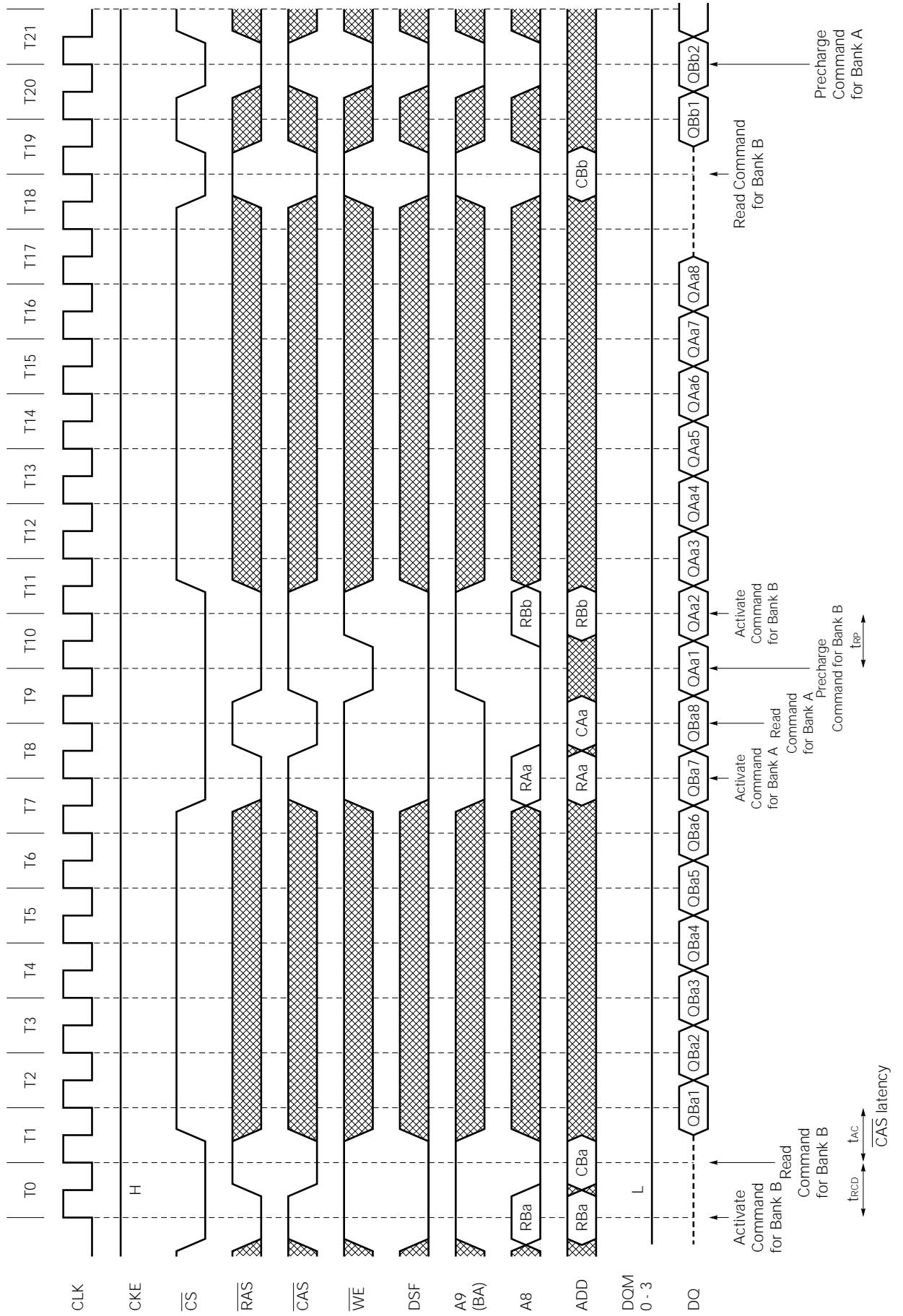
Random Column Write (Page with same bank) (2/3) (Burst length = 4, CAS latency = 2)



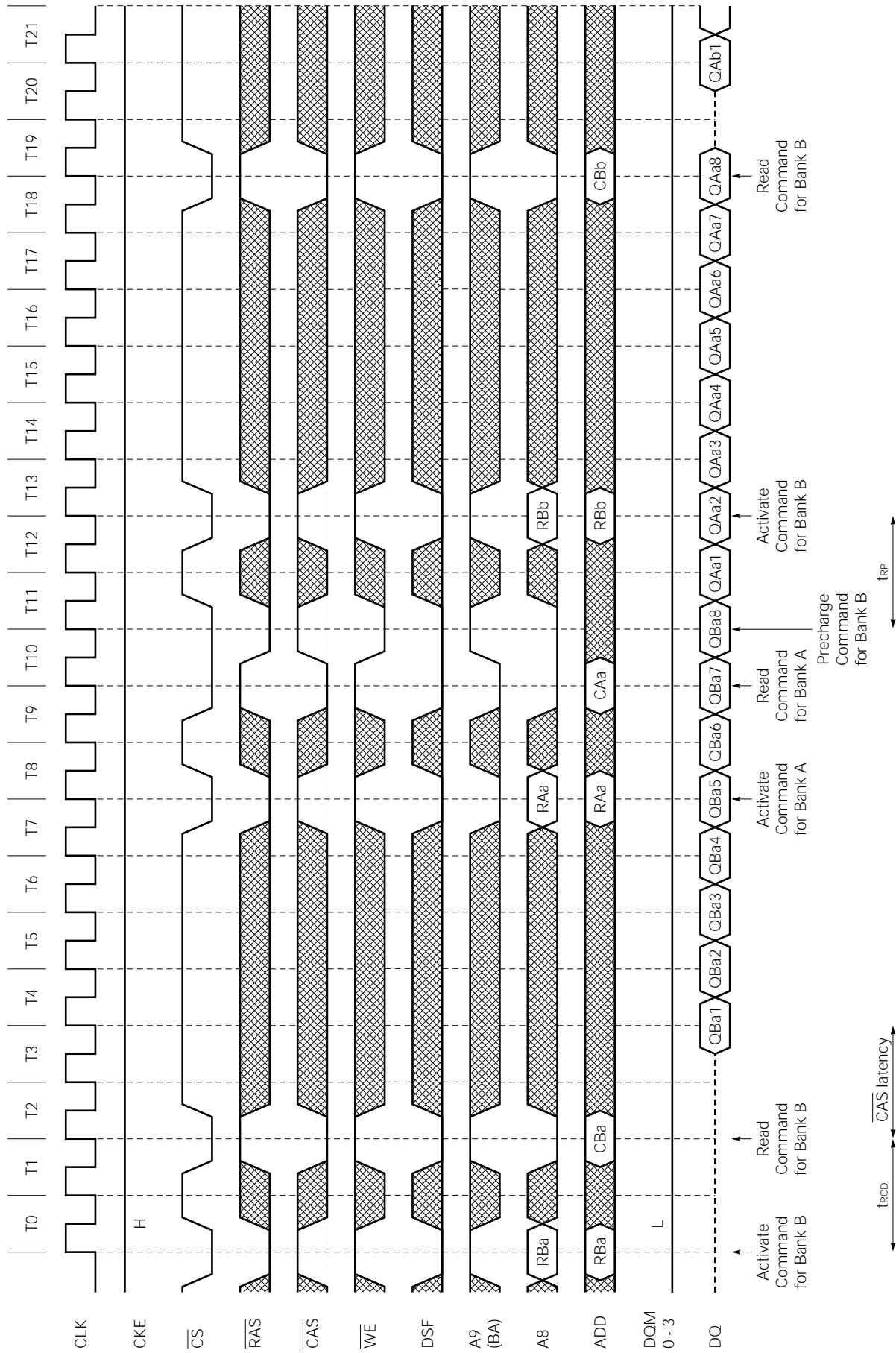
Random Column Write (Page with same bank) (3/3) (Burst length = 4, CAS latency = 3)



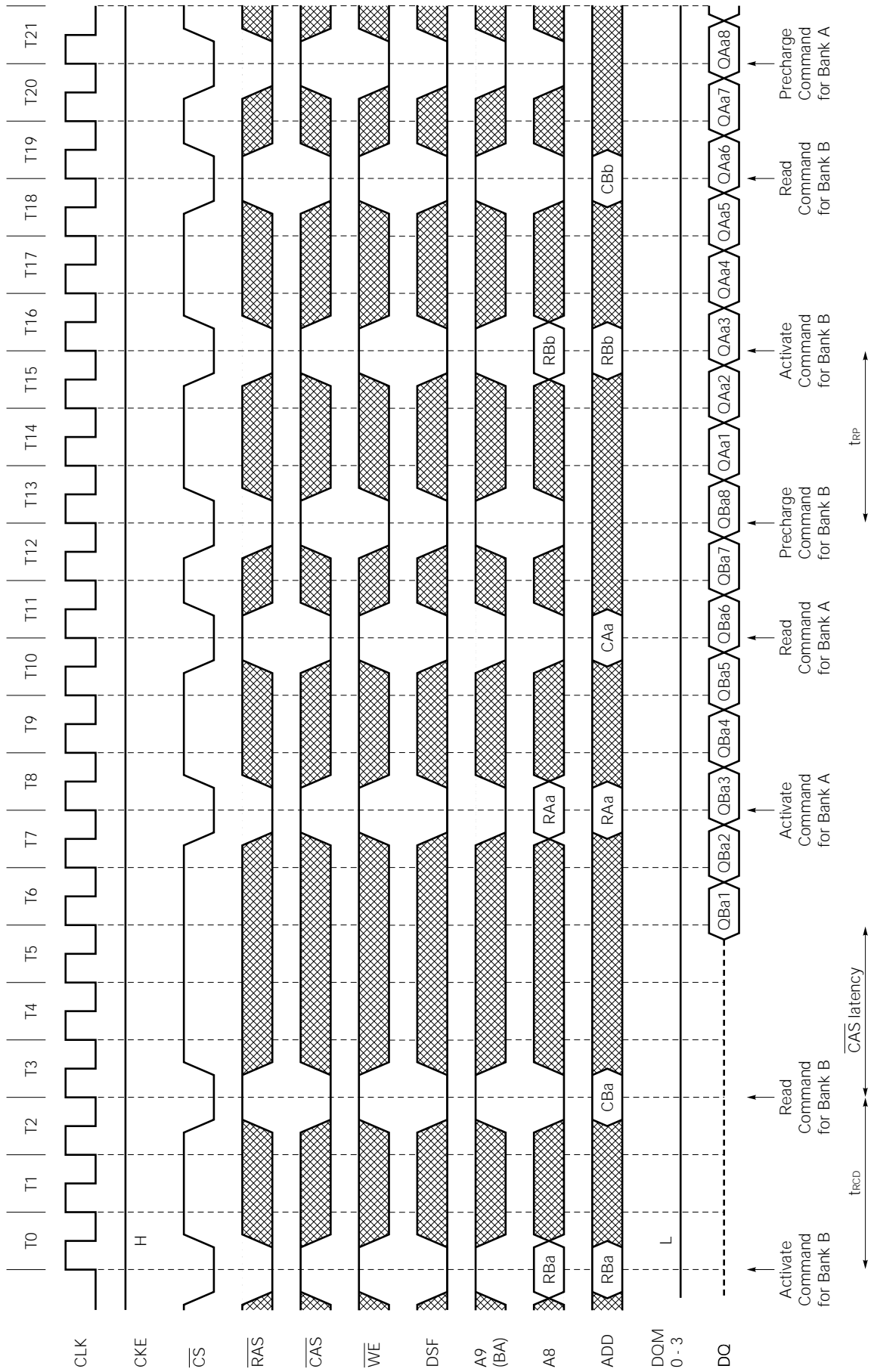
16.6.2 Cycles with Pingpong Banks
 Random Row Read (Pingpong banks) (1/3) (Burst length = 8, CAS latency = 1)



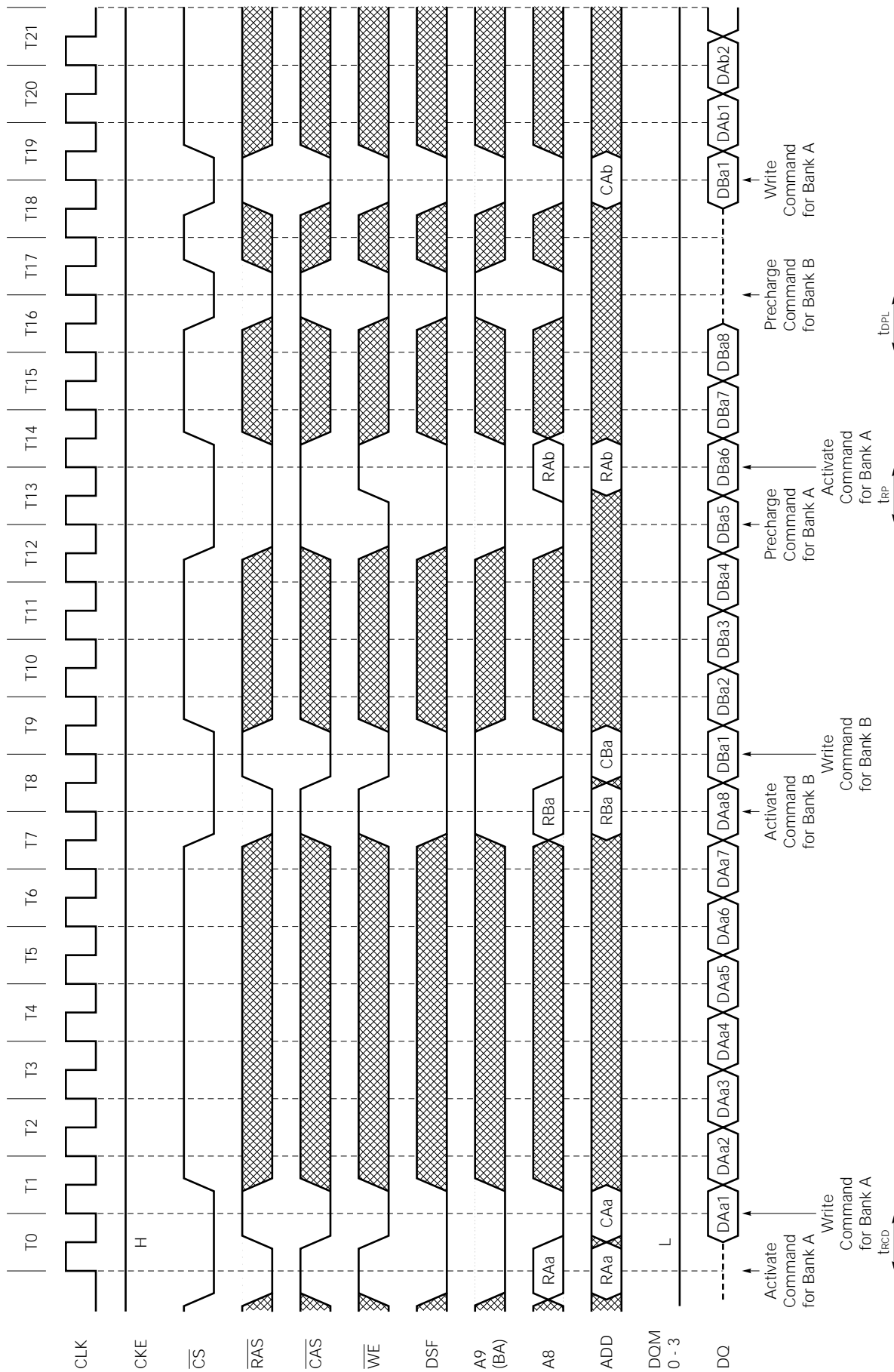
Random Row Read (Pingpong banks) (2/3) (Burst length = 8, CAS latency = 2)



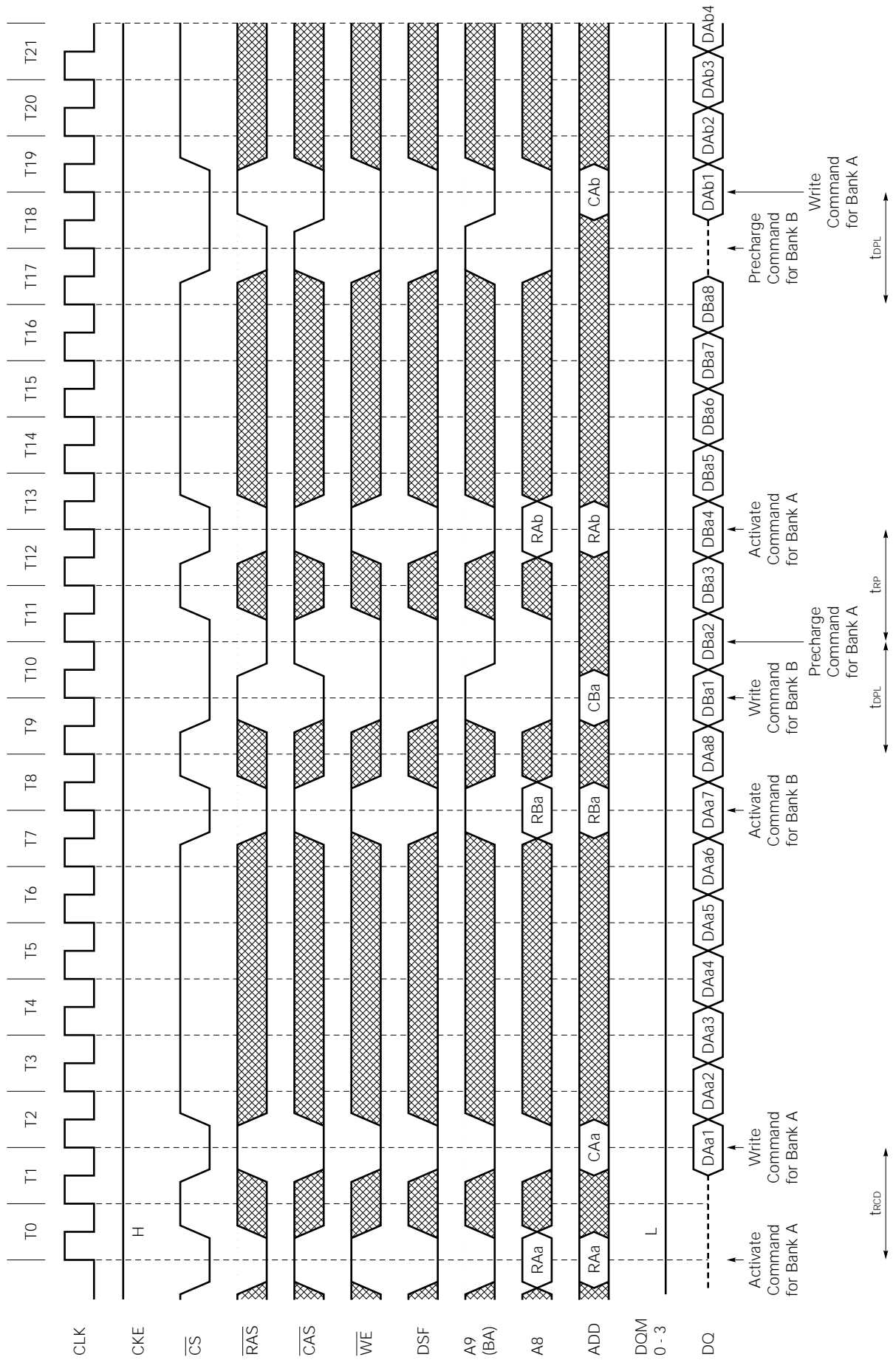
Random Row Read (Pingpong banks) (3/3) (Burst length = 8, CAS latency = 3)



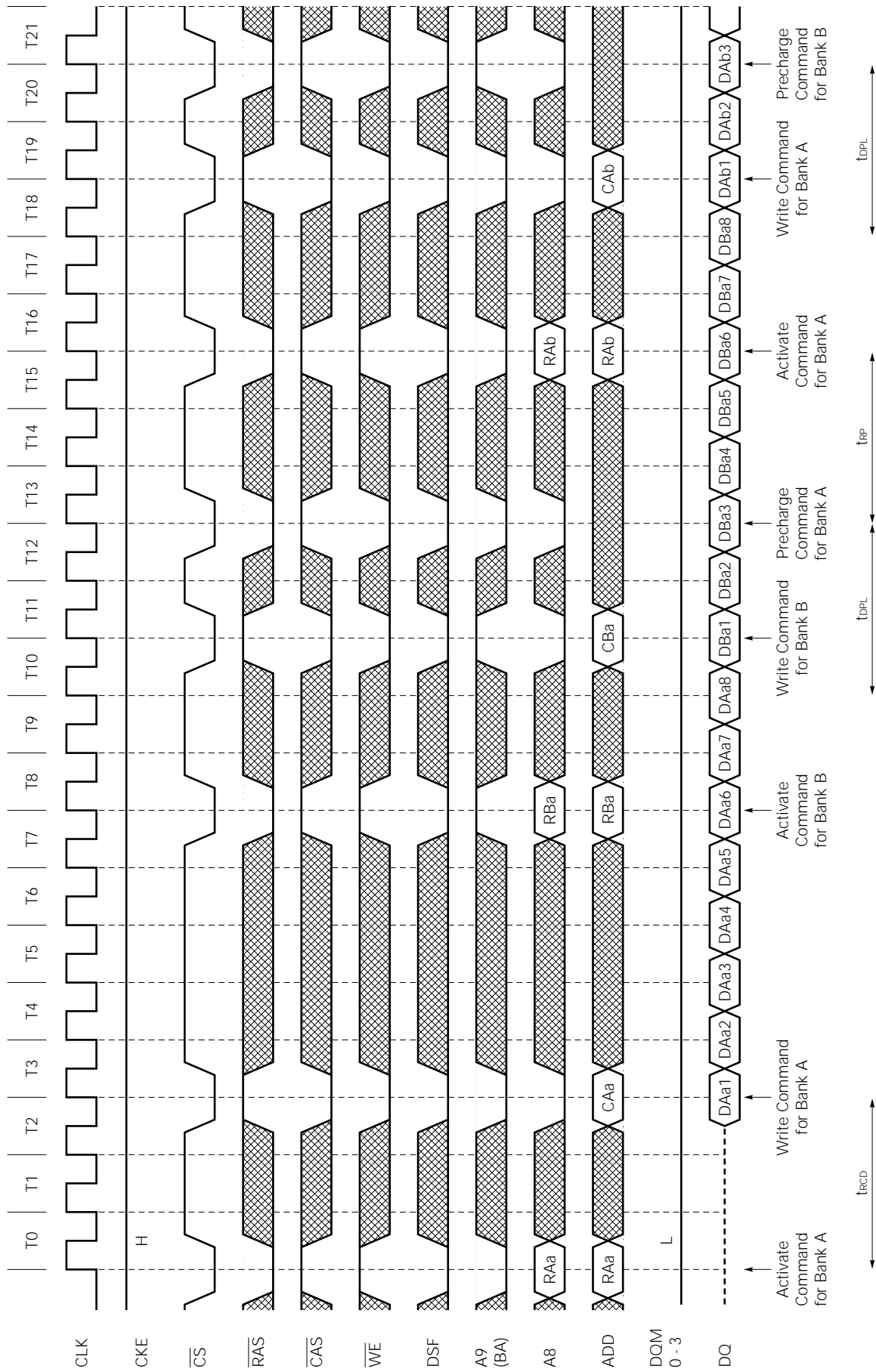
Random Row Write (Pingpong banks) (1/3) (Burst length = 8, CAS latency = 1)



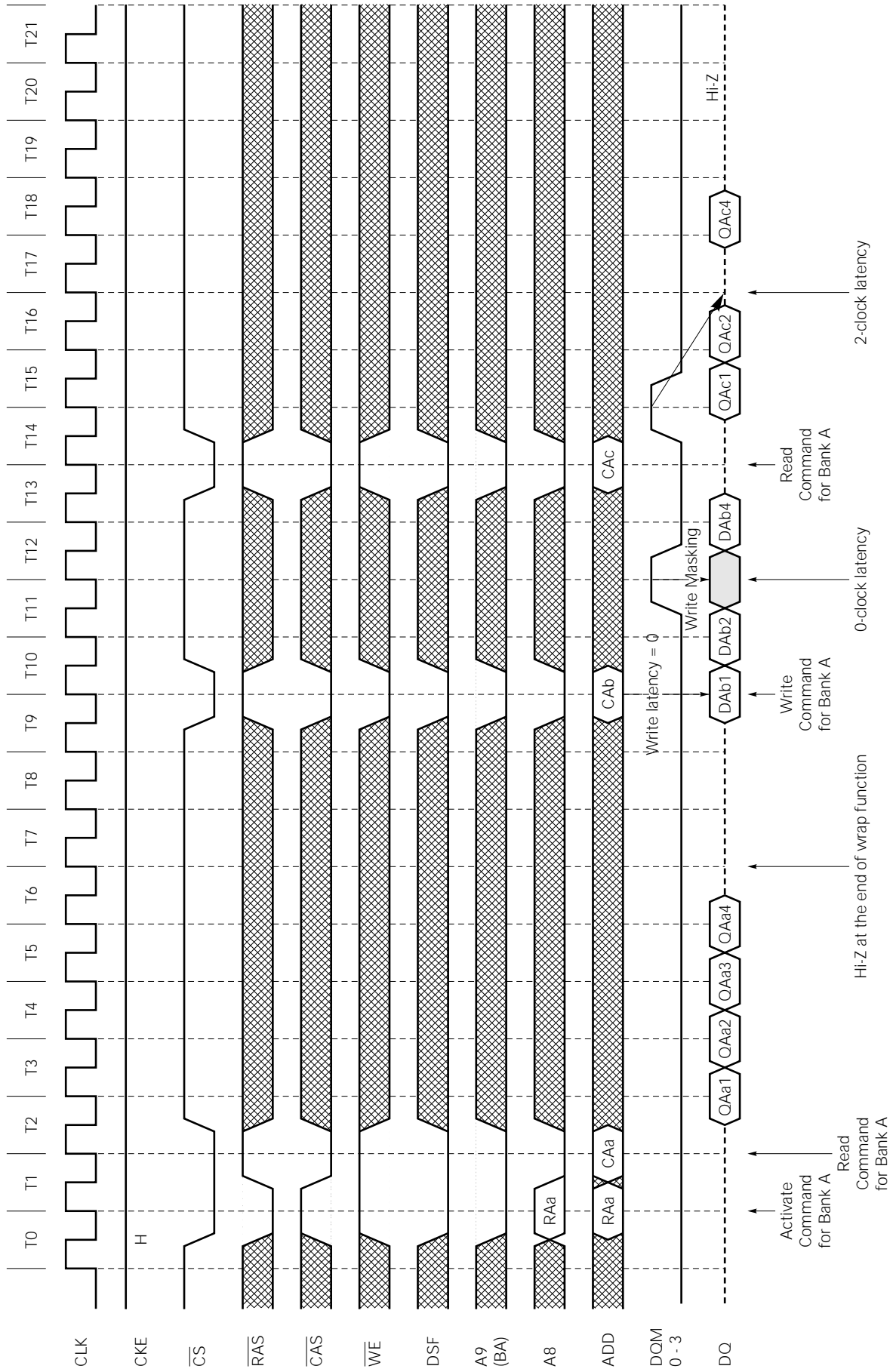
Random Row Write (Pingpong banks) (2/3) (Burst length = 8, CAS latency = 2)



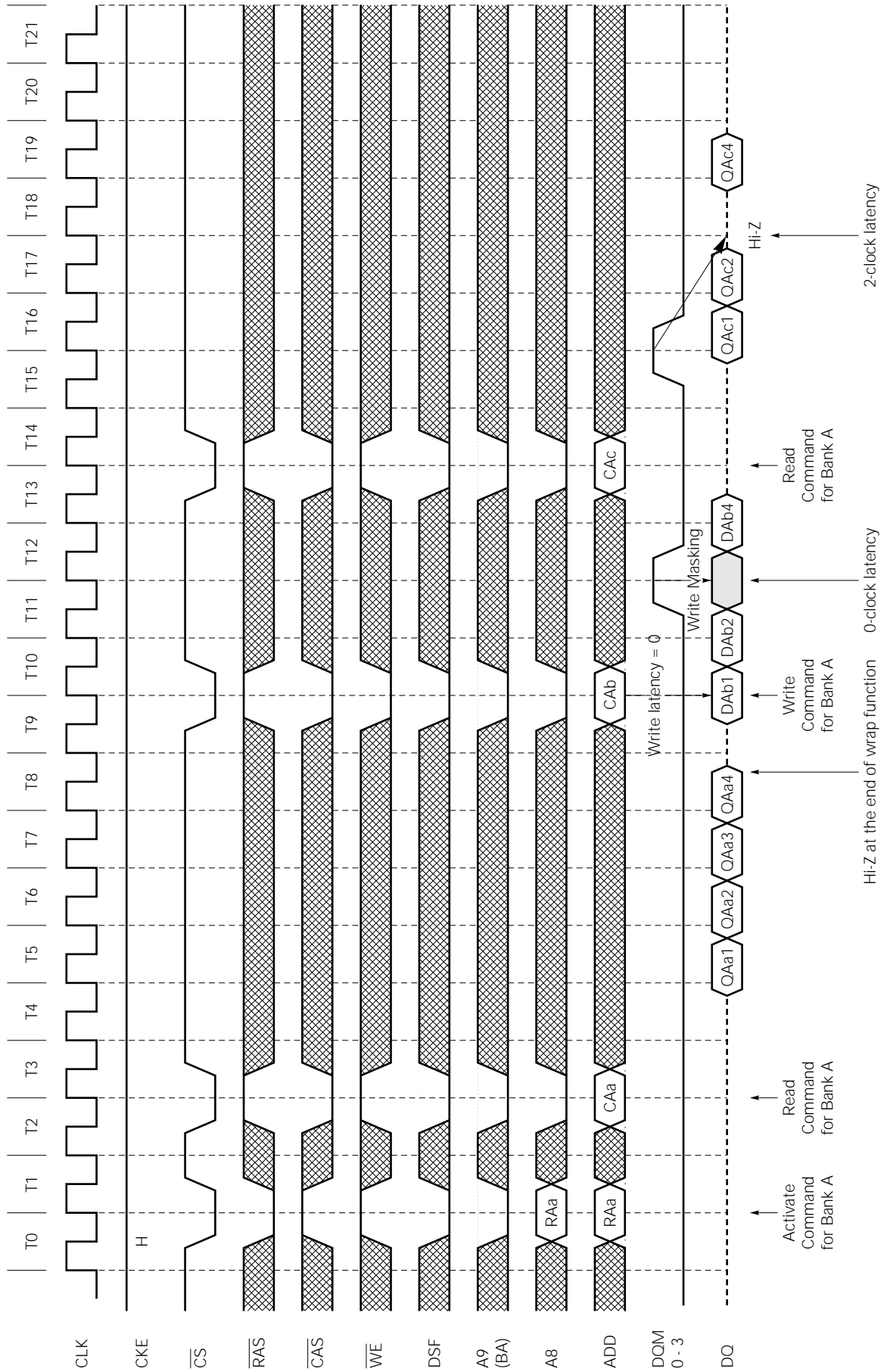
Random Row Write (Pingpong banks) (3/3) (Burst length = 8, CAS latency = 3)



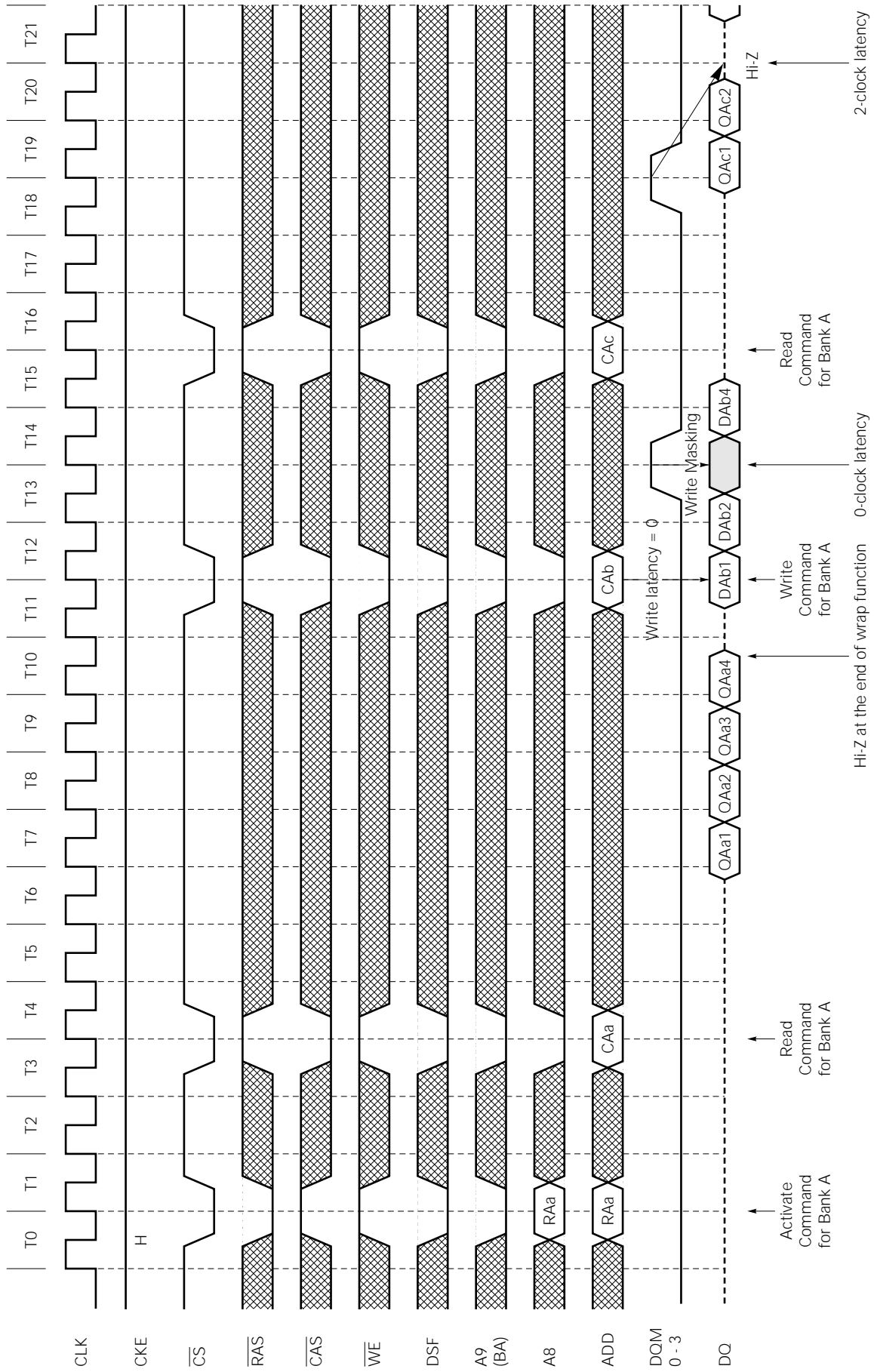
16.6.3 READ and WRITE Cycles
 READ and WRITE (1/3) (Burst length = 4, CAS latency = 1)



READ and WRITE (2/3) (Burst length = 4, CAS latency = 2)

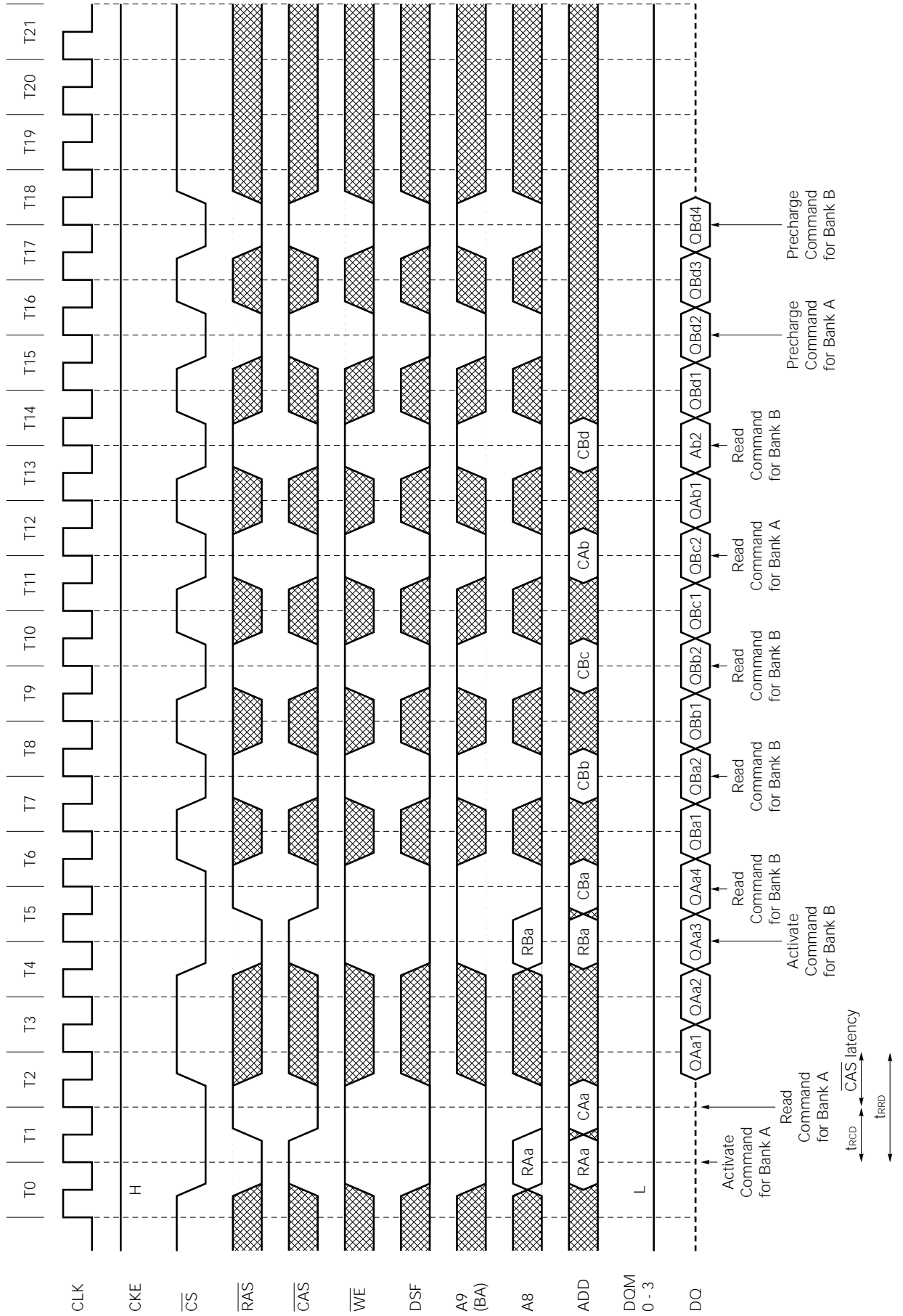


READ and WRITE (3/3) (Burst length = 4, CAS latency = 3)

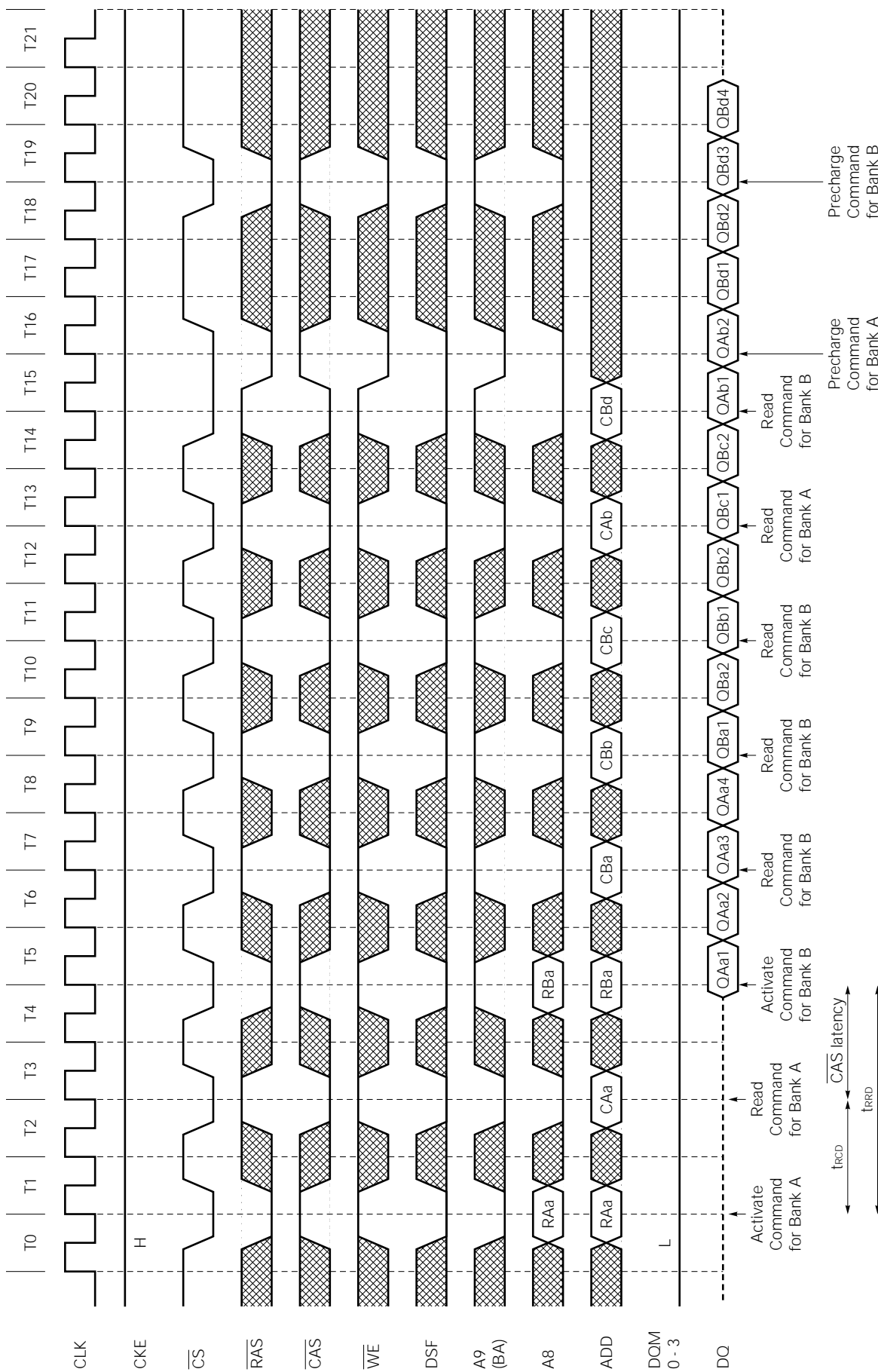


16.6.4 Interleaved Cycles

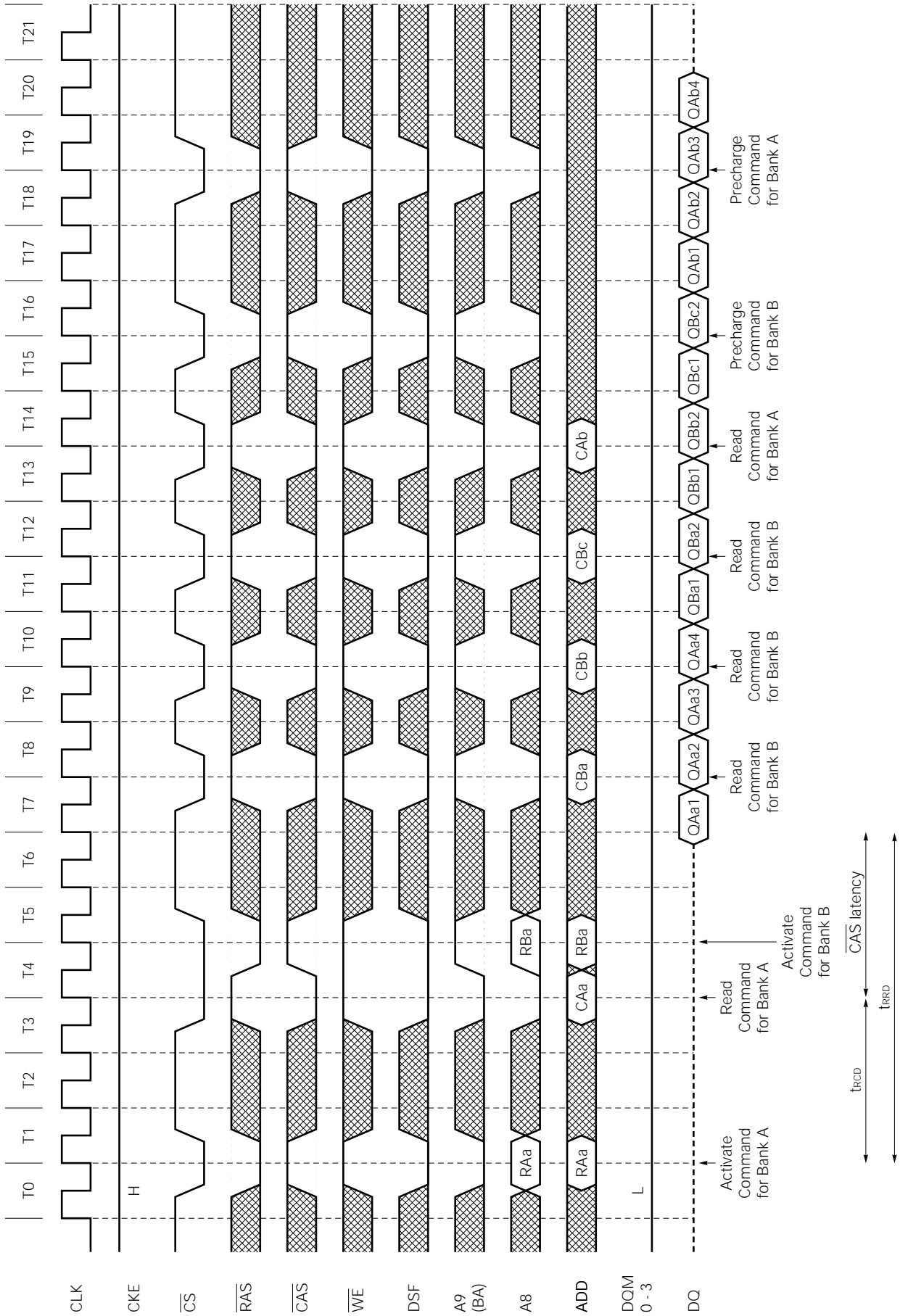
Interleaved Column READ Cycle (1/3) (Burst length = 4, CAS latency = 1)



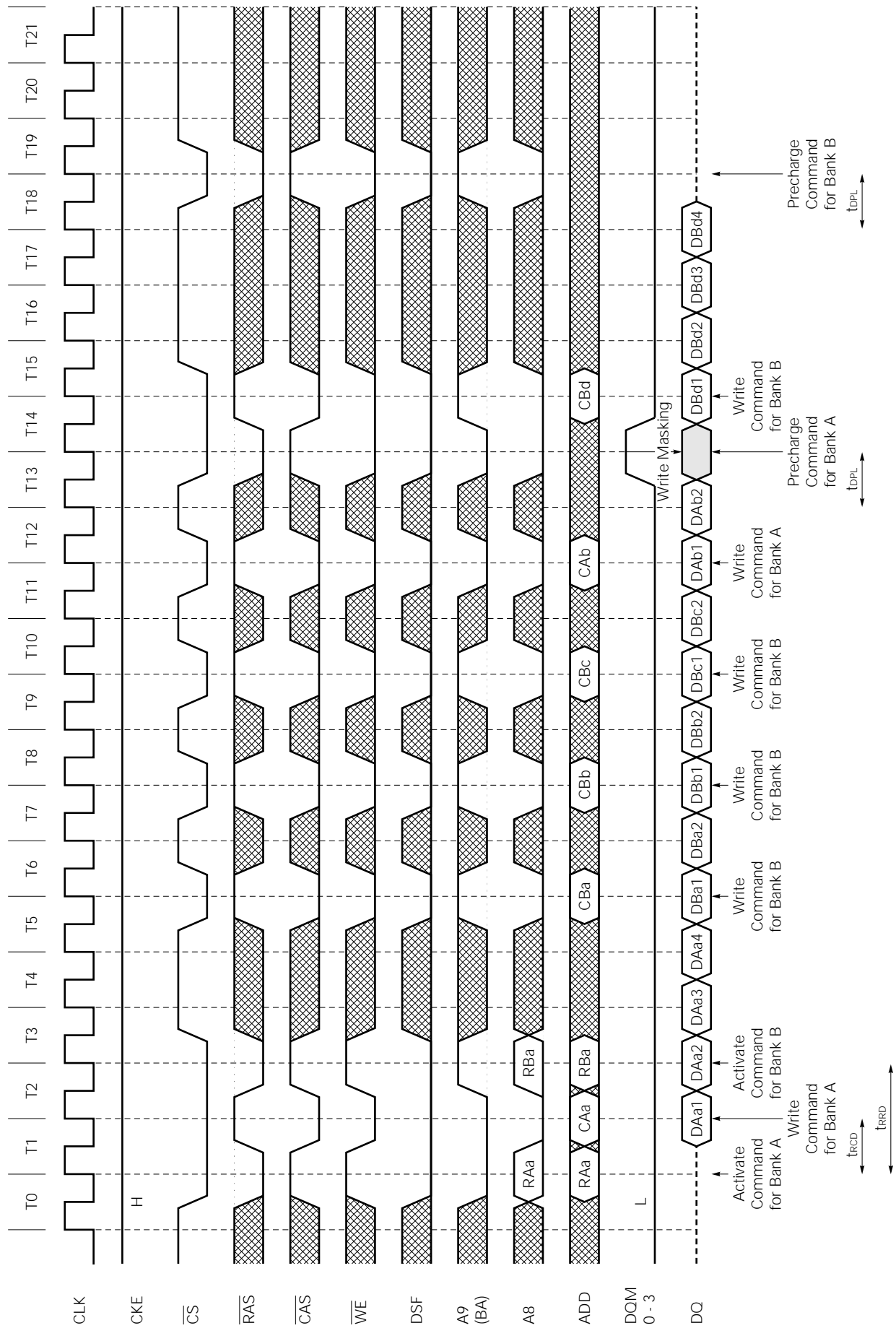
Interleaved Column READ Cycle (2/3) (Burst length = 4, CAS latency = 2)



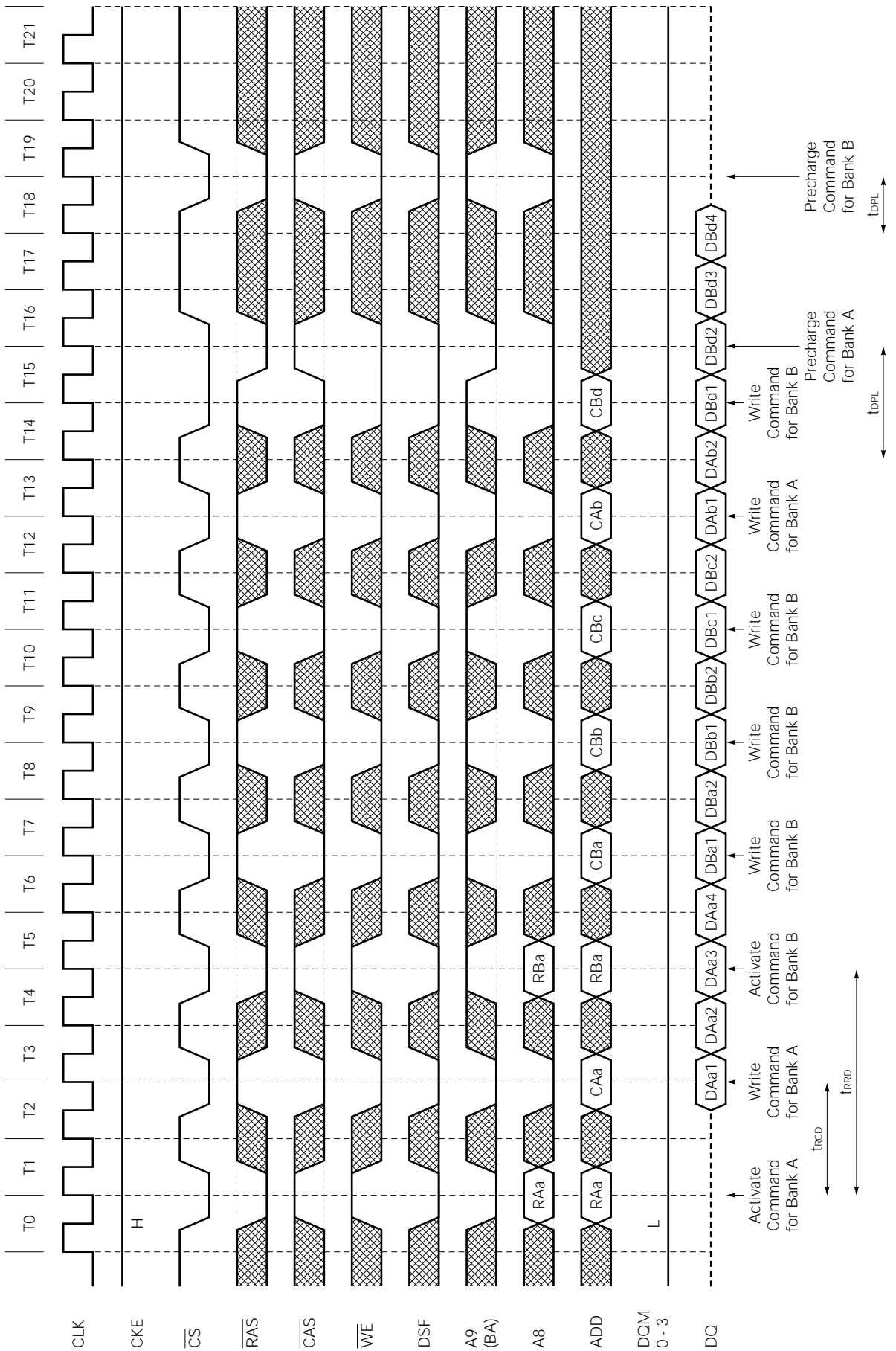
Interleaved Column READ Cycle (3/3) (Burst length = 4, CAS latency = 3)



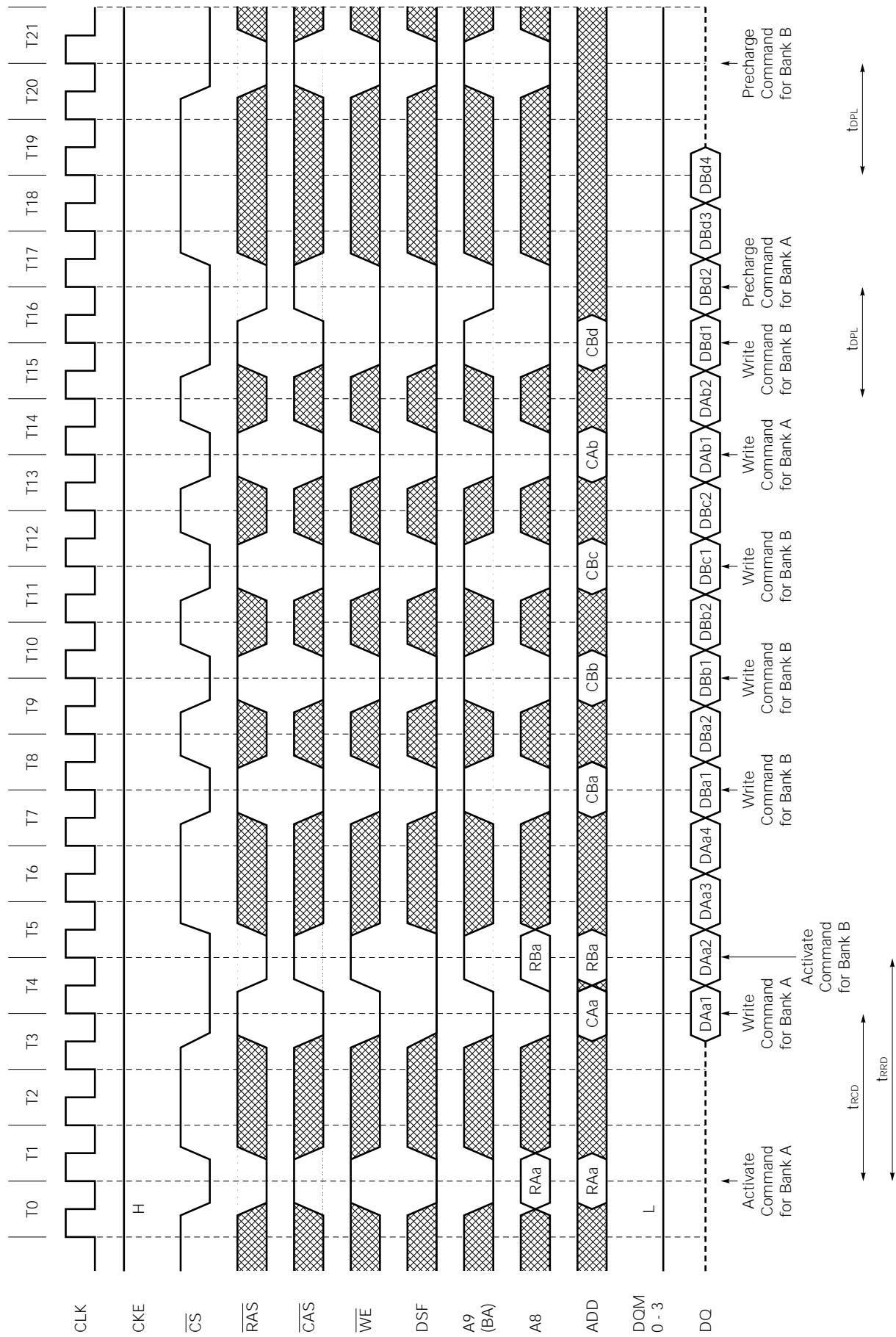
Interleaved Column WRITE Cycle (1/3) (Burst length = 4, CAS latency = 1)



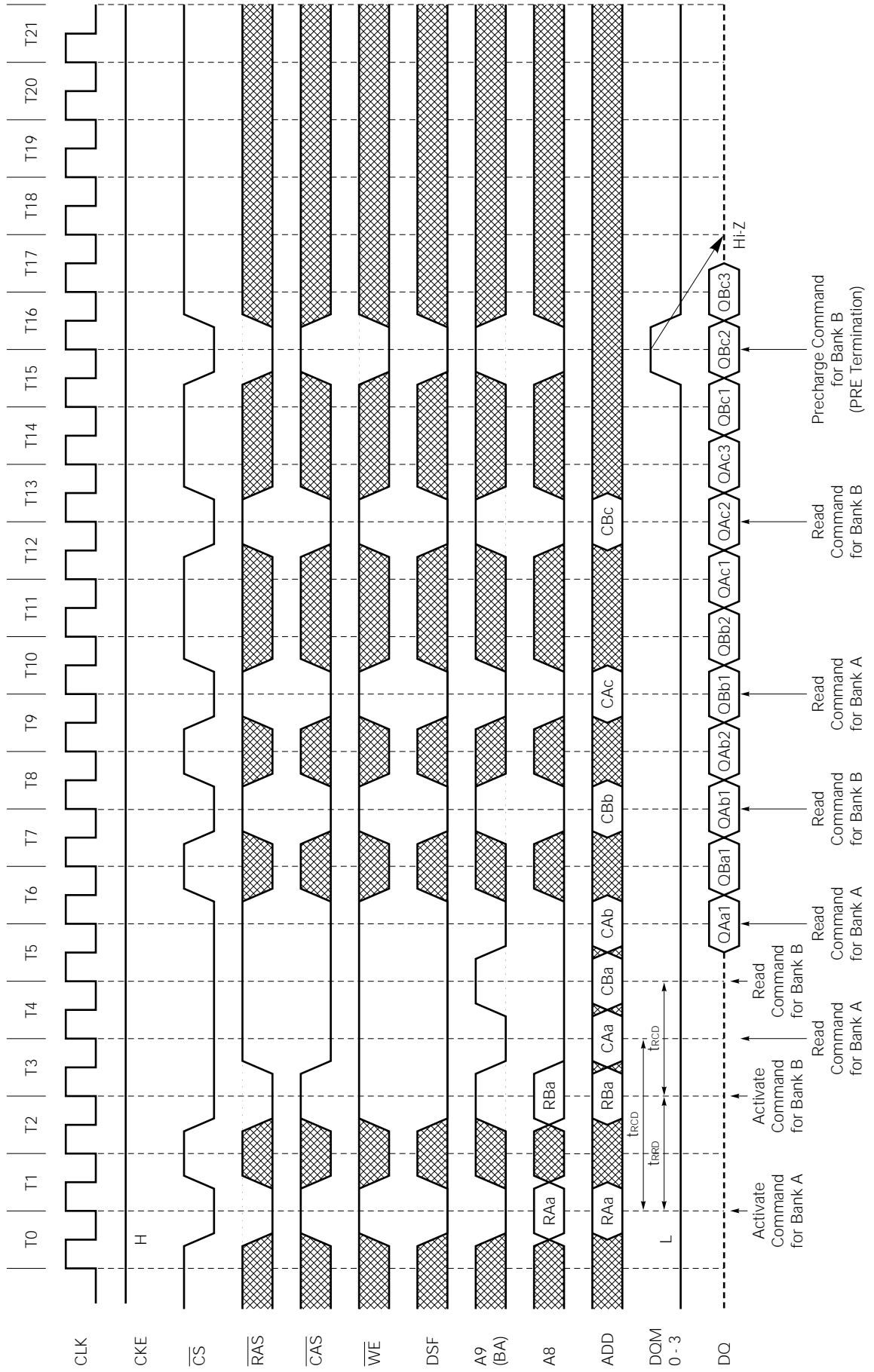
Interleaved Column WRITE Cycle (2/3) (Burst length = 4, CAS latency = 2)



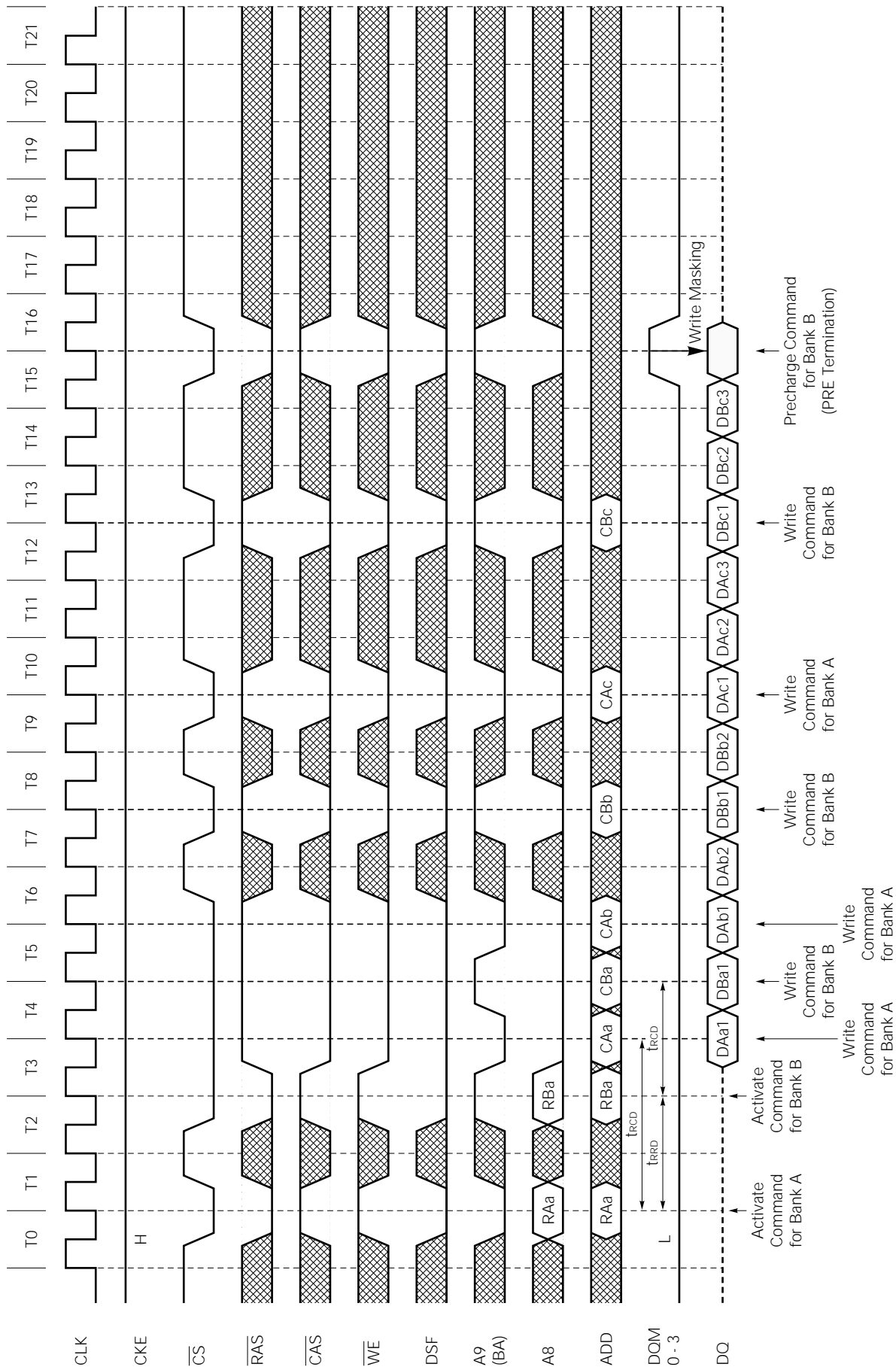
Interleaved Column WRITE Cycle (3/3) (Burst length = 4, CAS latency = 3)



16.6.5 Full Page Random Cycles
 Full Page Random Column Read (Burst length = Full Page, CAS latency = 2)

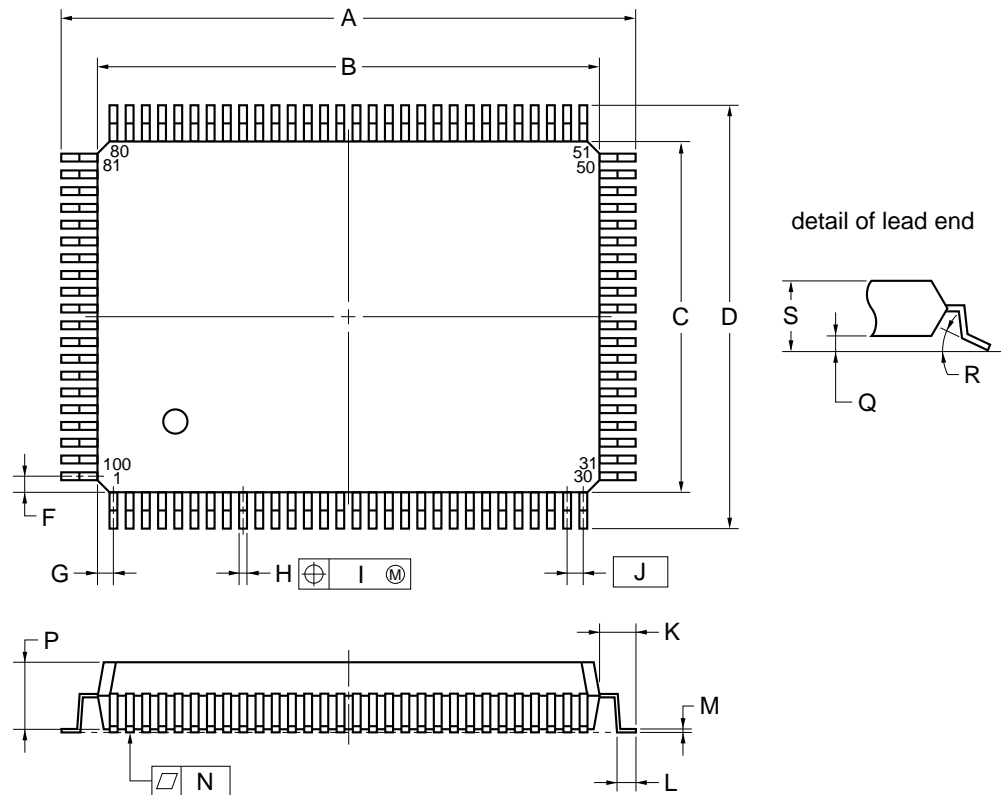


Full Page Random Column Write (Burst length = Full Page, CAS latency = 2)



17. Package Drawing

100PIN PLASTIC QFP (14 × 20)



NOTE

Each lead centerline is located within 0.13 mm (0.005 inch) of its true position (T.P.) at maximum material condition.

ITEM	MILLIMETERS	INCHES
A	23.2±0.2	0.913 ^{+0.009} _{-0.008}
B	20.0±0.2	0.787 ^{+0.009} _{-0.008}
C	14.0±0.2	0.551 ^{+0.009} _{-0.008}
D	17.2±0.2	0.677±0.008
F	0.825	0.032
G	0.575	0.023
H	0.32 ^{+0.08} _{-0.07}	0.013±0.003
I	0.13	0.005
J	0.65 (T.P.)	0.026 (T.P.)
K	1.6±0.2	0.063±0.008
L	0.8±0.2	0.031 ^{+0.009} _{-0.008}
M	0.17 ^{+0.06} _{-0.05}	0.007±0.002
N	0.10	0.004
P	2.7	0.106
Q	0.125±0.075	0.005±0.003
R	3° ^{+7°} _{-3°}	3° ^{+7°} _{-3°}
S	3.0 MAX.	0.119 MAX.

S100GF-65-JBT

18. Recommended Soldering Conditions

Please consult with our sales offices for soldering conditions of the μ PD481850.

Type of Surface Mount Device

μ PD481850GF-JBT: 100-pin Plastic QFP (14 × 20 mm)

NOTES FOR CMOS DEVICES

① PRECAUTION AGAINST ESD FOR SEMICONDUCTORS

Note: Strong electric field, when exposed to a MOS device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop generation of static electricity as much as possible, and quickly dissipate it once, when it has occurred. Environmental control must be adequate. When it is dry, humidifier should be used. It is recommended to avoid using insulators that easily build static electricity. Semiconductor devices must be stored and transported in an anti-static container, static shielding bag or conductive material. All test and measurement tools including work bench and floor should be grounded. The operator should be grounded using wrist strap. Semiconductor devices must not be touched with bare hands. Similar precautions need to be taken for PW boards with semiconductor devices on it.

② HANDLING OF UNUSED INPUT PINS FOR CMOS

Note: No connection for CMOS device inputs can be cause of malfunction. If no connection is provided to the input pins, it is possible that an internal input level may be generated due to noise, etc., hence causing malfunction. CMOS device behave differently than Bipolar or NMOS devices. Input levels of CMOS devices must be fixed high or low by using a pull-up or pull-down circuitry. Each unused pin should be connected to V_{DD} or GND with a resistor, if it is considered to have a possibility of being an output pin. All handling related to the unused pins must be judged device by device and related specifications governing the devices.

③ STATUS BEFORE INITIALIZATION OF MOS DEVICES

Note: Power-on does not necessarily define initial status of MOS device. Production process of MOS does not define the initial operation status of the device. Immediately after the power source is turned ON, the devices with reset function have not yet been initialized. Hence, power-on does not guarantee out-pin levels, I/O settings or contents of registers. Device is not initialized until the reset signal is received. Reset operation must be executed immediately after power-on for devices having reset function.

[MEMO]

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NEC devices are classified into the following three quality grades:

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Standard: Computers, office equipment, communications equipment, test and measurement equipment, audio and visual equipment, home electronic appliances, machine tools, personal electronic equipment and industrial robots

Special: Transportation equipment (automobiles, trains, ships, etc.), traffic control systems, anti-disaster systems, anti-crime systems, safety equipment and medical equipment (not specifically designed for life support)

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Anti-radioactive design is not implemented in this product.